

**WHAT IS CLAIMED IS:**

1. A system configured to determine at least two properties of a specimen during use, comprising:
  - 5 a stage configured to support the specimen during use;
  - a measurement device coupled to the stage, comprising:
    - 10 an illumination system configured to direct energy toward a surface of the specimen during use; and
    - a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use,
    - 15 wherein the measurement device is configured to generate one or more output signals in response to the detected energy during use; and
    - a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output
    - 20 signals during use, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises overlay misregistration of the specimen.
2. The system of claim 1, wherein the stage is further configured to move laterally  
25 during use.
3. The system of claim 1, wherein the stage is further configured to move rotatably during use.

4. The system of claim 1, wherein the stage is further configured to move laterally and rotatably during use.
- 5 5. The system of claim 1, wherein the illumination system comprises a single energy source.
6. The system of claim 1, wherein the illumination system comprises more than one energy sources.
- 10 7. The system of claim 1, wherein the detection system comprises a single energy sensitive device.
8. The system of claim 1, wherein the detection system comprises more than one energy sensitive devices.
- 15 9. The system of claim 1, wherein the measurement device further comprises a non-imaging scatterometer.
- 20 10. The system of claim 1, wherein the measurement device further comprises a scatterometer.
11. The system of claim 1, wherein the measurement device further comprises a spectroscopic scatterometer.
- 25 12. The system of claim 1, wherein the measurement device further comprises a reflectometer.

13. The system of claim 1, wherein the measurement device further comprises a spectroscopic reflectometer.
14. The system of claim 1, wherein the measurement device further comprises an ellipsometer.
15. The system of claim 1, wherein the measurement device further comprises a spectroscopic ellipsometer.
16. The system of claim 1, wherein the measurement device further comprises a bright field imaging device.
17. The system of claim 1, wherein the measurement device further comprises a dark field imaging device.
18. The system of claim 1, wherein the measurement device further comprises a bright field and a dark field imaging device.
19. The system of claim 1, wherein the measurement device further comprises a bright field non-imaging device.
20. The system of claim 1, wherein the measurement device further comprises a dark field non-imaging device.
21. The system of claim 1, wherein the measurement device further comprises a bright field and a dark field non-imaging device.

22. The system of claim 1, wherein the measurement device further comprises a coherence probe microscope.
23. The system of claim 1, wherein the measurement device further comprises an  
5 interference microscope.
24. The system of claim 1, wherein the measurement device further comprises an optical profilometer.
- 10 25. The system of claim 1, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field  
15 imaging device, a dark field imaging device, a bright field and a dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and a dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.
- 20 26. The system of claim 1, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
- 25 27. The system of claim 1, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property comprises a presence of defects on the specimen.



28. The system of claim 27, wherein the defects comprise micro defects and macro defects.

29. The system of claim 27, wherein the illumination system is further configured to  
5 direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the third property further comprises a presence of defects on the bottom surface of the specimen.

10 30. The system of claim 29, wherein the defects comprise macro defects.

31. The system of claim 1, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property comprises a flatness measurement of the specimen.

15

32. The system of claim 1, wherein the processor is further configured to determine a third property and a fourth property of the specimen from the one or more output signals during use, wherein the third property comprises a presence of defects on the specimen, and wherein the fourth property comprises a flatness measurement of the specimen.

20

33. The system of claim 1, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the  
25 specimen.

34. The system of claim 33, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.
- 5 35. The system of claim 1, wherein the system is further configured to determine at least two properties of the specimen simultaneously during use.
36. The system of claim 1, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.
- 10
37. The system of claim 1, wherein the system is coupled to a process tool.
- 15
38. The system of claim 1, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.
39. The system of claim 1, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.
- 20
40. The system of claim 1, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.
- 25

41. The system of claim 1, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.
- 5 42. The system of claim 1, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.
43. The system of claim 1, wherein the system is coupled to a process tool, and  
10 wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.
44. The system of claim 1, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a  
15 process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.
45. The system of claim 1, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a  
20 process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.
46. The system of claim 1, wherein the system is coupled to a process tool, and wherein the process tool comprises a lithography tool.  
25
47. The system of claim 1, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

48. The system of claim 1, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement  
chamber, wherein the measurement chamber is coupled to a process tool, and wherein the  
5 measurement chamber is disposed within the process tool.

49. The system of claim 1, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement  
chamber, wherein the measurement chamber is coupled to a process tool, and wherein the  
10 measurement chamber is arranged laterally proximate to a process chamber of the process  
tool.

50. The system of claim 1, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement  
15 chamber, wherein the measurement chamber is coupled to a process tool, and wherein the  
measurement chamber is arranged vertically proximate to a process chamber of the  
process tool.

51. The system of claim 1, wherein a process tool comprises a process chamber,  
20 wherein the stage is disposed within the process chamber, and wherein the stage is further  
configured to support the specimen during a process step.

52. The system of claim 51, wherein the processor is further configured to determine  
at least the two properties of the specimen during the process step.

25

53. The system of claim 51, wherein the processor is further configured to obtain a  
signature characterizing the process step during use, and wherein the signature comprises  
at least one singularity representative of an end of the process step.

54. The system of claim 51, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique  
5 during use.

55. The system of claim 1, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.  
10

56. The system of claim 1, wherein a process tool comprises a first process chamber and a second process chamber, wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use, and wherein the processor is further configured to determine at least the two properties of the  
15 specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

57. The system of claim 1, wherein a process tool comprises a first process chamber and a second process chamber, wherein the stage is further configured to move the  
20 specimen from the first process chamber to the second process chamber during use, wherein the processor is further configured to determine at least the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber, and wherein the process tool comprises a lithography tool.

25 58. The system of claim 57, wherein the first process chamber is configured to chill the specimen during use, and wherein the second process chamber is configured to apply resist to the specimen during use.

59. The system of claim 57, wherein the first process chamber is configured to chill the specimen subsequent to a post apply bake process step during use, and wherein the second process chamber is configured to expose the specimen during use.
- 5 60. The system of claim 57, wherein the first process chamber is configured to expose the specimen during use, and wherein the second process chamber is configured to bake the specimen subsequent to exposure of the specimen during use.
61. The system of claim 57, wherein the first process chamber is configured to chill  
10 the specimen subsequent to a post exposure bake process step during use, and wherein the second process chamber is configured to develop the specimen during use.
62. The system of claim 57, wherein the first process chamber is configured to develop the specimen during use, and wherein the second process chamber is configured  
15 to bake the specimen subsequent to a develop process step during use.
63. The system of claim 57, wherein the first process chamber is configured to develop the specimen during use, and wherein the second process chamber is configured to receive the specimen in a wafer cassette during use.  
20
64. The system of claim 1, wherein the processor is further configured to compare the determined properties of the specimen and properties of a plurality of specimens during use.
- 25 65. The system of claim 1, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property.

66. The system of claim 1, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property, and wherein the processor is further configured to generate an output signal if the determined property of the specimen is outside of the predetermined range during use.

5

67. The system of claim 1, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

10 68. The system of claim 1, wherein the processor is further configured to alter a parameter of an instrument coupled to the measurement device in response to the determined first or second property using a feedback control technique during use.

15 69. The system of claim 1, wherein the processor is further configured to alter a parameter of an instrument coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

20 70. The system of claim 1, wherein the processor is further configured to generate a database during use, and wherein the database comprises the determined first and second properties of the specimen.

71. The system of claim 70, wherein the processor is further configured to calibrate the measurement device using the database during use.

25 72. The system of claim 70, wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

73. The system of claim 70, wherein the database further comprises first and second properties of a plurality of specimens.
74. The system of claim 73, wherein the first and second properties of the plurality of specimens are determined using the measurement device.
75. The system of claim 73, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.
76. The system of claim 75, wherein the processor is further coupled to the plurality of measurement devices.
77. The system of claim 76, wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.
78. The system of claim 76, wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.
79. The system of claim 1, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.
80. The system of claim 1, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is



further configured to calibrate the system and at least the one additional system during use.

81. The system of claim 1, wherein the system is further configured to determine at  
5 least the two properties of the specimen at more than one position on the specimen,  
wherein the specimen comprises a wafer, and wherein the processor is configured to alter  
at least one parameter of one or more instruments coupled to a process tool in response to  
at least one of the determined properties of the specimen at the more than one position on  
the specimen to reduce within wafer variation of at least one of the determined properties.

10

82. The system of claim 1, wherein the processor is further coupled to a process tool.

83. The system of claim 82, wherein the process tool comprises a lithography tool.

15 84. The system of claim 82, wherein the processor is further configured to alter a  
parameter of one or more instruments coupled to the process tool in response to the  
determined first or second property using a feedback control technique during use.

85. The system of claim 82, wherein the processor is further configured to alter a  
20 parameter of one or more instruments coupled to the process tool in response to the  
determined first or second property using a feedforward control technique during use.

86. The system of claim 82, wherein the processor is further configured to monitor a  
parameter of one or more instruments coupled to the process tool during use.

25

87. The system of claim 86, wherein the processor is further configured to determine a  
relationship between the determined properties and at least one of the monitored  
parameters during use.

88. The system of claim 87, wherein the processor is further configured to alter the parameter of the one or more instruments in response to the determined relationship during use.

5

89. The system of claim 1, wherein the processor is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

10 90. The system of claim 1, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

15

91. The system of claim 90, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

92. The system of claim 90, wherein the remote controller computer is further  
20 configured to determine the first property and the second property of the specimen during use.

93. A method for determining at least two properties of a specimen, comprising:  
25 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

5

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises overlay misregistration of the specimen.

10

94. The method of claim 93, further comprising laterally moving the stage during said directing energy and said detecting energy.

15

95. The method of claim 93, further comprising rotatably moving the stage during said directing energy and said detecting energy.

96. The method of claim 93, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

20

97. The method of claim 93, wherein the illumination system comprises a single energy source.

98. The method of claim 93, wherein the illumination system comprises more than one energy source.

25

99. The method of claim 93, wherein the detection system comprises a single energy sensitive device.
100. The method of claim 93, wherein the detection system comprises more than one  
5 energy sensitive devices.
101. The method of claim 93, wherein the measurement device further comprises a non-imaging scatterometer.
102. The method of claim 93, wherein the measurement device further comprises a  
10 scatterometer.
103. The method of claim 93, wherein the measurement device further comprises a spectroscopic scatterometer.  
15
104. The method of claim 93, wherein the measurement device further comprises a reflectometer.
105. The method of claim 93, wherein the measurement device further comprises a  
20 spectroscopic reflectometer.
106. The method of claim 93, wherein the measurement device further comprises an ellipsometer.
107. The method of claim 93, wherein the measurement device further comprises a  
25 spectroscopic ellipsometer.

108. The method of claim 93, wherein the measurement device further comprises a bright field imaging device.
109. The method of claim 93, wherein the measurement device further comprises a  
5 dark field imaging device.
110. The method of claim 93, wherein the measurement device further comprises a bright field and dark field imaging device.
- 10 111. The method of claim 93, wherein the measurement device further comprises a bright field non-imaging device.
112. The method of claim 93, wherein the measurement device further comprises a dark field non-imaging device.  
15
113. The method of claim 93, wherein the measurement device further comprises a bright field and dark field non-imaging device
114. The method of claim 93, wherein the measurement device further comprises a  
20 coherence probe microscope.
115. The method of claim 93, wherein the measurement device further comprises an interference microscope.
- 25 116. The method of claim 93, wherein the measurement device further comprises an optical profilometer.

117. The method of claim 93, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.
118. The method of claim 93, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
119. The method of claim 93, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen.
120. The method of claim 93, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen, and wherein the defects comprise micro defects and macro defects.
121. The method of claim 93, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen, the method further comprising:

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein  
the third property further comprises a presence of defects on the bottom surface of  
the specimen.

122. The method of claim 121, wherein the defects comprise macro defects.

123. The method of claim 93, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property  
comprises a flatness measurement of the specimen.

124. The method of claim 93, further comprising processing the one or more output  
signals to determine a third property and a fourth property of the specimen, wherein the  
third property comprises a presence of defects on the specimen, and wherein the fourth  
property comprises a flatness measurement of the specimen.

125. The method of claim 93, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.

126. The method of claim 125, wherein the stage and the measurement device are  
coupled to a process tool selected from the group consisting of a lithography tool, an  
atomic layer deposition tool, a cleaning tool, and an etch tool.

127. The method of claim 93, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

5 128. The method of claim 93, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

10

129. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool.

130. The method of claim 93, wherein the stage and the measurement device are  
15 coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

131. The method of claim 93, wherein the stage and the measurement device are  
coupled to a process tool, and wherein the stage and the measurement device are disposed  
20 within the process tool.

132. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a lithography tool.

25 133. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.



134. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

5

135. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

10 136. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

15 137. The method of claim 93, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

20 138. The method of claim 93, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

25 139. The method of claim 93, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is disposed within the process tool.

140. The method of claim 93, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is arranged laterally proximate to a process chamber of the process tool.

5

141. The method of claim 93, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is arranged vertically proximate to a process chamber of the process tool.

10

142. The method of claim 93, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

15

143. The method of claim 142, further comprising performing said directing and said detecting during the process step.

20

144. The method of claim 143, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

25

145. The method of claim 143, further comprising altering a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.

146. The method of claim 93, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

5 147. The method of claim 146, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

148. The method of claim 146, wherein the process tool comprises a lithography tool.

10

149. The method of claim 148, further comprising:

chilling the specimen in the first process chamber; and

15

applying resist to the specimen in the second process chamber.

150. The method of claim 148, further comprising:

chilling the specimen in the first process chamber subsequent to a post apply bake process step; and

20

exposing the specimen in the second process chamber.

151. The method of claim 148, further comprising:

25

exposing the specimen in the first process chamber; and

baking the specimen subsequent to exposure of the specimen in the second process chamber.

152. The method of claim 148, further comprising:

5

chilling the specimen in the first process chamber subsequent to a post exposure bake process step; and

developing the specimen in the second process chamber.

10

153. The method of claim 148, further comprising:

developing the specimen in the first process chamber; and

15

baking the specimen in the second process chamber subsequent to a develop process step.

154. The method of claim 148, further comprising:

20

developing the specimen in the first process chamber; and

receiving the specimen in a wafer cassette in the second process chamber.

155. The method of claim 93, further comprising comparing at least one of the

25

determined properties of the specimen and determined properties of a plurality of specimens.

156. The method of claim 93, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

5 157. The method of claim 93, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property and generating an output signal if the determined property of the specimen is outside of the predetermined range.

10 158. The method of claim 93, further comprising altering a sampling frequency of the measurement device in response to the determined first or second property of the specimen.

15 159. The method of claim 93, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

20 160. The method of claim 93, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

161. The method of claim 93, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

25 162. The method of claim 161, further comprising calibrating the measurement device using the database.

163. The method of claim 161, further comprising monitoring output signals generated by the measurement device using the database.

164. The method of claim 161, wherein the database further comprises first and second properties of a plurality of specimens.

5 165. The method of claim 164, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

166. The method of claim 165, further comprising calibrating the plurality of measurement devices using the database.

10

167. The method of claim 165, further comprising monitoring output signals generated by the plurality of measurement devices using the database.

15 168. The method of claim 93, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

20 169. The method of claim 93, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

25 170. The method of claim 93, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one

of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

171. The method of claim 93, further comprising altering a parameter of one or more  
5 instruments coupled to a process tool in response to the determined first or second property of the specimen.

172. The method of claim 93, further comprising altering a parameter of one or more  
instruments coupled to a process tool in response to the determined first or second  
10 property of the specimen using a feedback control technique.

173. The method of claim 93, further comprising altering a parameter of one or more  
instruments coupled to a process tool in response to the determined first or second  
property of the specimen using a feedforward control technique.

15

174. The method of claim 93, further comprising monitoring a parameter of one or  
more instruments coupled to a process tool.

175. The method of claim 93, further comprising monitoring a parameter of one or  
20 more instruments coupled to a process tool and determining a relationship between the determined properties and at least one of the monitored parameters.

176. The method of claim 93, further comprising monitoring a parameter of one or  
more instruments coupled to a process tool, determining a relationship between the  
25 determined properties and at least one of the monitored parameters, and altering the parameter of the one or more instruments in response to the relationship.

177. The method of claim 93, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to the determined first or second property of the specimen.

5 178. The method of claim 93, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

15

further processing the partially processed one or more output signals using the remote controller computer.

179. The method of claim 178, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

20 180. The method of claim 178, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

25 181. A computer-implemented method for controlling a system configured to determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:



controlling the measurement device, wherein the measurement device comprises an illumination system and a detection system, and wherein the measurement device is coupled to a stage, comprising:

5                   controlling the illumination system to direct energy toward a surface of the specimen;

                  controlling the detection system to detect energy propagating from the surface of the specimen; and

10

                  generating one or more output signals responsive to the detected energy; and

15

                  processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises overlay misregistration of the specimen.

20           182.   The method of claim 181, further comprising controlling the stage, wherein the stage is configured to support the specimen.

          183.   The method of claim 181, further comprising controlling the stage to move laterally during said directing energy and said detecting energy.

25           184.   The method of claim 181, further comprising controlling the stage to move rotatably during said directing energy and said detecting energy.

185. The method of claim 181, further comprising controlling the stage to move laterally and rotatably during said directing energy and said detecting energy.

5 186. The method of claim 181, wherein the illumination system comprises a single energy source.

187. The method of claim 181, wherein the illumination system comprises more than one energy source.

10 188. The method of claim 181, wherein the detection system comprises a single energy sensitive device.

189. The method of claim 181, wherein the detection system comprises more than one energy sensitive devices.

15

190. The method of claim 181, wherein the measurement device further comprises a non-imaging scatterometer.

20 191. The method of claim 181, wherein the measurement device further comprises a scatterometer.

192. The method of claim 181, wherein the measurement device further comprises a spectroscopic scatterometer.

25 193. The method of claim 181, wherein the measurement device further comprises a reflectometer.

194. The method of claim 181, wherein the measurement device further comprises a spectroscopic reflectometer.
195. The method of claim 181, wherein the measurement device further comprises an  
5 ellipsometer.
196. The method of claim 181, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 10 197. The method of claim 181, wherein the measurement device further comprises a bright field imaging device.
198. The method of claim 181, wherein the measurement device further comprises a dark field imaging device.  
15
199. The method of claim 181, wherein the measurement device further comprises a bright field and dark field imaging device.
200. The method of claim 181, wherein the measurement device further comprises a  
20 bright field non-imaging device.
201. The method of claim 181, wherein the measurement device further comprises a dark field non-imaging device.
- 25 202. The method of claim 181, wherein the measurement device further comprises a bright field and dark field non-imaging device.

203. The method of claim 181, wherein the measurement device further comprises a coherence probe microscope.
204. The method of claim 181, wherein the measurement device further comprises an  
5 interference microscope.
205. The method of claim 181, wherein the measurement device further comprises an optical profilometer.
- 10 206. The method of claim 181, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field  
15 imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.
- 20 207. The method of claim 181, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
- 25 208. The method of claim 181, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen.

209. The method of claim 208, wherein the defects comprise micro defects and macro defects.

210. The method of claim 208, further comprising:

5

controlling the illumination system to direct energy toward a bottom surface of the specimen; and

10

controlling the detection system to detect energy propagating from the bottom surface of the specimen, wherein the third property further comprises a presence of defects on the bottom surface of the specimen.

211. The method of claim 210, wherein the defects comprise macro defects.

15

212. The method of claim 181, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a flatness measurement of the specimen.

20

213. The method of claim 181, further comprising processing the one or more output signals to determine a third property and a fourth property of the specimen, wherein the third property comprises a presence of defects on the specimen, and wherein the fourth property comprises a flatness measurement of the specimen.

25

214. The method of claim 181, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

215. The method of claim 214, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 216. The method of claim 181, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

217. The method of claim 181, further comprising controlling the illumination system  
10 to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

15

218. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool.

219. The method of claim 181, wherein the stage and the measurement device are  
20 coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

220. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed  
25 within the process tool.

221. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a lithography tool.

222. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is  
5 coupled to the process tool.

223. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.  
10

224. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.  
15

225. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.  
20

226. The method of claim 181, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.  
25

227. The method of claim 181, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

228. The method of claim 181, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is disposed within the process  
5 tool.

229. The method of claim 181, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is arranged laterally proximate  
10 to a process chamber of the process tool.

230. The method of claim 181, wherein the stage and the measurement device are disposed within a measurement chamber, wherein the measurement chamber is coupled to a process tool, and wherein the measurement chamber is arranged vertically proximate  
15 to a process chamber of the process tool.

231. The method of claim 181, wherein the stage comprises a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.  
20

232. The method of claim 231, further comprising controlling the illumination system and controlling the detection system during the process step.

233. The method of claim 231, further comprising controlling the system to obtain a  
25 signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.



234. The method of claim 231, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.

5 235. The method of claim 181, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

236. The method of claim 235, further comprising controlling the illumination system  
10 and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.

237. The method of claim 235, wherein the process tool comprises a lithography tool.

15 238. The method of claim 237, further comprising:

chilling the specimen in the first process chamber; and

applying resist to the specimen in the second process chamber.

20

239. The method of claim 237, further comprising:

chilling the specimen in the first process chamber subsequent to a post apply bake  
process step; and

25

exposing the specimen in the second process chamber.

240. The method of claim 237, further comprising:

exposing the specimen in the first process chamber; and

5       baking the specimen subsequent to exposure of the specimen in the second  
process chamber.

241.   The method of claim 237, further comprising:

10       chilling the specimen in the first process chamber subsequent to a post exposure  
bake process step; and

developing the specimen in the second process chamber.

15       242.   The method of claim 237, further comprising:

developing the specimen in the first process chamber; and

20       baking the specimen in the second process chamber subsequent to a develop  
process step.

243.   The method of claim 237, further comprising:

developing the specimen in the first process chamber; and

25       receiving the specimen in a wafer cassette in the second process chamber.

244. The method of claim 181, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

- 5 245. The method of claim 181, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

246. The method of claim 245, further comprising generating an output signal if the determined property of the specimen is outside of the predetermined range.

10

247. The method of claim 181, further comprising altering a sampling frequency of the measurement device in response to the determined first or second properties of the specimen.

- 15 248. The method of claim 181, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

249. The method of claim 181, further comprising altering a parameter of one or more  
20 instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

250. The method of claim 181, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

25

251. The method of claim 250, further comprising calibrating the measurement device using the database.

252. The method of claim 250, further comprising monitoring output signals of the measurement device using the database.

5 253. The method of claim 250, wherein the database further comprises first and second properties of a plurality of specimens.

254. The method of claim 253, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

10 255. The method of claim 254, further comprising calibrating the plurality of measurement devices using the database.

256. The method of claim 254, further comprising monitoring output signals of the plurality of measurement devices using the database.

15

257. The method of claim 181, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

20

258. The method of claim 181, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

25

259. The method of claim 181, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and

wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

5

260. The method of claim 181, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen.

10 261. The method of claim 181, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen using a feedback control technique.

15 262. The method of claim 181, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen using a feedforward control technique.

263. The method of claim 181, further comprising monitoring a parameter of one or more instruments coupled to the process tool.

20

264. The method of claim 181, further comprising monitoring a parameter of one or more instruments coupled to the process tool and determining a relationship between the determined properties and at least one of the monitored parameters.

25 265. The method of claim 181, further comprising monitoring a parameter of one or more instruments coupled to the process tool, determining a relationship between the determined properties and at least one of the monitored parameters, and altering the parameter of at least one of the instruments in response to the relationship.

266. The method of claim 181, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to the determined first or second property of the specimen.

5

267. The method of claim 181, wherein processing the one or more output signals comprises:

10 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

15 further processing the partially processed one or more output signals using the remote controller computer.

268. The method of claim 267, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

20

269. The method of claim 267, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

25 270. A semiconductor device fabricated by a method, the method comprising:

forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

5 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

10 generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the portion of the semiconductor device, wherein the first property comprises a critical dimension of the portion of the semiconductor

15 device, and wherein the second property comprises overlay misregistration of the portion of the semiconductor device.

271. The device of claim 270, wherein the illumination system comprises a single energy source.

20

272. The device of claim 270, wherein the illumination system comprises more than one energy source.

273. The device of claim 270, wherein the detection system comprises a single energy

25

274. The device of claim 270, wherein the detection system comprises more than one energy sensitive devices.

275. The device of claim 270, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.
276. The device of claim 270, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.
277. The device of claim 270, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
278. The device of claim 270, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen.



279. The device of claim 278, wherein the defects comprise micro defects and macro defects.

280. The device of claim 278, further comprising:

5

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein  
the third property further comprises a presence of defects on the bottom surface of  
the specimen.

10

281. The device of claim 280, wherein the defects comprise macro defects.

282. The device of claim 270, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property  
comprises a flatness measurement of the specimen.

15

283. The device of claim 270, further comprising processing the one or more output  
signals to determine a third property and a fourth property of the specimen, wherein the  
third property comprises a presence of defects on the specimen, and wherein the fourth  
property comprises a flatness measurement of the specimen.

20

284. The device of claim 270, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.

25

285. The device of claim 284, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 286. The device of claim 270, wherein the stage and the measurement device are coupled to a process tool.

287. The device of claim 270, wherein the stage and the measurement device are coupled to a lithography tool.

10

288. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;

15

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

20

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

25

processing the one or more output signals to determine a first property and a second property of the portion of the semiconductor device, wherein the first property comprises a critical dimension of the portion of the semiconductor

device, and wherein the second property comprises overlay misregistration of the portion of the semiconductor device.

5 289. The method of claim 288, wherein the illumination system comprises a single energy source.

290. The method of claim 288, wherein the illumination system comprises more than one energy source.

10 291. The method of claim 288, wherein the detection system comprises a single energy sensitive device.

292. The method of claim 288, wherein the detection system comprises more than one energy sensitive devices.

15

293. The method of claim 288, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a  
20 bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.

25 294. The method of claim 288, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field

imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.

5     295.   The method of claim 288, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10    296.   The method of claim 288, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen.

15    297.   The method of claim 296, wherein the defects comprise micro defects and macro defects.

298.   The method of claim 296, further comprising:

20       directing energy toward a bottom surface of the specimen; and

      detecting energy propagating from the bottom surface of the specimen, wherein the third property further comprises a presence of defects on the bottom surface of the specimen.

25    299.   The method of claim 298, wherein the defects comprise macro defects.

300. The method of claim 288, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property comprises a flatness measurement of the specimen.
- 5 301. The method of claim 288, further comprising processing the one or more output signals to determine a third property and a fourth property of the specimen, wherein the third property comprises a presence of defects on the specimen, and wherein the fourth property comprises a flatness measurement of the specimen.
- 10 302. The method of claim 288, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.
- 15 303. The method of claim 302, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.
- 20 304. The method of claim 288, wherein the stage and the measurement device are coupled to a process tool.
305. The method of claim 288, wherein the stage and the measurement device are coupled to a lithography tool.
- 25 306. A system configured to determine at least two properties of a specimen during use, comprising:
- a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

5                   an illumination system configured to direct energy toward a surface of the specimen during use; and

                  a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more  
10                   output signals in response to the detected energy during use;

                  a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

15                   a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, and  
20                   wherein the second property comprises overlay misregistration of the specimen.

307.   The system of claim 306, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a  
25   spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.

308. The system of claim 306, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
5 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.

10

309. The system of claim 306, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the illumination system of the first measurement device comprises the illumination system of the second measurement device.

15

310. The system of claim 306, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the detection system of the first measurement device comprises the detection system of the second measurement device.

20

311. The system of claim 306, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially processed one or more output signals during use, and wherein the third property comprises a presence of defects on the specimen.

25

312. The system of claim 311, wherein the defects comprise micro defects and macro defects.

313. The system of claim 311, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the third property further comprises a presence of  
5 defects on the bottom surface of the specimen.

314. The system of claim 313, wherein the defects comprise macro defects.

315. The system of claim 306, wherein the remote controller computer is further  
10 configured to determine a third property of the specimen from the at least partially processed one or more output signals during use, and wherein the third property comprises a flatness measurement of the specimen.

316. The system of claim 306, wherein the remote controller computer is further  
15 configured to determine a third property and a fourth property of the specimen from the at least partially processed one or more output signals during use, wherein the third property comprises a presence of defects on the specimen, and wherein the fourth property comprises a flatness measurement of the specimen.

20 317. The system of claim 306, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially processed one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

25

318. The system of claim 317, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.



319. The system of claim 306, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy  
5 propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

320. The system of claim 306, wherein the remote controller computer is coupled to a  
10 process tool.

321. The system of claim 320, wherein the process tool comprises a lithography tool.

322. The system of claim 320, wherein the remote controller computer is further  
15 configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.

323. The system of claim 320, wherein the remote controller computer is further  
20 configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.

324. The system of claim 320, wherein the remote controller computer is further  
25 configured to monitor a parameter of one or more instruments coupled to the process tool during use.

325. The system of claim 324, wherein the remote controller computer is further configured to determine a relationship between the determined properties and at least one of the monitored parameters during use.

5 326. The system of claim 325, wherein the remote controller computer is further configured to alter the parameter of at least one of the instruments in response to the relationship during use.

327. The system of claim 320, wherein the illumination system is further configured to  
10 direct energy toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during the process step.

15 .  
328. The system of claim 327, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

20  
329. The system of claim 327, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using an in situ control technique during use.

25  
330. The system of claim 306, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to

move the specimen from the first process chamber to the second process chamber during use.

5 331. The system of claim 330, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

10

332. The system of claim 306, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

15 333. The system of claim 306, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

20 334. The system of claim 333, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

25 335. The system of claim 306, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

336. The system of claim 306, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement

device in response to the determined first or second property using a feedback control technique during use.

5 337. The system of claim 306, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

10 338. The system of claim 306, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

15 339. The system of claim 338, wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

340. The system of claim 338, wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

20 341. The system of claim 338, wherein the database further comprises first and second properties of a plurality of specimens.

342. The system of claim 341, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.

25 343. The system of claim 342, wherein the remote controller computer is further coupled to the plurality of measurement devices.

344. The system of claim 343, wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.
- 5 345. The system of claim 343, wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.
346. The system of claim 343, wherein each of the plurality of measurement devices is  
10 coupled to at least one of a plurality of process tools.
347. A method for determining at least two properties of a specimen, comprising:
- 15 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;
- directing energy toward a surface of the specimen using the illumination system;
- 20 detecting energy propagating from the surface of the specimen using the detection system;
- generating one or more output signals in response to the detected energy; and
- 25 processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises overlay

misregistration of the specimen, wherein processing the one or more output signals comprises:

5                   at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

                  sending the partially processed one or more output signals from the local processor to a remote controller computer; and

10                   further processing the partially processed one or more output signals using the remote controller computer.

348.   The method of claim 347, wherein the measurement device is selected from the  
15   group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark field non-imaging device, a coherence probe  
20   microscope, an interference microscope, and an optical profilometer.

349.   The method of claim 347, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
25   scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a bright field non-imaging device, a dark field non-imaging device, a bright field and dark

field non-imaging device, a coherence probe microscope, an interference microscope, and an optical profilometer.

350. The method of claim 347, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein an illumination system of the first measurement device comprises an illumination system of the second measurement device.

351. The method of claim 347, wherein the measurement device further comprises at  
10 least a first measurement device and a second measurement device, and wherein a detection system of the first measurement device comprises a detection system of the second measurement device.

352. The method of claim 347, further comprising processing the one or more output  
15 signals to determine a third property of the specimen, wherein the third property comprises a presence of defects on the specimen.

353. The method of claim 352, wherein the defects comprise micro defects and macro  
20 defects.

354. The method of claim 352, further comprising:  
  
directing energy toward a bottom surface of the specimen; and  
  
25 detecting energy propagating from the bottom surface of the specimen, wherein the third property further comprises a presence of defects on the bottom surface of the specimen.

355. The method of claim 354, wherein the defects comprise macro defects.

356. The method of claim 347, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property  
5 comprises a flatness measurement of the specimen.

357. The method of claim 347, further comprising processing the one or more output signals to determine a third property and a fourth property of the specimen, wherein the third property comprises a presence of defects on the specimen, and wherein the fourth  
10 property comprises a flatness measurement of the specimen.

358. The method of claim 347, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer  
15 on the specimen, and a roughness of a feature of the specimen.

359. The method of claim 358, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.  
20

360. The method of claim 347, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple  
25 locations substantially simultaneously.

361. The method of claim 347, wherein the remote controller computer is coupled to a process tool.



362. The method of claim 361, wherein the process tool comprises a lithography tool.

363. The method of claim 361, further comprising altering a parameter of one or more  
5 instruments coupled to the process tool using the remote controller computer in response  
to the determined first or second property of the specimen using a feedback control  
technique.

364. The method of claim 361, further comprising altering a parameter of one or more  
10 instruments coupled to the process tool using the remote controller computer in response  
to the determined first or second property of the specimen using a feedforward control  
technique.

365. The method of claim 361, further comprising monitoring a parameter of one or  
15 more instruments coupled to the process tool using the remote controller computer.

366. The method of claim 365, further comprising determining a relationship between  
the determined properties and at least one of the monitored parameters using the remote  
controller computer.

20

367. The method of claim 366, further comprising altering a parameter of at least one  
of the instruments in response to the relationship using the remote controller computer.

368. The method of claim 361, wherein the illumination system and the detection  
25 system are coupled to a process chamber of the process tool, further comprising  
performing said directing and said detecting during a process step.

369. The method of claim 368, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

5 370. The method of claim 368, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property using an in situ control technique.

371. The method of claim 347, further comprising:

10

moving the specimen from a first process chamber to a second process chamber using the stage;

performing said directing and said detecting during said moving the specimen.

15

372. The method of claim 347, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

20 373. The method of claim 347, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

374. The method of claim 373, further comprising generating an output signal using the  
25 remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

375. The method of claim 347, wherein the remote controller computer is coupled to the measurement device.

376. The method of claim 375, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to the determined first or second property of the specimen.

377. The method of claim 375, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedback control technique.

378. The method of claim 375, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedforward control technique.

379. The method of claim 347, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen.

380. The method of claim 379, further comprising calibrating the measurement device using the database and the remote controller computer.

381. The method of claim 379, further comprising monitoring output signals of the measurement device using the remote controller computer.

382. The method of claim 379, wherein the database further comprises first and second properties of a plurality of specimens.

383. The method of claim 382, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

384. The method of claim 383, further comprising calibrating the plurality of measurement devices using the remote controller computer.

385. The method of claim 383, further comprising monitoring output signals of the plurality of measurement devices using the remote controller computer.

386. The method of claim 347, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

387. The method of claim 386, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to the determined first or second property of the specimen.

388. The method of claim 386, wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

389. The method of claim 388, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of process tools using the remote controller computer in response to the determined first or second property of the specimen.

390. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals in response to the detected energy during use; and

a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

391. The system of claim 390, wherein the stage is further configured to move laterally during use.

392. The system of claim 390, wherein the stage is further configured to move rotatably during use.

393. The system of claim 390, wherein the stage is further configured to move laterally and rotatably during use.
- 5 394. The system of claim 390, wherein the illumination system comprises a single energy source.
395. The system of claim 390, wherein the illumination system comprises more than one energy source.
- 10 396. The system of claim 390, wherein the detection system comprises a single energy sensitive device.
397. The system of claim 390, wherein the detection system comprises more than one energy sensitive device.
- 15 398. The system of claim 390, wherein the measurement device further comprises a non-imaging dark field device.
399. The system of claim 390, wherein the measurement device further comprises a non-imaging bright field device.
- 20 400. The system of claim 390, wherein the measurement device further comprises a non-imaging dark field and bright field device.
- 25 401. The system of claim 390, wherein the measurement device further comprises a double dark field device.

402. The system of claim 390, wherein the measurement device further comprises a dark field imaging device.
- 5 403. The system of claim 390, wherein the measurement device further comprises a bright field imaging device.
404. The system of claim 390, wherein the measurement device further comprises a dark field and bright field imaging device.
- 10 405. The system of claim 390, wherein the measurement device further comprises a scatterometer.
406. The system of claim 390, wherein the measurement device further comprises a spectroscopic scatterometer.
- 15 407. The system of claim 390, wherein the measurement device further comprises an ellipsometer.
408. The system of claim 390, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 20 409. The system of claim 390, wherein the measurement device further comprises a reflectometer.
- 25 410. The system of claim 390, wherein the measurement device further comprises a spectroscopic reflectometer.

411. The system of claim 390, wherein the measurement device further comprises a dual beam spectrophotometer.

412. The system of claim 390, wherein the measurement device further comprises a  
5 beam profile ellipsometer.

413. The system of claim 390, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
10 dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam  
15 profile ellipsometer.

414. The system of claim 390, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second  
20 measurement device.

415. The system of claim 390, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.  
25

416. The system of claim 390, wherein the defects comprise micro defects and macro defects.



417. The system of claim 390, wherein the defects comprise micro defects or macro defects.

418. The system of claim 390, wherein the thin film characteristic comprises a  
5 thickness of a copper film, and wherein the defects comprise voids in the copper film.

419. The system of claim 390, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

10 420. The system of claim 390, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

15

421. The system of claim 420, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

20 422. The system of claim 390, wherein the system is further configured to determine at least two properties of the specimen substantially simultaneously during use.

423. The system of claim 390, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially  
25 simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

424. The system of claim 390, wherein the system is coupled to a process tool.

425. The system of claim 390, wherein the system is coupled to a process tool, and  
5 wherein the system is disposed within the process tool.

426. The system of claim 390, wherein the system is coupled to a process tool, and  
wherein the system is arranged laterally proximate to the process tool.

10 427. The system of claim 390, wherein the system is coupled to a process tool, and  
wherein the process tool comprises a wafer handler configured to move the specimen to  
the stage during use.

428. The system of claim 390, wherein the system is coupled to a process tool, and  
15 wherein the stage is further configured to move the specimen from the system to the  
process tool during use.

429. The system of claim 390, wherein the system is coupled to a process tool, and  
wherein the stage is further configured to move the specimen to a process chamber of the  
20 process tool during use.

430. The system of claim 390, wherein the system is coupled to a process tool, and  
wherein the system is further configured to determine at least the two properties of the  
specimen while the specimen is waiting between process steps.

25

431. The system of claim 390, wherein the system is coupled to a process tool, wherein  
the process tool comprises a support device configured to support the specimen during a

process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

432. The system of claim 390, wherein the system is coupled to a process tool, wherein  
5 the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

433. The system of claim 390, wherein the system is coupled to a process tool, and  
10 wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

434. The system of claim 390, wherein the system comprises a measurement chamber,  
15 wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

435. The system of claim 390, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement  
20 chamber, and wherein the measurement chamber is disposed within a process tool.

436. The system of claim 390, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement  
chamber, and wherein the measurement chamber is arranged laterally proximate to a  
25 process chamber of a process tool.

437. The system of claim 390, wherein the system comprises a measurement chamber,  
wherein the stage and the measurement device are disposed within the measurement

chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

5 438. The system of claim 390, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

10 439. The system of claim 438, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

440. The system of claim 439, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

15 441. The system of claim 439, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique during use.

20 442. The system of claim 390, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

25 443. The system of claim 390, wherein a process tool comprises a first process chamber and a second process chamber, wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use, and wherein the system is further configured to determine at least the two properties of

the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

5     444.    The system of claim 390, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

10    445.    The system of claim 390, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

15    446.    The system of claim 445, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

20    447.    The system of claim 390, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

25    448.    The system of claim 390, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique during use.

30    449.    The system of claim 390, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

450. The system of claim 390, wherein the processor is further configured to generate a database during use, and wherein the database comprises the determined first and second properties of the specimen.
- 5 451. The system of claim 390, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to calibrate the measurement device using the database during use.
- 10 452. The system of claim 390, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.
- 15 453. The system of claim 390, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.
- 20 454. The system of claim 453, wherein the first and second properties of the plurality of specimens are determined using the measurement device.
455. The system of claim 453, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.
- 25 456. The system of claim 455, wherein the processor is further coupled to the plurality of measurement devices.

457. The system of claim 456, wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

458. The system of claim 456, wherein the processor is further configured to monitor  
5 output signals generated by the plurality of measurement devices using the database during use.

459. The system of claim 390, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration  
10 standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

460. The system of claim 390, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to  
15 be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

461. The system of claim 390, wherein the system is further configured to determine at  
20 least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.  
25

462. The system of claim 390, wherein the processor is further coupled to a process tool.

463. The system of claim 390, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.

5

464. The system of claim 390, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.

10

465. The system of claim 390, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

15 466. The system of claim 465, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

20 467. The system of claim 466, wherein the processor is further configured to alter the parameter of at least one of the instruments in response to the relationship during use.

468. The system of claim 390, wherein the processor is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

25

469. The system of claim 390, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or



more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

5 470. The system of claim 469, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

471. The system of claim 469, wherein the remote controller computer is further configured to determine the first property and the second property of the specimen during use.  
10

472. A method for determining at least two properties of a specimen, comprising:  
  
disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an  
15 illumination system and a detection system;  
  
directing energy toward a surface of the specimen using the illumination system;  
  
detecting energy propagating from the surface of the specimen using the detection  
20 system;  
  
generating one or more output signals in response to the detected energy; and  
  
processing the one or more output signals to determine a first property and a  
25 second property of the specimen, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

473. The method of claim 472, further comprising laterally moving the stage during said directing energy and said detecting energy.

474. The method of claim 472, further comprising rotatably moving the stage during  
5 said directing energy and said detecting energy.

475. The method of claim 472, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

10 476. The method of claim 472, wherein the illumination system comprises a single energy source.

477. The method of claim 472, wherein the illumination system comprises more than one energy source.

15

478. The method of claim 472, wherein the detection system comprises a single energy sensitive device.

479. The method of claim 472, wherein the detection system comprises more than one  
20 energy sensitive device.

480. The method of claim 472, wherein the measurement device further comprises a non-imaging dark field device.

25 481. The method of claim 472, wherein the measurement device further comprises a non-imaging bright field device.

482. The method of claim 472, wherein the measurement device further comprises a non-imaging dark field and bright field device.
483. The method of claim 472, wherein the measurement device further comprises a  
5 double dark field device.
484. The method of claim 472, wherein the measurement device further comprises a dark field imaging device.
- 10 485. The method of claim 472, wherein the measurement device further comprises a bright field imaging device.
486. The method of claim 472, wherein the measurement device further comprises a dark field and bright field imaging device.  
15
487. The method of claim 472, wherein the measurement device further comprises a scatterometer.
488. The method of claim 472, wherein the measurement device further comprises a  
20 spectroscopic scatterometer.
489. The method of claim 472, wherein the measurement device further comprises an ellipsometer.
- 25 490. The method of claim 472, wherein the measurement device further comprises a spectroscopic ellipsometer.

491. The method of claim 472, wherein the measurement device further comprises a reflectometer.

492. The method of claim 472, wherein the measurement device further comprises a spectroscopic reflectometer.

493. The method of claim 472, wherein the measurement device further comprises a dual beam spectrophotometer.

494. The method of claim 472, wherein the measurement device further comprises a beam profile ellipsometer.

495. The method of claim 472, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

496. The method of claim 472, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

497. The method of claim 472, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

5 498. The method of claim 472, wherein the defects comprise micro defects and macro defects.

499. The method of claim 472, wherein the defects comprise micro defects or macro defects.

10

500. The method of claim 472, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

15 501. The method of claim 472, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

502. The method of claim 472, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer  
20 on the specimen, and a roughness of a feature of the specimen.

503. The method of claim 502, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

25

504. The method of claim 472, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

505. The method of claim 472, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.
506. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool.
507. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.
508. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.
509. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.
510. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

511. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

5 512. The method of claim 472, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

513. The method of claim 472, wherein the stage and the measurement device are  
10 coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

514. The method of claim 472, wherein the stage and the measurement device are  
15 coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

515. The method of claim 472, wherein the stage and the measurement device are  
20 disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

516. The method of claim 472, wherein the stage and the measurement device are  
25 disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

517. The method of claim 472, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

5 518. The method of claim 472, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

519. The method of claim 472, wherein disposing the specimen upon the stage  
10 comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

520. The method of claim 472, wherein disposing the specimen upon the stage  
15 comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step, the method further comprising performing said directing and said detecting during the process step.

20 521. The method of claim 520, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

522. The method of claim 520, further comprising altering a parameter of one or more  
25 instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.



523. The method of claim 472, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.
- 5 524. The method of claim 472, further comprising moving the specimen from a first process chamber to a second process chamber using the stage and performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.
- 10 525. The method of claim 472, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.
526. The method of claim 472, further comprising comparing at least one of the  
15 determined properties of the specimen to a predetermined range for the property.
527. The method of claim 526, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.
- 20 528. The method of claim 472, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.
- 25 529. The method of claim 472, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

530. The method of claim 472, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

5 531. The method of claim 472, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

532. The method of claim 472, further comprising calibrating the measurement device using the database.

10

533. The method of claim 472, further comprising monitoring output signals generated by the measurement device using the database.

534. The method of claim 472, wherein the database further comprises first and second  
15 properties of a plurality of specimens.

535. The method of claim 534, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

20 536. The method of claim 535, further comprising calibrating the plurality of measurement devices using the database.

537. The method of claim 535, further comprising monitoring output signals generated by the plurality of measurement devices using the database.

25

538. The method of claim 472, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system

with a calibration standard and calibrating the measurement device with the stand alone system.

539. The method of claim 472, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

540. The method of claim 472, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

541. The method of claim 472, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.

542. The method of claim 472, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.

543. The method of claim 472, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

544. The method of claim 543, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

5 545. The method of claim 544, further comprising altering a parameter of at least one of the instruments in response to the relationship.

546. The method of claim 472, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to at least one of the determined properties of the specimen.

10

547. The method of claim 472, wherein processing the one or more output signals comprises:

15 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

20 further processing the partially processed one or more output signals using the remote controller computer.

548. The method of claim 547, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

25

549. The method of claim 547, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

550. A computer-implemented method for controlling a system configured to determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:

5

controlling the measurement device, wherein the measurement device comprises an illumination system and a detection system, and wherein the measurement device is coupled to a stage, comprising:

10                   controlling the illumination system to direct energy toward a surface of the specimen;

controlling the detection system to detect energy propagating from the surface of the specimen; and

15

generating one or more output signals responsive to the detected energy; and

20

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

551. The method of claim 550, further comprising controlling the stage, wherein the stage is configured to support the specimen.

25

552. The method of claim 550, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.

553. The method of claim 550, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.

5 554. The method of claim 550, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.

555. The method of claim 550, wherein the illumination system comprises a single energy source.

10

556. The method of claim 550, wherein the illumination system comprises more than one energy source.

15

557. The method of claim 550, wherein the detection system comprises a single energy sensitive device.

558. The method of claim 550, wherein the detection system comprises more than one energy sensitive devices.

20

559. The method of claim 550, wherein the measurement device further comprises a non-imaging dark field device.

560. The method of claim 550, wherein the measurement device further comprises a non-imaging bright field device.

25

561. The method of claim 550, wherein the measurement device further comprises a non-imaging dark field and bright field device.

562. The method of claim 550, wherein the measurement device further comprises a double dark field device.
563. The method of claim 550, wherein the measurement device further comprises a dark field imaging device.
564. The method of claim 550, wherein the measurement device further comprises a bright field imaging device.
565. The method of claim 550, wherein the measurement device further comprises a dark field and bright field imaging device.
566. The method of claim 550, wherein the measurement device further comprises a scatterometer.
567. The method of claim 550, wherein the measurement device further comprises a spectroscopic scatterometer.
568. The method of claim 550, wherein the measurement device further comprises an ellipsometer.
569. The method of claim 550, wherein the measurement device further comprises a spectroscopic ellipsometer.
570. The method of claim 550, wherein the measurement device further comprises a reflectometer.

571. The method of claim 550, wherein the measurement device further comprises a spectroscopic reflectometer.
572. The method of claim 550, wherein the measurement device further comprises a  
5 dual beam spectrophotometer.
573. The method of claim 550, wherein the measurement device further comprises a beam profile ellipsometer.
- 10 574. The method of claim 550, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field  
15 imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.
- 20 575. The method of claim 550, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
- 25 576. The method of claim 550, wherein the measurement device comprises non-optical components, and wherein controlling the detection system to detect energy comprises controlling the non-optical components to measure a non-optical characteristic of the surface of the specimen.



577. The method of claim 550, wherein the defects comprise micro defects and macro defects.

5 578. The method of claim 550, wherein the defects comprise micro defects or macro defects.

579. The method of claim 550, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

10

580. The method of claim 550, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

581. The method of claim 550, further comprising processing the one or more output  
15 signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

582. The method of claim 581, wherein the stage and the measurement device are  
20 coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

583. The method of claim 550, wherein processing the one or more output signals to  
25 determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

584. The method of claim 550, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially

simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

5

585. The method of claim 550, wherein the stage and the measurement device are coupled to a process tool.

586. The method of claim 550, wherein the stage and the measurement device are  
10 coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

587. The method of claim 550, wherein the stage and the measurement device are  
coupled to a process tool, and wherein the stage and the measurement device are disposed  
15 within the process tool.

588. The method of claim 550, wherein the stage and the measurement device are  
coupled to a process tool, and wherein the process tool is selected from the group  
consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical  
20 polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

589. The method of claim 550, wherein the stage and the measurement device are  
coupled to a process tool, the method further comprising controlling a wafer handler to  
move the specimen from the process tool to the stage, and wherein the wafer handler is  
25 coupled to the process tool.

590. The method of claim 550, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.
- 5 591. The method of claim 550, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.
- 10 592. The method of claim 550, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.
- 15 593. The method of claim 550, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.
- 20 594. The method of claim 550, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.
595. The method of claim 550, wherein the stage and the measurement device are  
25 disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

596. The method of claim 550, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.
- 5 597. The method of claim 550, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.
598. The method of claim 550, further comprising disposing the specimen upon a  
10 support device disposed within a process chamber of a process tool, wherein the support device is configured to support the specimen during a process step.
599. The method of claim 598, further comprising controlling the illumination system and controlling the detection system during the process step.
- 15 600. The method of claim 598, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.
- 20 601. The method of claim 598, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.
602. The method of claim 550, further comprising controlling the stage to move the  
25 specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

603. The method of claim 602, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.
- 5 604. The method of claim 550, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.
605. The method of claim 550, further comprising comparing at least one of the  
10 determined properties of the specimen to a predetermined range for the property.
606. The method of claim 605, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.
- 15 607. The method of claim 550, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties.
608. The method of claim 550, further comprising altering a parameter of one or more  
20 instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.
609. The method of claim 550, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the  
25 determined properties using a feedforward control technique.
610. The method of claim 550, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

611. The method of claim 610, further comprising calibrating the measurement device using the database.
- 5 612. The method of claim 610, further comprising monitoring output signals of measurement device using the database.
613. The method of claim 610, wherein the database further comprises first and second properties of a plurality of specimens.
- 10 614. The method of claim 613, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.
615. The method of claim 613, further comprising calibrating the plurality of
- 15 measurement devices using the database.
616. The method of claim 613, further comprising monitoring output signals of the plurality of measurement devices using the database.
- 20 617. The method of claim 550, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.
- 25 618. The method of claim 550, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further

controlling the stand alone system to calibrate the system and at least the one additional system.

5 619. The method of claim 550, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

10

620. The method of claim 550, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.

15 621. The method of claim 550, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.

20 622. The method of claim 550, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

623. The method of claim 622, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

25 624. The method of claim 623, further comprising altering a parameter of at least one of the instruments in response to the relationship.

625. The method of claim 550, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to at least one of the determined properties of the specimen.

5 626. The method of claim 550, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

15

627. The method of claim 626, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

20 628. The method of claim 626, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

629. A semiconductor device fabricated by a method, the method comprising:

25

forming a portion of the semiconductor device upon a specimen;



disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

5 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

10 generating one or more output signals in response to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

15

630. The device of claim 629, wherein the illumination system comprises a single energy source.

20 631. The device of claim 629, wherein the illumination system comprises more than one energy source.

632. The device of claim 629, wherein the detection system comprises a single energy sensitive device.

25

633. The device of claim 629, wherein the detection system comprises more than one energy sensitive devices.

634. The device of claim 629, wherein the measurement device further comprises a measurement device selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.
635. The device of claim 629, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.
636. The device of claim 629, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
637. The device of claim 629, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

638. The device of claim 629, wherein the defects comprise micro defects and macro defects.

5 639. The device of claim 629, wherein the defects comprise micro defects or macro defects.

640. The device of claim 629, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

10 641. The device of claim 629, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

642. The device of claim 629, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is  
15 selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

643. The device of claim 642, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an  
20 atomic layer deposition tool, a cleaning tool, and an etch tool.

644. The device of claim 629, wherein the stage and the measurement device are coupled to a process tool.

25 645. The device of claim 629, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

646. A method for fabricating a semiconductor device, comprising:
- 5 forming a portion of the semiconductor device upon a specimen;
- disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;
- 10 directing energy toward a surface of the specimen using the illumination system;
- detecting energy propagating from the surface of the specimen using the detection system;
- 15 generating one or more output signals responsive to the detected energy; and
- processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.
- 20
647. The method of claim 646, wherein the illumination system comprises a single energy source.
- 25 648. The method of claim 646, wherein the illumination system comprises more than one energy source.

649. The method of claim 646, wherein the detection system comprises a single energy sensitive device.

650. The method of claim 646, wherein the detection system comprises more than one  
5 energy sensitive devices.

651. The method of claim 646, wherein the measurement device further comprises a measurement device selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field  
10 device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

15

652. The method of claim 646, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright  
20 field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

25

653. The method of claim 646, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical

elements of the first measurement device comprise optical elements of the second measurement device.

5 654. The method of claim 646, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

655. The method of claim 646, wherein the defects comprise micro defects and macro defects.

10

656. The method of claim 646, wherein the defects comprise micro defects or macro defects.

657. The method of claim 646, wherein the thin film characteristic comprises a  
15 thickness of a copper film, and wherein the defects comprise voids in the copper film.

658. The method of claim 646, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

20 659. The method of claim 646, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

25 660. The method of claim 659, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

661. The method of claim 646, wherein the stage and the measurement device are coupled to a process tool.

662. The method of claim 646, wherein the stage and the measurement device are  
5 coupled to a process tool, and wherein the process tool comprises a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

663. A system configured to determine at least two properties of a specimen during  
10 use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

15

an illumination system configured to direct energy toward a surface of the specimen during use; and

20

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use;

25

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or

more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

664. The system of claim 663, wherein the measurement device further comprises a measurement device selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

665. The system of claim 663, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

666. The system of claim 663, wherein the illumination system and the detection system comprise non-optical components, and the detected energy is responsive to a non-optical characteristic of the surface of the specimen.



667. The system of claim 663, wherein the defects comprise micro defects and macro defects.

5 668. The system of claim 663, wherein the defects comprise micro defects or macro defects.

669. The system of claim 663, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

10

670. The system of claim 663, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

671. The system of claim 663, wherein the remote controller computer is further  
15 configured to determine a third property of the specimen from the at least partially processed one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

20 672. The system of claim 671, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

673. The system of claim 663, wherein the illumination system is further configured to  
25 direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially

simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

5     674.    The system of claim 663, wherein the stage and the measurement device are coupled to a process tool.

675.    The system of claim 663, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical  
10    polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

676.    The system of claim 663, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least  
15    one of the determined properties using a feedback control technique during use.

677.    The system of claim 663, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least  
20    one of the determined properties using a feedforward control technique during use.

678.    The system of claim 663, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.  
25

679.    The system of claim 678, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

680. The system of claim 679, wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

5

681. The system of claim 663, wherein the illumination system is further configured to direct energy toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is  
10 further configured to determine the first and second properties of the specimen during the process step.

682. The system of claim 681, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein  
15 the signature comprises at least one singularity representative of an end of the process step.

683. The system of claim 681, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in  
20 response to at least one of the determined properties using an in situ control technique during use.

684. The system of claim 663, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to  
25 move the specimen from the first process chamber to the second process chamber during use.

685. The system of claim 684, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further  
5 configured to determine the first and second properties of the specimen during said moving.

686. The system of claim 663, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and  
10 properties of a plurality of specimens during use.

687. The system of claim 663, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.  
15

688. The system of claim 687, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

20 689. The system of claim 663, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

25 690. The system of claim 663, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

691. The system of claim 663, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

5

692. The system of claim 663, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

10 693. The system of claim 692, wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

694. The system of claim 692, wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database  
15 during use.

695. The system of claim 692, wherein the database further comprises first and second properties of a plurality of specimens.

20 696. The system of claim 695, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.

697. The system of claim 696, wherein the remote controller computer is further coupled to the plurality of measurement devices.  
25

698. The system of claim 697, wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

699. The system of claim 697, wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

5

700. The system of claim 663, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

10 701. The system of claim 663, wherein the remote controller computer is further coupled to a plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

15 702. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

20

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

25

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of defects on the specimen, and wherein the second property comprises a thin film characteristic of the specimen, comprising:

5

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

15

703. The method of claim 702, wherein the measurement device further comprises a measurement device selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright field device, a double dark field device, a dark field imaging device, a bright field imaging device, a dark field and bright field imaging device, a scatterometer, a spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

20

25

704. The method of claim 702, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging dark field device, a non-imaging bright field device, a non-imaging dark field and bright

field device, a double dark field device, a dark field imaging device, a bright field  
imaging device, a dark field and bright field imaging device, a scatterometer, a  
spectroscopic scatterometer, an ellipsometer, a spectroscopic ellipsometer, a  
reflectometer, a spectroscopic reflectometer, a dual beam spectrophotometer, and a beam  
5 profile ellipsometer.

705. The method of claim 702, wherein the measurement device comprises non-optical  
components, and wherein detecting energy comprises measuring a non-optical  
characteristic of the surface of the specimen.

10

706. The method of claim 702, wherein the defects comprise micro defects and macro  
defects.

707. The method of claim 702, wherein the defects comprise micro defects or macro  
15 defects.

708. The method of claim 702, wherein the thin film characteristic comprises a  
thickness of a copper film, and wherein the defects comprise voids in the copper film.

20 709. The method of claim 702, wherein the defects comprise macro defects on a back  
side of the specimen, and wherein the macro defects comprise copper contamination.

710. The method of claim 702, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
25 selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.



711. The method of claim 710, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 712. The method of claim 702, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

10

713. The method of claim 702, wherein the stage and the measurement device are coupled to a process tool.

15 714. The method of claim 702, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

20 715. The method of claim 702, wherein the stage and the measurement device are coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback control technique.

25 716. The method of claim 702, wherein the stage and the measurement device are coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in

response to at least one of the determined properties of the specimen using a feedforward control technique.

717. The method of claim 702, wherein the stage and the measurement device are  
5 coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

718. The method of claim 717, further comprising determining a relationship between  
at least one of the determined properties and at least one of the monitored parameters  
10 using the remote controller computer.

719. The method of claim 718, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

15 720. The method of claim 702, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, the method further comprising performing said directing and said detecting during a process step.

721. The method of claim 720, further comprising obtaining a signature characterizing  
20 the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

722. The method of claim 720, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response  
25 to at least one of the determined properties using an in situ control technique.

723. The method of claim 702, further comprising:

moving the specimen from a first process chamber to a second process chamber using the stage;

performing said directing and said detecting during said moving the specimen.

5

724. The method of claim 702, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

10 725. The method of claim 702, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

15 726. The method of claim 725, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

727. The method of claim 702, wherein the remote controller computer is coupled to the measurement device.

20

728. The method of claim 727, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to at least one of the determined properties of the specimen.

25 729. The method of claim 727, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control technique.

730. The method of claim 727, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedforward control technique.

5

731. The method of claim 702, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen.

10 732. The method of claim 731, further comprising calibrating the measurement device using the remote controller computer and the database.

733. The method of claim 731, further comprising monitoring output signals from the measurement device using the remote controller computer and the database.

15

734. The method of claim 731, wherein the database further comprises first and second properties of a plurality of specimens.

20 735. The method of claim 734, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

736. The method of claim 735, further comprising calibrating the plurality of measurement devices using the remote controller computer and the database.

25 737. The method of claim 735, further comprising monitoring the plurality of measurement devices using the remote controller computer and the database.

738. The method of claim 702, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

5

739. The method of claim 738, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to at least one of the determined properties of the specimen.

10

740. The method of claim 738, wherein each of the plurality of measurement devices is coupled to one of a plurality of process tools.

741. The method of claim 740, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of process tools using the remote controller computer in response to at least one of the determined properties of the specimen.

15

742. A system configured to determine at least two properties of a specimen during use, comprising:

20

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

25

an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals in response to the detected energy during use; and

5

a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a presence of defects on the specimen.

10

743. The system of claim 742, wherein the stage is further configured to move laterally during use.

15 744. The system of claim 742, wherein the stage is further configured to move rotatably during use.

745. The system of claim 742, wherein the stage is further configured to move laterally and rotatably during use.

20

746. The system of claim 742, wherein the illumination system comprises a single energy source.

25 747. The system of claim 742, wherein the illumination system comprises more than one energy source.

748. The system of claim 742, wherein the detection system comprises a single energy sensitive device.

749. The system of claim 742, wherein the detection system comprises more than one energy sensitive devices.

5 750. The system of claim 742, wherein the measurement device further comprises a non-imaging scatterometer.

751. The system of claim 742, wherein the measurement device further comprises a scatterometer.

10

752. The system of claim 742, wherein the measurement device further comprises a spectroscopic scatterometer.

15 753. The system of claim 742, wherein the measurement device further comprises a reflectometer.

754. The system of claim 742, wherein the measurement device further comprises a spectroscopic reflectometer.

20 755. The system of claim 742, wherein the measurement device further comprises a coherence probe microscope.

756. The system of claim 742, wherein the measurement device further comprises an ellipsometer.

25

757. The system of claim 742, wherein the measurement device further comprises a spectroscopic ellipsometer.

758. The system of claim 742, wherein the measurement device further comprises a bright field imaging device.

759. The system of claim 742, wherein the measurement device further comprises a  
5 dark field imaging device.

760. The system of claim 742, wherein the measurement device further comprises a bright field and dark field imaging device.

10 761. The system of claim 742, wherein the measurement device further comprises a non-imaging bright field device.

762. The system of claim 742, wherein the measurement device further comprises a non-imaging dark field device.

15

763. The system of claim 742, wherein the measurement device further comprises a non-imaging bright field and dark field device.

764. The system of claim 742, wherein the measurement device further comprises at  
20 least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a  
25 bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.



765. The system of claim 742, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

5

766. The system of claim 742, wherein the defects comprise micro defects and macro defects.

767. The system of claim 742, wherein the defects comprises micro defects or macro defects.

10

768. The system of claim 742, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

15

769. The system of claim 768, wherein the defects comprise macro defects.

770. The system of claim 742, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

20

25

771. The system of claim 770, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

772. The system of claim 742, wherein the system is further configured to determine at least two properties of the specimen substantially simultaneously during use.

5 773. The system of claim 742, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be  
10 determined at the multiple locations substantially simultaneously.

774. The system of claim 742, wherein the system is coupled to a process tool.

775. The system of claim 742, wherein the system is coupled to a process tool, and  
15 wherein the system is disposed within the process tool.

776. The system of claim 742, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

20 777. The system of claim 742, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

778. The system of claim 742, wherein the system is coupled to a process tool, and  
25 wherein the stage is configured to move the specimen from the system to the process tool during use.

779. The system of claim 742, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

5 780. The system of claim 742, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

10 781. The system of claim 742, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

15 782. The system of claim 742, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

783. The system of claim 742, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement  
20 chamber, and wherein the measurement chamber is coupled to a process tool.

784. The system of claim 742, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within the process tool.

25

785. The system of claim 742, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement

chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of the process tool.

5 786. The system of claim 742, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of the process tool.

10 787. The system of claim 742, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

15 788. The system of claim 787, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

789. The system of claim 788, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

20 790. The system of claim 788, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique during use.

25 791. The system of claim 742, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

792. The system of claim 742, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the system is further configured to determine at least the two properties of the specimen as the stage is moving the specimen  
5 from the first process chamber to the second process chamber.

793. The system of claim 742, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.  
10

794. The system of claim 742, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

15 795. The system of claim 794, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

796. The system of claim 742, wherein the processor is further configured to alter a  
20 sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

797. The system of claim 742, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to  
25 the determined first or second property using a feedback control technique during use.

798. The system of claim 742, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

5 799. The system of claim 742, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

800. The system of claim 799, wherein the processor is further configured to calibrate  
10 the measurement device using the database during use.

801. The system of claim 799, wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

15 802. The system of claim 799, wherein the database further comprises first and second properties of a plurality of specimens.

803. The system of claim 802, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.  
20

804. The system of claim 803, wherein the processor is further coupled to the plurality of measurement devices.

805. The system of claim 804, wherein the processor is further configured to calibrate  
25 the plurality of measurement devices using the database during use.

806. The system of claim 804, wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

5 807. The system of claim 742, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

10 808. The system of claim 742, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

15

809. The system of claim 742, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to  
20 at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

25

810. The system of claim 742, wherein the processor is further coupled to a process tool.

811. The system of claim 742, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more

instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.

5 812. The system of claim 742, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.

10 813. The system of claim 742, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

15 814. The system of claim 813, wherein the processor is further configured to determine a relationship between the determined properties and at least one of the monitored parameter during use.

815. The system of claim 814, wherein the processor is further configured to alter the parameter of at least one of the instruments in response to the relationship during use.

20 816. The system of claim 742, wherein the processor is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

25 817. The system of claim 742, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.



818. The system of claim 817, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

5 819. The system of claim 817, wherein the remote controller computer is further configured to determine the first property and the second property of the specimen during use.

820. A method for determining at least two properties of a specimen, comprising:  
10 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;  
15 directing energy toward a surface of the specimen using the illumination system;  
detecting energy propagating from the surface of the specimen using the detection system;  
20 generating one or more output signals responsive to the detected energy; and  
processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a presence  
25 of defects on the specimen.

821. The method of claim 820, further comprising laterally moving the stage during said directing energy and said detecting energy.

822. The method of claim 820, further comprising rotatably moving the stage during said directing energy and said detecting energy.

5 823. The method of claim 820, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

824. The method of claim 820, wherein the illumination system comprises a single energy source.

10

825. The method of claim 820, wherein the illumination system comprises more than one energy source.

15

826. The method of claim 820, wherein the detection system comprises a single energy sensitive device.

827. The method of claim 820, wherein the detection system comprises more than one energy sensitive devices.

20

828. The method of claim 820, wherein the measurement device further comprises a non-imaging scatterometer.

829. The method of claim 820, wherein the measurement device further comprises a scatterometer.

25

830. The method of claim 820, wherein the measurement device further comprises a spectroscopic scatterometer.

831. The method of claim 820, wherein the measurement device further comprises a reflectometer.
- 5 832. The method of claim 820, wherein the measurement device further comprises a spectroscopic reflectometer.
833. The method of claim 820, wherein the measurement device further comprises a coherence probe microscope.
- 10 834. The method of claim 820, wherein the measurement device further comprises an ellipsometer.
835. The method of claim 820, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 15 836. The method of claim 820, wherein the measurement device further comprises a bright field imaging device.
837. The method of claim 820, wherein the measurement device further comprises a dark field imaging device.
- 20 838. The method of claim 820, wherein the measurement device further comprises a bright field and dark field imaging device.
- 25 839. The method of claim 820, wherein the measurement device further comprises a non-imaging bright field device.

840. The method of claim 820, wherein the measurement device further comprises a non-imaging dark field device.

841. The method of claim 820, wherein the measurement device further comprises and  
5 a non-imaging bright field and dark field device.

842. The method of claim 820, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
10 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

15 843. The method of claim 820, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

20 844. The method of claim 820, wherein the defects comprise micro defects and macro defects.

845. The method of claim 820, wherein the defects comprises micro defects or macro  
25 defects.

846. The method of claim 820, further comprising:

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein  
the second property comprises a presence of defects on the bottom surface of the  
specimen.

. 5

847. The method of claim 846, wherein the defects comprise macro defects.

848. The method of claim 820, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.

10

849. The method of claim 848, wherein the stage and the measurement device are  
coupled to a process tool selected from the group consisting of a lithography tool, an  
atomic layer deposition tool, a cleaning tool, and an etch tool.

15

850. The method of claim 820, wherein processing the one or more output signals to  
determine the first and second properties of the specimen comprises substantially  
simultaneously determining the first and second properties of the specimen.

20

851. The method of claim 820, further comprising directing energy toward multiple  
locations on the surface of the specimen substantially simultaneously and detecting  
energy propagating from the multiple locations substantially simultaneously such that one  
or more of the at least two properties of the specimen can be determined at the multiple  
locations substantially simultaneously.

25

852. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool.

5 853. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

854. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed  
10 within the process tool.

855. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

15

856. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

20

857. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

25 858. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

859. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

5

860. The method of claim 820, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

10

861. The method of claim 820, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

15

862. The method of claim 820, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within the process tool.

20

863. The method of claim 820, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of the process tool.

25

864. The method of claim 820, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of the process tool.

865. The method of claim 820, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process

chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

866. The method of claim 865, further comprising performing said directing and said  
5 detecting during the process step.

867. The method of claim 866, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

10 868. The method of claim 866, further comprising altering a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.

15 869. The method of claim 820, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

20 870. The method of claim 869, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

25 871. The method of claim 820, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

872. The method of claim 820, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.



873. The method of claim 872, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5

874. The method of claim 820, further comprising altering a sampling frequency of the measurement device in response to the determined first or second property of the specimen.

10 875. The method of claim 820, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

15 876. The method of claim 820, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

877. The method of claim 820, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

20

878. The method of claim 877, further comprising calibrating the measurement device using the database.

25 879. The method of claim 877, further comprising monitoring output signals of the measurement device using the database.

880. The method of claim 877, wherein the database further comprises first and second properties of a plurality of specimens.

881. The method of claim 880, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

5 882. The method of claim 881, further comprising calibrating the plurality of measurement devices using the database.

883. The method of claim 881, further comprising monitoring output signals of the plurality of measurement devices using the database.

10

884. The method of claim 820, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

15

885. The method of claim 820, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device and at least the one additional measurement device with the stand alone system.

20

886. The method of claim 820, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

25

887. The method of claim 820, further comprising altering a parameter of one or more instrument coupled to a process tool in response to the determined first or second property of the specimen using a feedback control technique.
- 5 888. The method of claim 820, further comprising altering a parameter of one or more instrument coupled to a process tool in response to the determined first or second property of the specimen using a feedforward control technique.
889. The method of claim 820, further comprising monitoring a parameter of one or  
10 more instruments coupled to a process tool.
890. The method of claim 889, further comprising determining a relationship between the determined properties and at least one of the monitored parameters.
- 15 891. The method of claim 890, further comprising altering the parameter of at least one of the instruments in response to the relationship.
892. The method of claim 820, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to the determined  
20 first or second property of the specimen.
893. The method of claim 820, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

894. The method of claim 893, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

10 895. The method of claim 893, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

896. A computer-implemented method for controlling a system configured to  
15 determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:

controlling the measurement device, wherein the measurement device comprises  
an illumination system and a detection system, and wherein the measurement  
20 device is coupled to a stage, comprising:

controlling the illumination system to direct energy toward a surface of the  
specimen;

25 controlling the detection system to detect energy propagating from the  
surface of the specimen; and

generating one or more output signals responsive to the detected energy;  
and

5        processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises a critical  
dimension of the specimen, and wherein the second property comprises a presence  
of defects on the specimen.

897.    The method of claim 896, further comprising controlling the stage, wherein the  
10    stage is configured to support the specimen.

898.    The method of claim 896, further comprising controlling the stage to move  
laterally during said directing energy and said detecting energy.

15    899.    The method of claim 896, further comprising controlling the stage to move  
rotatably during said directing energy and said detecting energy.

900.    The method of claim 896, further comprising controlling the stage to move  
laterally and rotatably during said directing energy and said detecting energy.

20

901.    The method of claim 896, wherein the illumination system comprises a single  
energy source.

902.    The method of claim 896, wherein the illumination system comprises more than  
25    one energy source.

903.    The method of claim 896, wherein the detection system comprises a single energy  
sensitive device.

904. The method of claim 896, wherein the detection system comprises more than one energy sensitive devices.

5 905. The method of claim 896, wherein the measurement device further comprises a non-imaging scatterometer.

906. The method of claim 896, wherein the measurement device further comprises a scatterometer.

10

907. The method of claim 896, wherein the measurement device further comprises a spectroscopic scatterometer.

15 908. The method of claim 896, wherein the measurement device further comprises a reflectometer.

909. The method of claim 896, wherein the measurement device further comprises a spectroscopic reflectometer.

20 910. The method of claim 896, wherein the measurement device further comprises a coherence probe microscope.

911. The method of claim 896, wherein the measurement device further comprises an ellipsometer.

25

912. The method of claim 896, wherein the measurement device further comprises a spectroscopic ellipsometer.

913. The method of claim 896, wherein the measurement device further comprises a bright field imaging device.
914. The method of claim 896, wherein the measurement device further comprises a  
5 dark field imaging device.
915. The method of claim 896, wherein the measurement device further comprises a bright field and dark field imaging device.
- 10 916. The method of claim 896, wherein the measurement device further comprises a non-imaging bright field device.
917. The method of claim 896, wherein the measurement device further comprises a non-imaging dark field device.  
15
918. The method of claim 896, wherein the measurement device further comprises and a non-imaging bright field and dark field device.
919. The method of claim 896, wherein the measurement device further comprises at  
20 least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a  
25 bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

920. The method of claim 896, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

5

921. The method of claim 896, wherein the defects comprise micro defects and macro defects.

922. The method of claim 896, wherein the defects comprises micro defects or macro defects.

10

923. The method of claim 896, further comprising:

controlling the illumination system to direct energy toward a bottom surface of the specimen; and

15

controlling the detection system to detect energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

20

924. The method of claim 923, wherein the defects comprise macro defects.

925. The method of claim 896, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

25



926. The method of claim 925, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

- 5 927. The method of claim 896, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

928. The method of claim 896, further comprising controlling the illumination system  
10 to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

15

929. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool.

930. The method of claim 896, wherein the stage and the measurement device are  
20 coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

931. The method of claim 896, wherein the stage and the measurement device are  
25 coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

932. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

5 933. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is coupled to the process tool.

10 934. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.

15 935. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.

20 936. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

25 937. The method of claim 896, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

938. The method of claim 896, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

5 939. The method of claim 896, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

940. The method of claim 896, wherein the stage and the measurement device are  
10 disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

941. The method of claim 896, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is  
• 15 arranged vertically proximate to a process chamber of a process tool.

942. The method of claim 896, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.  
20

943. The method of claim 942, further comprising controlling the illumination system and controlling the detection system during the process step.

944. The method of claim 943, further comprising controlling the system to obtain a  
25 signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

945. The method of claim 943, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.
- 5 946. The method of claim 896, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.
947. The method of claim 946, further comprising controlling the illumination system  
10 and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.
948. The method of claim 896, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of  
15 specimens.
949. The method of claim 896, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.
- 20 950. The method of claim 949, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.
951. The method of claim 896, further comprising altering a sampling frequency of the  
25 measurement device in response to the determined first or second property of the specimen.

952. The method of claim 896, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.
- 5 953. The method of claim 896, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.
954. The method of claim 896, further comprising generating a database, wherein the  
10 database comprises the determined first and second properties of the specimen.
955. The method of claim 954, further comprising calibrating the measurement device using the database.
- 15 956. The method of claim 954, further comprising monitoring output signals of the measurement device using the database.
957. The method of claim 954, wherein the database further comprises first and second properties of a plurality of specimens.  
20
958. The method of claim 957, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.
959. The method of claim 958, further comprising calibrating the plurality of  
25 measurement devices using the database.
960. The method of claim 958, further comprising monitoring output signals of the plurality of measurement devices using the database.

961. The method of claim 896, wherein a stand alone system is coupled to the system,  
the method further comprising controlling the stand alone system to calibrate the stand  
alone system with a calibration standard and further controlling the stand alone system to  
5 calibrate the system.

962. The method of claim 896, wherein a stand alone system is coupled to the system  
and at least one additional system, the method further comprising controlling the stand  
alone system to calibrate the stand alone system with a calibration standard and further  
10 controlling the stand alone system to calibrate the system and at least the one additional  
system.

963. The method of claim 896, wherein the system is further configured to determine at  
least the two properties of the specimen at more than one position on the specimen, and  
15 wherein the specimen comprises a wafer, the method further comprising altering at least  
one parameter of one or more instruments coupled to a process tool in response to at least  
one of the determined properties of the specimen at the more than one position on the  
specimen to reduce within wafer variation of at least one of the determined properties.

20 964. The method of claim 896, further comprising altering a parameter of one or more  
instruments coupled to a process tool in response to the determined first or second  
property of the specimen using a feedback control technique.

965. The method of claim 896, further comprising altering a parameter of one or more  
25 instruments coupled to a process tool in response to the determined first or second  
property of the specimen using a feedforward control technique.

966. The method of claim 896, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

5 967. The method of claim 966, further comprising determining a relationship between the determined properties and at least one of the monitored parameters.

968. The method of claim 967, further comprising altering a parameter of one or more of the instruments in response to the relationship.

10 969. The method of claim 896, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to the determined first or second property of the specimen.

15 970. The method of claim 896, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

20 sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

25

971. The method of claim 970, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

972. The method of claim 970, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

5 973. A semiconductor device fabricated by a method, the method comprising:

forming a portion of the semiconductor device upon a specimen;

10 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

15 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

20 processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the portion of the specimen, and wherein the second property comprises a presence of defects on the portion of the specimen.

25 974. The device of claim 973, wherein the illumination system comprises a single energy source.



975. The device of claim 973, wherein the illumination system comprises more than one energy source.

976. The device of claim 973, wherein the detection system comprises a single energy  
5 sensitive device.

977. The device of claim 973, wherein the detection system comprises more than one energy sensitive devices.

10 978. The device of claim 973, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging  
15 bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

979. The device of claim 973, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first  
20 and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-  
25 imaging dark field device, and a non-imaging bright field and dark field device.

980. The device of claim 973, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical

elements of the first measurement device comprise optical elements of the second measurement device.

5 981. The device of claim 973, wherein the defects comprise micro defects and macro defects.

982. The device of claim 973, wherein the defects comprises micro defects or macro defects.

10 983. The device of claim 973, further comprising:

directing energy toward a bottom surface of the specimen; and

15 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

984. The device of claim 983, wherein the defects comprise macro defects.

20 985. The device of claim 973, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

25 986. The device of claim 973, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

987. The device of claim 973, wherein the stage and the measurement device are coupled to a process tool.

988. The device of claim 973, wherein the stage and the measurement device are  
5 coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

989. A method for fabricating a semiconductor device, comprising:

10 forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

15

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

20

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical  
25 dimension of the specimen, and wherein the second property comprises a presence of defects on the portion of the specimen.

990. The method of claim 989, wherein the illumination system comprises a single energy source.

991. The method of claim 989, wherein the illumination system comprises more than  
5 one energy source.

992. The method of claim 989, wherein the detection system comprises a single energy sensitive device.

10 993. The method of claim 989, wherein the detection system comprises more than one energy sensitive devices.

994. The method of claim 989, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic  
15 scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

20 995. The method of claim 989, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a  
25 spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

996. The method of claim 989, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second  
5 measurement device.

997. The method of claim 989, wherein the defects comprise micro defects and macro defects.

10 998. The method of claim 989, wherein the defects comprises micro defects or macro defects.

999. The method of claim 989, further comprising:

15 directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

20

1000. The method of claim 999, wherein the defects comprise macro defects.

1001. The method of claim 989, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is  
25 selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1002. The method of claim 1001, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 1003. The method of claim 989, wherein the stage and the measurement device are coupled to a process tool.

1004. The method of claim 989, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group  
10 consisting of a lithography tool and an etch tool.

1005. A system configured to determine at least two properties of a specimen during use, comprising:

15 a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

20 an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more  
25 output signals responsive to the detected energy during use;

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a presence of defects on the specimen.

1006. The system of claim 1005, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a spectroscopic ellipsometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

1007. The system of claim 1005, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, and a non-imaging bright field and dark field device.

1008. The system of claim 1005, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical

elements of the first measurement device comprise optical elements of the second measurement device.

5 1009. The system of claim 1005, wherein the defects comprise micro defects and macro defects.

1010. The system of claim 1005, wherein the defects comprises micro defects or macro defects.

10 1011. The system of claim 1005, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

15

1012. The system of claim 1011, wherein the defects comprise macro defects.

1013. The system of claim 1005, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially  
20 processed one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1014. The system of claim 1013, wherein the system is coupled to a process tool  
25 selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.



1015. The system of claim 1005, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.
1016. The system of claim 1005, wherein the remote controller computer is coupled to a process tool.
1017. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from a group consisting of a lithography tool, an etch tool, and a deposition tool.
1018. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.
1019. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.
1020. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instrument coupled to the process tool during use.

1021. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use, and wherein the remote controller computer is further configured to determine a relationship between the determined properties and at least one of the monitored parameters during use.

1022. The system of claim 1005, wherein the remote controller computer is coupled to a process tool, wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use, wherein the remote controller computer is further configured to determine a relationship between the determined properties and the at least one of the monitored parameters during use, and wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

1023. The system of claim 1005, wherein the system and the remote controller computer are coupled to a process tool, wherein the process tool is configured to perform a step of a process, wherein the illumination system is further configured to direct energy toward the surface of the specimen during the process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during the process step.

1024. The system of claim 1023, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

1025. The system of claim 1023, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using an in situ control technique during use.

5

1026. The system of claim 1005, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

10

1027. The system of claim 1026, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

15

1028. The system of claim 1005, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

20

1029. The system of claim 1005, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

25

1030. The system of claim 1029, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

1031. The system of claim 1005, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

5

1032. The system of claim 1005, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique during use.

10

1033. The system of claim 1005, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

15

1034. The system of claim 1005, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

20

1035. The system of claim 1034, wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

1036. The system of claim 1034, wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

25

1037. The system of claim 1034, wherein the database further comprises first and second properties of a plurality of specimens.

1038. The system of claim 1037, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.
- 5 1039. The system of claim 1038, wherein the remote controller computer is further coupled to the plurality of measurement devices.
1040. The system of claim 1039, wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during  
10 use.
1041. The system of claim 1039, wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.  
15
1042. The system of claim 1005, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.
- 20 1043. The system of claim 1042, wherein the remote controller computer is further coupled to at least one of the plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.
- 25 1044. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

5 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

10 generating one or more output signals in response to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a presence  
15 of defects on the specimen, comprising:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

20

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using  
25 the remote controller computer.

1045. The method of claim 1044, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic

scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
microscope, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a  
dark field imaging device, a bright field and dark field imaging device, a non-imaging  
bright field device, a non-imaging dark field device, and a non-imaging bright field and  
5 dark field device.

1046. The method of claim 1044, wherein the measurement device further comprises at  
least a first measurement device and a second measurement device, and wherein the first  
and second measurement devices are selected from the group consisting of a non-imaging  
10 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a  
spectroscopic reflectometer, a coherence probe microscope, an ellipsometer, a  
spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a  
bright field and dark field imaging device, a non-imaging bright field device, a non-  
imaging dark field device, and a non-imaging bright field and dark field device.

15

1047. The method of claim 1044, wherein the measurement device further comprises at  
least a first measurement device and a second measurement device, and wherein optical  
elements of the first measurement device comprise optical elements of the second  
measurement device.

20

1048. The method of claim 1044, wherein the defects comprise micro defects and macro  
defects.

1049. The method of claim 1044, wherein the defects comprises micro defects or macro  
25 defects.

1050. The method of claim 1044, further comprising:

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein  
the second property comprises a presence of defects on the bottom surface of the  
specimen.

5

1051. The method of claim 1050, wherein the defects comprise macro defects.

1052. The method of claim 1044, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.

10

1053. The method of claim 1052, wherein the stage and the measurement device are  
coupled to a process tool selected from the group consisting of a lithography tool, an  
atomic layer deposition tool, a cleaning tool, and an etch tool.

15

1054. The method of claim 1044, further comprising directing energy toward multiple  
locations on the surface of the specimen substantially simultaneously and detecting  
energy propagating from the multiple locations substantially simultaneously such that one  
or more of the at least two properties of the specimen can be determined at the multiple  
locations substantially simultaneously.

20

1055. The method of claim 1044, wherein the remote controller computer is coupled to a  
process tool.

25



1056. The method of claim 1044, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

5 1057. The method of claim 1044, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property of the specimen using a feedback control technique.

10

1058. The method of claim 1044, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property of the specimen using a feedforward control technique.

15

1059. The method of claim 1044, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

20

1060. The method of claim 1059, further comprising determining a relationship between the determined properties and the monitored parameters using the remote controller computer.

25

1061. The method of claim 1060, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

1062. The method of claim 1044, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, the method further comprising performing said directing and said detecting during a process step.

- 5 1063. The method of claim 1062, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

1064. The method of claim 1062, further comprising altering a parameter of one or more  
10 instruments coupled to the process tool using the remote controller computer in response to the determined first or second property using an in situ control technique.

1065. The method of claim 1044, further comprising:

- 15 moving the specimen from a first process chamber to a second process chamber using the stage;

performing said directing and said detecting during said moving the specimen.

- 20 1066. The method of claim 1044, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

1067. The method of claim 1044, further comprising comparing at least one of the  
25 determined properties of the specimen to a predetermined range for the property using the remote controller computer.

1068. The method of claim 1067, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5 1069. The method of claim 1044, wherein the remote controller computer is coupled to the measurement device.

1070. The method of claim 1069, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to the  
10 determined first or second property of the specimen.

1071. The method of claim 1069, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedback control technique.

15

1072. The method of claim 1069, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedforward control technique.

20 1073. The method of claim 1044, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen.

1074. The method of claim 1073, further comprising calibrating the measurement device  
25 using the database and the remote controller computer.

1075. The method of claim 1073, further comprising monitoring output signals of the measurement device using the database and the remote controller computer.

1076. The method of claim 1073, wherein the database further comprises first and second properties of a plurality of specimens.

5 1077. The method of claim 1076, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

1078. The method of claim 1077, further comprising calibrating the plurality of measurement devices using the database and the remote controller computer.

10

1079. The method of claim 1077, further comprising monitoring output signals of the plurality of measurement devices using the database and the remote controller computer.

1080. The method of claim 1044, further comprising sending the at least partially  
15 processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

1081. The method of claim 1080, wherein each of the plurality of measurement devices  
20 is coupled to at least one of a plurality of process tools.

1082. The method of claim 1081, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of process tools using the remote controller computer in response to the determined first or second property of the  
25 specimen.

1083. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

5

an illumination system configured to direct energy toward a surface of the specimen during use; and

10

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals in response to the detected energy during use; and

15

a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a thin film characteristic of the specimen.

20

1084. The system of claim 1083, wherein the stage is further configured to move laterally during use.

1085. The system of claim 1083, wherein the stage is further configured to move rotatably during use.

25

1086. The system of claim 1083, wherein the stage is further configured to move laterally and rotatably during use.

1087. The system of claim 1083, wherein the illumination system comprises a single energy source.

5 1088. The system of claim 1083, wherein the illumination system comprises more than one energy source.

1089. The system of claim 1083, wherein the detection system comprises a single energy sensitive device.

10 1090. The system of claim 1083, wherein the detection system comprises more than one energy sensitive devices.

1091. The system of claim 1083, wherein the measurement device further comprises a non-imaging scatterometer.

15

1092. The system of claim 1083, wherein the measurement device further comprises a scatterometer.

20 1093. The system of claim 1083, wherein the measurement device further comprises a spectroscopic scatterometer.

1094. The system of claim 1083, wherein the measurement device further comprises a reflectometer.

25 1095. The system of claim 1083, wherein the measurement device further comprises a spectroscopic reflectometer.

1096. The system of claim 1083, wherein the measurement device further comprises a coherence probe microscope.
- 5 1097. The system of claim 1083, wherein the measurement device further comprises a bright field imaging device.
1098. The system of claim 1083, wherein the measurement device further comprises a dark field imaging device.
- 10 1099. The system of claim 1083, wherein the measurement device further comprises a bright field and dark field imaging device.
1100. The system of claim 1083, wherein the measurement device further comprises an ellipsometer.
- 15 1101. The system of claim 1083, wherein the measurement device further comprises a spectroscopic ellipsometer.
1102. The system of claim 1083, wherein the measurement device further comprises a dual beam spectrophotometer.
- 20 1103. The system of claim 1083, wherein the measurement device further comprises a beam profile ellipsometer.
- 25 1104. The system of claim 1083, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a

spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grating X-ray reflectometer.

5

1105. The system of claim 1083, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10

1106. The system of claim 1083, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

15

1107. The system of claim 1083, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

20

1108. The system of claim 1083, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is coupled to an atomic layer deposition tool.

25

1109. The system of claim 1083, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.



1110. The system of claim 1109, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

- 5     1111. The system of claim 1083, wherein the system is further configured to determine at least the two properties of the specimen substantially simultaneously during use.

1112. The system of claim 1083, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially  
10 simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

- 15     1113. The system of claim 1083, wherein the system is coupled to a process tool.

1114. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

- 20     1115. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

1116. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to  
25 the stage during use.

1117. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.

- 5 1118. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

- 10 1119. The system of claim 1083, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

- 15 1120. The system of claim 1083, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

- 20 1121. The system of claim 1083, wherein the system is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

- 25 1122. The system of claim 1083, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

1123. The system of claim 1083, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

5

1124. The system of claim 1083, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

10

1125. The system of claim 1083, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of is process tool.

15

1126. The system of claim 1083, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

20 1127. The system of claim 1126, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

1128. The system of claim 1127, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises  
25 at least one singularity representative of an end of the process step.

1129. The system of claim 1127, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the

process tool in response to the determined properties using an in situ control technique during use.

5 1130. The system of claim 1083, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

10 1131. The system of claim 1130, wherein the system is further configured to determine at least the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

15 1132. The system of claim 1083, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

20 1133. The system of claim 1083, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

1134. The system of claim 1133, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

25 1135. The system of claim 1083, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

1136. The system of claim 1083, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique during use.
- 5 1137. The system of claim 1083, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.
1138. The system of claim 1083, wherein the processor is further configured to generate  
10 a database during use, wherein the database comprises the determined first and second properties of the specimen.
1139. The system of claim 1138, wherein the processor is further configured to calibrate the measurement device using the database during use.
- 15 1140. The system of claim 1139, wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.
1141. The system of claim 1139, wherein the database further comprises first and  
20 second properties of a plurality of specimens.
1142. The system of claim 1141, wherein the first and second properties of the plurality of specimens are determined using the measurement device.
- 25 1143. The system of claim 1141, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.

1144. The system of claim 1143, wherein the processor is further coupled to the plurality of measurement devices.

5 1145. The system of claim 1144, wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

1146. The system of claim 1144, wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

10

1147. The system of claim 1083, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

15

1148. The system of claim 1083, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

20

1149. The system of claim 1083, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter  
25 at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1150. The system of claim 1083, wherein the processor is further coupled to a process tool.

1151. The system of claim 1150, wherein the processor is further configured to alter a  
5 parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.

1152. The system of claim 1150, wherein the processor is further configured to alter a  
10 parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.

1153. The system of claim 1150, wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

1154. The system of claim 1153, wherein the processor is further configured to  
15 determine a relationship between the determined properties and the monitored parameters during use.

1155. The system of claim 1154, wherein the processor is further configured to alter a  
20 parameter of one or more instruments coupled to the process tool in response to the relationship during use.

1156. The system of claim 1083, wherein the processor is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is  
25 coupled to at least one of a plurality of process tools.

1157. The system of claim 1083, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local

processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

- 5    1158. The system of claim 1157, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

1159. The system of claim 1157, wherein the remote controller computer is further configured to determine the first property and the second property of the specimen during  
10    use.

1160. A method for determining at least two properties of a specimen, comprising:

15        disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

20        detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals in response to the detected energy; and

25        processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a thin film characteristic of the specimen.



1161. The method of claim 1160, further comprising laterally moving the stage during said directing energy and said detecting energy.

5 1162. The method of claim 1160, further comprising rotatably moving the stage during said directing energy and said detecting energy.

1163. The method of claim 1160, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

10

1164. The method of claim 1160, wherein the illumination system comprises a single energy source.

15 1165. The method of claim 1160, wherein the illumination system comprises more than one energy source.

1166. The method of claim 1160, wherein the detection system comprises a single energy sensitive device.

20 1167. The method of claim 1160, wherein the detection system comprises more than one energy sensitive devices.

1168. The method of claim 1160, wherein the measurement device further comprises a non-imaging scatterometer.

25

1169. The method of claim 1160, wherein the measurement device further comprises a scatterometer.

1170. The method of claim 1160, wherein the measurement device further comprises a spectroscopic scatterometer.

5 1171. The method of claim 1160, wherein the measurement device further comprises a reflectometer.

1172. The method of claim 1160, wherein the measurement device further comprises a spectroscopic reflectometer.

10 1173. The method of claim 1160, wherein the measurement device further comprises a coherence probe microscope.

1174. The method of claim 1160, wherein the measurement device further comprises a bright field imaging device.

15 1175. The method of claim 1160, wherein the measurement device further comprises a dark field imaging device.

1176. The method of claim 1160, wherein the measurement device further comprises a  
20 bright field and dark field imaging device.

1177. The method of claim 1160, wherein the measurement device further comprises an ellipsometer.

25 1178. The method of claim 1160, wherein the measurement device further comprises a spectroscopic ellipsometer.

1179. The method of claim 1160, wherein the measurement device further comprises a dual beam spectrophotometer.

1180. The method of claim 1160, wherein the measurement device further comprises a  
5 beam profile ellipsometer.

1181. The method of claim 1160, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
10 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grating X-ray reflectometer.

15

1182. The method of claim 1160, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

20

1183. The method of claim 1160, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

25 1184. The method of claim 1160, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1185. The method of claim 1160, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

5 1186. The method of claim 1160, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

10 1187. The method of claim 1186, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

1188. The method of claim 1160, wherein processing the one or more output signals to  
15 determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

1189. The method of claim 1160, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting  
20 energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

1190. The method of claim 1160, wherein the stage and the measurement device are  
25 coupled to a process tool.

1191. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

5 1192. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

1193. The method of claim 1160, wherein the stage and the measurement device are  
10 coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

1194. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and  
15 wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

1195. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the  
20 process tool subsequent to said directing and said detecting using the stage.

1196. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.  
25

1197. The method of claim 1160, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured

to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

1198. The method of claim 1160, wherein the stage and the measurement device are  
5 coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

1199. The method of claim 1160, wherein the stage and the measurement device are  
10 disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

1200. The method of claim 1160, wherein the stage and the measurement device are  
disposed within a measurement chamber, and wherein the measurement chamber is  
15 disposed within the process tool.

1201. The method of claim 1160, wherein the stage and the measurement device are  
disposed within a measurement chamber, and wherein the measurement chamber is  
arranged laterally proximate to a process chamber of the process tool.

20

1202. The method of claim 1160, wherein the stage and the measurement device are  
disposed within a measurement chamber, and wherein the measurement chamber is  
arranged vertically proximate to a process chamber of the process tool.

25 1203. The method of claim 1160, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

1204. The method of claim 1203, further comprising performing said directing and said detecting during the process step.

5 1205. The method of claim 1204, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

1206. The method of claim 1204, further comprising altering a parameter of one or more  
10 instrument coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

1207. The method of claim 1160, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process  
15 chamber and the second process chamber are disposed within a process tool.

1208. The method of claim 1207, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

20

1209. The method of claim 1160, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

25 1210. The method of claim 1160, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

1211. The method of claim 1210, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5 1212. The method of claim 1160, further comprising altering a sampling frequency of the measurement device in response to the determined first or second properties of the specimen.

1213. The method of claim 1160, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

1214. The method of claim 1160, further comprising altering a parameter of one or more  
15 instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

1215. The method of claim 1160, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

20 1216. The method of claim 1215, further comprising calibrating the measurement device using the database.

1217. The method of claim 1215, further comprising monitoring output signals of the  
25 measurement device using the database.

1218. The method of claim 1215, wherein the database further comprises first and second properties of a plurality of specimens.



1219. The method of claim 1218, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

5 1220. The method of claim 1219, further comprising calibrating the plurality of measurement devices using the database.

1221. The method of claim 1219, further comprising monitoring output signals of the plurality of measurement devices using the database.

10 1222. The method of claim 1160, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

15 1223. The method of claim 1160, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

20

1224. The method of claim 1160, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one  
25 of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1225. The method of claim 1160, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen using a feedback control technique.
- 5 1226. The method of claim 1160, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen using a feedforward control technique.
1227. The method of claim 1160, further comprising monitoring a parameter of one or  
10 more instruments coupled to a process tool.
1228. The method of claim 1227, further comprising determining a relationship between the determined properties and the monitored parameters.
- 15 1229. The method of claim 1228, further comprising altering a parameter of at least one of the instruments in response to the relationship.
1230. The method of claim 1160, further comprising altering a parameter of one or more instrument coupled to a plurality of process tools in response to the determined first or  
20 second property of the specimen.
1231. The method of claim 1160, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

1232. The method of claim 1231, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

10 1233. The method of claim 1231, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

1234. A computer-implemented method for controlling a system configured to  
15 determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:

controlling the measurement device, wherein the measurement device comprises  
an illumination system and a detection system, and wherein the measurement  
20 device is coupled to a stage, comprising:

controlling the illumination system to direct energy toward a surface of the  
specimen;

25 controlling the detection system to detect energy propagating from the  
surface of the specimen; and

generating one or more output signals responsive to the detected energy;  
and

5        processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises a critical  
dimension of the specimen, and wherein the second property comprises a thin film  
characteristic of the specimen.

1235. The method of claim 1234, further comprising controlling the stage, wherein the  
10       stage is configured to support the specimen.

1236. The method of claim 1234, further comprising controlling the stage to move  
laterally during said directing energy and said detecting energy.

15       1237. The method of claim 1234, further comprising controlling the stage to move  
rotatably during said directing energy and said detecting energy.

1238. The method of claim 1234, further comprising controlling the stage to move  
laterally and rotatably during said directing energy and said detecting energy.  
20

1239. The method of claim 1234, wherein the illumination system comprises a single  
energy source.

1240. The method of claim 1234, wherein the illumination system comprises more than  
25       one energy source.

1241. The method of claim 1234, wherein the detection system comprises a single  
energy sensitive device.

1242. The method of claim 1234, wherein the detection system comprises more than one energy sensitive devices.

5 1243. The method of claim 1234, wherein the measurement device further comprises a non-imaging scatterometer.

1244. The method of claim 1234, wherein the measurement device further comprises a scatterometer.

10

1245. The method of claim 1234, wherein the measurement device further comprises a spectroscopic scatterometer.

1246. The method of claim 1234, wherein the measurement device further comprises a  
15 reflectometer.

1247. The method of claim 1234, wherein the measurement device further comprises a spectroscopic reflectometer.

20 1248. The method of claim 1234, wherein the measurement device further comprises a coherence probe microscope.

1249. The method of claim 1234, wherein the measurement device further comprises a bright field imaging device.

25

1250. The method of claim 1234, wherein the measurement device further comprises a dark field imaging device.

1251. The method of claim 1234, wherein the measurement device further comprises a bright field and dark field imaging device.

5 1252. The method of claim 1234, wherein the measurement device further comprises an ellipsometer.

1253. The method of claim 1234, wherein the measurement device further comprises a spectroscopic ellipsometer.

10 1254. The method of claim 1234, wherein the measurement device further comprises a dual beam spectrophotometer.

1255. The method of claim 1234, wherein the measurement device further comprises a beam profile ellipsometer.

15 1256. The method of claim 1234, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

20 1257. The method of claim 1234, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

1258. The method of claim 1234, wherein the measurement device further comprises non-optical components, and wherein controlling the detection system to detect energy comprises controlling the non-optical components to measure a non-optical characteristic  
5 of the surface of the specimen.

1259. The method of claim 1234, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

10 1260. The method of claim 1234, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is coupled to an atomic layer deposition tool.

1261. The method of claim 1234, further comprising processing the one or more output  
15 signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1262. The method of claim 1261, wherein the stage and the measurement device are  
20 coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

1263. The method of claim 1234, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially  
25 simultaneously determining the first and second properties of the specimen.

1264. The method of claim 1234, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially

simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

5

1265. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool.

1266. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

1267. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

1268. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

20

1269. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is coupled to the process tool.

25

1270. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.



1271. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties  
5 of the specimen can be determined while the specimen is waiting between process steps.

1272. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the  
10 support device is substantially parallel to an upper surface of the stage.

1273. The method of claim 1234, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage  
15 is angled with respect to an upper surface of the support device.

1274. The method of claim 1234, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.  
20

1275. The method of claim 1234, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within the process tool.

25 1276. The method of claim 1234, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of the process tool.

1277. The method of claim 1234, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of the process tool.

5 1278. The method of claim 1234, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

1279. The method of claim 1278, further comprising controlling the illumination system  
10 and controlling the detection system during the process step.

1280. The method of claim 1279, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

15

1281. The method of claim 1279, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique.

20 1282. The method of claim 1234, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

1283. The method of claim 1282, further comprising controlling the illumination system  
25 and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.

1284. The method of claim 1234, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

- 5 1285. The method of claim 1234, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

1286. The method of claim 1285, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined  
10 range for the property.

1287. The method of claim 1234, further comprising altering a sampling frequency of the measurement device in response to the determined first or second property of the specimen.

15

1288. The method of claim 1234, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique.

- 20 1289. The method of claim 1234, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique.

1290. The method of claim 1234, further comprising generating a database, wherein the  
25 database comprises the determined first and second properties of the specimen.

1291. The method of claim 1290, further comprising calibrating the measurement device using the database.

1292. The method of claim 1290, further comprising monitoring output signals of the measurement device using the database.

5 1293. The method of claim 1290, wherein the database further comprises first and second properties of a plurality of specimens.

1294. The method of claim 1293, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

10

1295. The method of claim 1294, further comprising calibrating the plurality of measurement devices using the database.

15

1296. The method of claim 1294, further comprising monitoring output signals of the plurality of measurement devices using the database.

20

1297. The method of claim 1234, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

25

1298. The method of claim 1234, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

1299. The method of claim 1234, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least  
5 one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1300. The method of claim 1234, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second  
10 property of the specimen using a feedback control technique.

1301. The method of claim 1234, further comprising altering a parameter of one or more instruments coupled to a process tool in response to the determined first or second property of the specimen using a feedforward control technique.  
15

1302. The method of claim 1234, further comprising monitoring a parameter of one or more instruments coupled to the process tool.

1303. The method of claim 1302, further comprising determining a relationship between  
20 the determined properties and the monitored parameters.

1304. The method of claim 1303, further comprising altering a parameter of at least one of the instruments in response to the relationship.

25 1305. The method of claim 1234, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to the determined first or second property of the specimen.

1306. The method of claim 1234, wherein processing the one or more output signals comprises:

5           at least partially processing the one or more output signals using a local processor,  
          wherein the local processor is coupled to the measurement device;

          sending the partially processed one or more output signals from the local  
          processor to a remote controller computer; and

10          further processing the partially processed one or more output signals using the  
          remote controller computer.

1307. The method of claim 1306, wherein at least partially processing the one or more  
output signals comprises determining the first and second properties of the specimen.

15

1308. The method of claim 1306, wherein further processing the partially processed one  
or more output signals comprises determining the first and second properties of the  
specimen.

20   1309. A semiconductor device fabricated by a method, the method comprising:

          forming a portion of the semiconductor device upon a specimen;

25          disposing the specimen upon a stage, wherein the stage is coupled to a  
          measurement device, and wherein the measurement device comprises an  
          illumination system and a detection system;

          directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

5       generating one or more output signals in response to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a thin film  
10       characteristic of the specimen.

1310. The device of claim 1309, wherein the illumination system comprises a single energy source.

15       1311. The device of claim 1309, wherein the illumination system comprises more than one energy source.

1312. The device of claim 1309, wherein the detection system comprises a single energy  
20       sensitive device.

1313. The device of claim 1309, wherein the detection system comprises more than one energy sensitive devices.

1314. The device of claim 1309, wherein the measurement device is selected from the  
25       group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam

spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

1315. The device of claim 1309, wherein the measurement device comprises at least a  
5 first measurement device and a second measurement device, and wherein the first and  
second measurement devices are selected from the group consisting of a non-imaging  
scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a  
spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device,  
a dark field imaging device, a bright field and dark field imaging device, an ellipsometer,  
10 a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile  
ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

1316. The device of claim 1309, wherein the measurement device comprises at least a  
first measurement device and a second measurement device, and wherein optical  
15 elements of the first measurement device comprise optical elements of the second  
measurement device.

1317. The device of claim 1309, wherein the measurement device further comprises  
non-optical components, and wherein detecting energy comprises measuring a non-  
20 optical characteristic of the surface of the specimen.

1318. The device of claim 1309, wherein the measurement device further comprises at  
least an eddy current device and a spectroscopic ellipsometer.

25 1319. The device of claim 1309, wherein the measurement device further comprises at  
least an eddy current device and a spectroscopic ellipsometer, and wherein the  
measurement device is further coupled to an atomic layer deposition tool.



1320. The device of claim 1309, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

5

1321. The device of claim 1320, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

10 1322. The device of claim 1309, wherein the stage and the measurement device are coupled to a process tool.

1323. The device of claim 1309, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group  
15 consisting of a lithography tool, an etch tool, and a deposition tool.

1324. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;

20

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

25

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals in response to the detected energy; and

5        processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises a critical  
dimension of the specimen, and wherein the second property comprises a thin film  
characteristic of the specimen.

10        1325. The method of claim 1324, wherein the illumination system comprises a single  
energy source.

1326. The method of claim 1324, wherein the illumination system comprises more than  
one energy source.

15        1327. The method of claim 1324, wherein the detection system comprises a single  
energy sensitive device.

1328. The method of claim 1324, wherein the detection system comprises more than one  
energy sensitive devices.  
20

1329. The method of claim 1324, wherein the measurement device is selected from the  
group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic  
scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
microscope, a bright field imaging device, a dark field imaging device, a bright field and  
25        dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam  
spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-  
ray reflectometer.

1330. The method of claim 1324, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.
1331. The method of claim 1324, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
1332. The method of claim 1324, wherein the measurement device further comprises non-optical components, and wherein measuring a non-optical characteristic of the surface of the specimen.
1333. The method of claim 1324, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.
1334. The method of claim 1324, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.
1335. The method of claim 1324, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is

selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

5 1336. The method of claim 1335, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

10 1337. The method of claim 1324, wherein the stage and the measurement device are coupled to a process tool.

1338. The method of claim 1324, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

15 1339. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

20 a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

25 a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy;

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

- 5 a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, and  
10 wherein the second property comprises a thin film characteristic of the specimen.

1340. The system of claim 1339, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
15 microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

- 20 1341. The system of claim 1339, wherein the measurement device comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device,  
25 a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

1342. The system of claim 1339, wherein the measurement device comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

5

1343. The system of claim 1339, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

10 1344. The system of claim 1339, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1345. The system of claim 1339, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is  
15 coupled to an atomic layer deposition tool.

1346. The system of claim 1339, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially processed one or more output signals during use, and wherein the third property is  
20 selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1347. The system of claim 1339, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a  
25 cleaning tool, and an etch tool.

1348. The system of claim 1339, wherein the remote controller computer is coupled to a process tool.

1349. The system of claim 1339, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from a group consisting of a lithography tool, an etch tool, and a deposition tool.

5

1350. The system of claim 1339, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedback control technique during use.

10

1351. The system of claim 1339, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined first or second property using a feedforward control technique during use.

15

1352. The system of claim 1339, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

20

1353. The system of claim 1352, wherein the remote controller computer is further configured to determine a relationship between the determined properties and the monitored parameters during use.

25

1354. The system of claim 1353, wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

1355. The system of claim 1339, wherein the system is coupled to a process tool,  
wherein the illumination system is further configured to direct energy toward the surface  
of the specimen during a process step, wherein the detection system is further configured  
to detect energy propagating from the surface of the specimen during the process step,  
5 and wherein the remote controller computer is further configured to determine the first  
and second properties of the specimen during the process step.

1356. The system of claim 1355, wherein the remote controller computer is further  
configured to obtain a signature characterizing the process step during use, and wherein  
10 the signature comprises at least one singularity representative of an end of the process  
step.

1357. The system of claim 1355, wherein the remote controller computer is further  
configured to alter a parameter of one or more instruments coupled to the process tool in  
15 response to the determined first or second property using an in situ control technique  
during use.

1358. The system of claim 1339, wherein a process tool comprises a first process  
chamber and a second process chamber, and wherein the stage is further configured to  
20 move the specimen from the first process chamber to the second process chamber during  
use.

1359. The system of claim 1358, wherein the illumination system is further configured  
to direct energy toward the surface of the specimen during said moving, wherein the  
25 detection system is further configured to detect energy propagating from the surface of  
the specimen during said moving, and wherein the remote controller computer is further  
configured to determine the first and second properties of the specimen during said  
moving.



1360. The system of claim 1339, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

5

1361. The system of claim 1339, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

10 1362. The system of claim 1361, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

15 1363. The system of claim 1339, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to the determined first or second property of the specimen during use.

20 1364. The system of claim 1339, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedback control technique during use.

25 1365. The system of claim 1339, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to the determined first or second property using a feedforward control technique during use.

1366. The system of claim 1339, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

- 5 1367. The system of claim 1366, wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

1368. The system of claim 1366, wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database  
10 during use.

1369. The system of claim 1366, wherein the database further comprises first and second properties of a plurality of specimens.

- 15 1370. The system of claim 1369, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.

1371. The system of claim 1370, wherein the remote controller computer is further coupled to the plurality of measurement devices.  
20

1372. The system of claim 1371, wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

- 25 1373. The system of claim 1371, wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

1374. The system of claim 1339, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

5 1375. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

10

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

15

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a critical dimension of the specimen, and wherein the second property comprises a thin film characteristic of the specimen, comprising:

20

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

25

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

5 1376. The method of claim 1375, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam  
10 spectrophotometer, a beam profile ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

1377. The method of claim 1375, wherein the measurement device comprises at least a first measurement device and a second measurement device, and wherein the first and  
15 second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile  
20 ellipsometer, a photo-acoustic device, and a grazing X-ray reflectometer.

1378. The method of claim 1375, wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

25 1379. The method of claim 1375, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

1380. The method of claim 1375, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1381. The method of claim 1375, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

1382. The method of claim 1375, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1383. The method of claim 1382, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

1384. The method of claim 1375, wherein the remote controller computer is coupled to a process tool.

1385. The method of claim 1375, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

1386. The method of claim 1375, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property of the specimen using a feedback control technique.

1387. The method of claim 1375, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property of the specimen using a feedforward control technique.

1388. The method of claim 1375, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

1389. The method of claim 1388, further comprising determining a relationship between the determined properties and at least one of the monitored parameters using the remote controller computer.

1390. The method of claim 1375, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

1391. The method of claim 1375, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, further comprising performing said directing and said detecting during a process step.

1392. The method of claim 1391, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

1393. The method of claim 1391, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to the determined first or second property using an in situ control technique.

5 1394. The method of claim 1375, further comprising:

moving the specimen from a first process chamber to a second process chamber using the stage;

10 performing said directing and said detecting during said moving the specimen.

1395. The method of claim 1375, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

15

1396. The method of claim 1375, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

20 1397. The method of claim 1396, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

25 1398. The method of claim 1375, wherein the remote controller computer is coupled to the measurement device.

1399. The method of claim 1398, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to the determined first or second property of the specimen.
- 5 1400. The method of claim 1398, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedback control technique.
- 10 1401. The method of claim 1398, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to the determined first or second property using a feedforward control technique.
- 15 1402. The method of claim 1375, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen.
1403. The method of claim 1402, further comprising calibrating the measurement device using the database and the remote controller computer.
- 20 1404. The method of claim 1402, further comprising monitoring output signals generating by the measurement device using the database and the remote controller computer.
- 25 1405. The method of claim 1402, wherein the database further comprises first and second properties of a plurality of specimens.
1406. The method of claim 1405, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.



1407. The method of claim 1406, further comprising calibrating the plurality of measurement devices using the database and the remote controller computer.

5 1408. The method of claim 1406, further comprising monitoring output signals generated by the plurality of measurement devices using the database and the remote controller computer.

1409. The method of claim 1375, further comprising sending the at least partially  
10 processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

1410. The method of claim 1409, further comprising altering a parameter of one or more  
15 instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to the determined first or second property of the specimen.

1411. The method of claim 1410, wherein each of the plurality of measurement devices  
20 is coupled to one of a plurality of process tools.

1412. The method of claim 1411, further comprising altering a parameter of one or more  
instruments coupled to at least one of the plurality of process tools using the remote  
controller computer in response to the determined first or second property of the  
25 specimen.

1413. A system configured to determine at least three properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

5

an illumination system configured to direct energy toward a surface of the specimen during use; and

10

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals in response to the detected energy during use; and

15

a processor coupled to the measurement device and configured to determine a first property, a second property, and a third property of the specimen from the one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

20

1414. The system of claim 1413, wherein the stage is further configured to move laterally during use.

25

1415. The system of claim 1413, wherein the stage is further configured to move rotatably during use.

1416. The system of claim 1413, wherein the stage is further configured to move laterally and rotatably during use.

1417. The system of claim 1413, wherein the illumination system comprises a single energy source.

5 1418. The system of claim 1413, wherein the illumination system comprises more than one energy source.

1419. The system of claim 1413, wherein the detection system comprises a single energy sensitive device.

10

1420. The system of claim 1413, wherein the detection system comprises more than one energy sensitive devices.

1421. The system of claim 1413, wherein the measurement device further comprises a  
15 non-imaging scatterometer.

1422. The system of claim 1413, wherein the measurement device further comprises a scatterometer.

20 1423. The system of claim 1413, wherein the measurement device further comprises a spectroscopic scatterometer.

1424. The system of claim 1413, wherein the measurement device further comprises a reflectometer.

25

1425. The system of claim 1413, wherein the measurement device further comprises a spectroscopic reflectometer.

1426. The system of claim 1413, wherein the measurement device further comprises a coherence probe microscope.

5 1427. The system of claim 1413, wherein the measurement device further comprises a bright field imaging device.

1428. The system of claim 1413, wherein the measurement device further comprises a dark field imaging device.

10 1429. The system of claim 1413, wherein the measurement device further comprises a bright field and dark field imaging device.

1430. The system of claim 1413, wherein the measurement device further comprises a non-imaging bright field device.

15

1431. The system of claim 1413, wherein the measurement device further comprises a non-imaging dark field device.

20 1432. The system of claim 1413, wherein the measurement device further comprises a non-imaging bright field and dark field device.

1433. The system of claim 1413, wherein the measurement device further comprises an ellipsometer.

25 1434. The system of claim 1413, wherein the measurement device further comprises a spectroscopic ellipsometer.

1435. The system of claim 1413, wherein the measurement device further comprises a dual beam spectrophotometer.

1436. The system of claim 1413, wherein the measurement device further comprises a  
5 beam profile ellipsometer.

1437. The system of claim 1413, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging  
10 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam  
15 spectrophotometer, and a beam profile ellipsometer.

1438. The system of claim 1413, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second  
20 measurement device.

1439. The system of claim 1413, wherein the defects comprise micro defects and macro defects.

25 1440. The system of claim 1413, wherein the defects comprises micro defects or macro defects.

1441. The system of claim 1413, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

1442. The system of claim 1413, wherein the defects comprise macro defects on a back  
5 side of the specimen, and wherein the macro defects comprise copper contamination.

1443. The system of claim 1413, wherein the processor is further configured to determine a fourth property of the specimen from the one or more output signals during use, and wherein the fourth property is selected from the group consisting of a roughness  
10 of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1444. The system of claim 1443, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a  
15 cleaning tool, and an etch tool.

1445. The system of claim 1413, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom  
20 surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

1446. The system of claim 1445, wherein the defects comprise macro defects.

25 1447. The system of claim 1413, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

1448. The system of claim 1413, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1449. The system of claim 1413, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is coupled to an atomic layer deposition tool.

1450. The system of claim 1413, wherein the system is further configured to determine at least three properties of the specimen substantially simultaneously during use.

1451. The system of claim 1413, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be determined substantially simultaneously.

1452. The system of claim 1413, wherein the system is coupled to a process tool.

1453. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

1454. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

1455. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

1456. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.

5

1457. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.

10 1458. The system of claim 1413, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

1459. The system of claim 1413, wherein the system is coupled to a process tool, and  
15 wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

1460. The system of claim 1413, wherein the system is coupled to a process tool,  
20 wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

1461. The system of claim 1413, wherein the system is coupled to a process tool, and  
25 wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.



1462. The system of claim 1413, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

5

1463. The system of claim 1413, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

10

1464. The system of claim 1413, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

15

1465. The system of claim 1413, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

20

1466. The system of claim 1413, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

25

1467. The system of claim 1466, wherein the processor is further configured to determine at least the three properties of the specimen during the process step.

1468. The system of claim 1467, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.
- 5 1469. The system of claim 1467, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to the determined properties using an in situ control technique during use.
- 10 1470. The system of claim 1413, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.
- 15 1471. The system of claim 1470, wherein the system is further configured to determine at least the three properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.
- 20 1472. The system of claim 1413, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.
- 25 1473. The system of claim 1413, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

1474. The system of claim 1473, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

- 5 1475. The system of claim 1413, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

1476. The system of claim 1413, wherein the processor is further configured to alter a  
10 parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

1477. The system of claim 1413, wherein the processor is further configured to alter a  
15 parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

1478. The system of claim 1413, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first, second, and  
20 third properties of the specimen.

1479. The system of claim 1478, wherein the processor is further configured to calibrate the measurement device using the database during use.

- 25 1480. The system of claim 1478, wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

1481. The system of claim 1478, wherein the database further comprises first, second, and third properties of a plurality of specimens.
1482. The system of claim 1481, wherein the first, second, and third properties of the plurality of specimens are determined using the measurement device.
1483. The system of claim 1481, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices.
1484. The system of claim 1483, wherein the processor is further coupled to the plurality of measurement devices.
1485. The system of claim 1484, wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.
1486. The system of claim 1485, wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.
1487. The system of claim 1413, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.
1488. The system of claim 1413, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is

further configured to calibrate the system and at least the one additional system during use.

1489. The system of claim 1413, wherein the system is further configured to determine  
5 at least the two properties of the specimen at more than one position on the specimen,  
wherein the specimen comprises a wafer, and wherein the processor is configured to alter  
at least one parameter of one or more instruments coupled to a process tool in response to  
at least one of the determined properties of the specimen at the more than one position on  
the specimen to reduce within wafer variation of at least one of the determined properties.

10

1490. The system of claim 1413, wherein the processor is further coupled to a process  
tool.

1491. The system of claim 1490, wherein the processor is further configured to alter a  
15 parameter of one or more instruments coupled to the process tool in response to at least  
one of the determined properties using a feedback control technique during use.

1492. The system of claim 1490, wherein the processor is further configured to alter a  
parameter of one or more instruments coupled to the process tool in response to at least  
20 one of the determined properties using a feedforward control technique during use.

1493. The system of claim 1490, wherein the processor is further configured to monitor  
a parameter of one or more instruments coupled to the process tool during use.

25 1494. The system of claim 1493, wherein the processor is further configured to  
determine a relationship between at least one of the determined properties and at least one  
of the monitored parameters during use.

1495. The system of claim 1494, wherein the processor is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

1496. The system of claim 1413, wherein the processor is further coupled to a plurality  
5 of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

1497. The system of claim 1413, wherein the processor comprises a local processor  
coupled to the measurement device and a remote controller computer coupled to the local  
10 processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

1498. The system of claim 1497, wherein the local processor is further configured to  
15 determine the first, second, and third properties of the specimen during use.

1499. The system of claim 1497, wherein the remote controller computer is further configured to determine the first, second, and properties of the specimen during use.

20 1500. A method for determining at least three properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a  
measurement device, and wherein the measurement device comprises an  
illumination system and a detection system;

25

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a critical dimension of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property

10 comprises a thin film characteristic of the specimen.

1501. The method of claim 1500, further comprising laterally moving the stage during said directing energy and said detecting energy.

15 1502. The method of claim 1500, further comprising rotatably moving the stage during said directing energy and said detecting energy.

1503. The method of claim 1500, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

20

1504. The method of claim 1500, wherein the illumination system comprises a single energy source.

1505. The method of claim 1500, wherein the illumination system comprises more than

25 one energy source.

1506. The method of claim 1500, wherein the detection system comprises a single energy sensitive device.

1507. The method of claim 1500, wherein the detection system comprises more than one energy sensitive devices.

5 1508. The method of claim 1500, wherein the measurement device further comprises a non-imaging scatterometer.

1509. The method of claim 1500, wherein the measurement device further comprises a scatterometer.

10

1510. The method of claim 1500, wherein the measurement device further comprises a spectroscopic scatterometer.

1511. The method of claim 1500, wherein the measurement device further comprises a reflectometer.

15

1512. The method of claim 1500, wherein the measurement device further comprises a spectroscopic reflectometer.

20 1513. The method of claim 1500, wherein the measurement device further comprises a coherence probe microscope.

1514. The method of claim 1500, wherein the measurement device further comprises a bright field imaging device.

25

1515. The method of claim 1500, wherein the measurement device further comprises a dark field imaging device.



1516. The method of claim 1500, wherein the measurement device further comprises a bright field and dark field imaging device.
1517. The method of claim 1500, wherein the measurement device further comprises a  
5 non-imaging bright field device.
1518. The method of claim 1500, wherein the measurement device further comprises a non-imaging dark field device.
- 10 1519. The method of claim 1500, wherein the measurement device further comprises a non-imaging bright field and dark field device.
1520. The method of claim 1500, wherein the measurement device further comprises an ellipsometer.  
15
1521. The method of claim 1500, wherein the measurement device further comprises a spectroscopic ellipsometer.
1522. The method of claim 1500, wherein the measurement device further comprises a  
20 dual beam spectrophotometer.
1523. The method of claim 1500, wherein the measurement device further comprises a beam profile ellipsometer.
- 25 1524. The method of claim 1500, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a

spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

1525. The method of claim 1500, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

1526. The method of claim 1500, wherein the defects comprise micro defects and macro defects.

1527. The method of claim 1500, wherein the defects comprises micro defects or macro defects.

1528. The method of claim 1500, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

1529. The method of claim 1500, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

1530. The method of claim 1500, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1531. The method of claim 1530, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 1532. The method of claim 1500, further comprising:

directing energy toward a bottom surface of the specimen; and

10 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

1533. The method of claim 1532, wherein the defects comprise macro defects.

15 1534. The method of claim 1500, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

20 1535. The method of claim 1500, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1536. The method of claim 1500, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

25

1537. The method of claim 1500, wherein processing the detected energy to determine the first, second, and third properties of the specimen comprises substantially simultaneously determining the first, second, and third properties of the specimen.

1538. The method of claim 1500, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be determined substantially simultaneously.

1539. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool.

10

1540. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

1541. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

1542. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

1543. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

1544. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

- 5 1545. The method of claim 1500, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

1546. The method of claim 1500, wherein the stage and the measurement device are  
10 coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

1547. The method of claim 1500, wherein the stage and the measurement device are  
15 coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

1548. The method of claim 1500, wherein the stage and the measurement device are  
20 disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

1549. The method of claim 1500, wherein the stage and the measurement device are  
disposed within a measurement chamber, and wherein the measurement chamber is  
25 disposed within a process tool.

1550. The method of claim 1500, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.
- 5 1551. The method of claim 1500, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.
1552. The method of claim 1500, wherein disposing the specimen upon the stage  
10 comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.
1553. The method of claim 1552, further comprising performing said directing and said  
15 detecting during the process step.
1554. The method of claim 1553, further comprising obtaining a signature  
characterizing the process step, wherein the signature comprises at least one singularity  
representative of an end of the process step.  
20
1555. The method of claim 1553, further comprising altering a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.
- 25 1556. The method of claim 1500, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

1557. The method of claim 1556, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

- 5 1558. The method of claim 1500, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

1559. The method of claim 1500, further comprising comparing at least one of the  
10 determined properties of the specimen to a predetermined range for the property.

1560. The method of claim 1559, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

15

1561. The method of claim 1500, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

- 20 1562. The method of claim 1500, further comprising altering a parameter of an instrument coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

1563. The method of claim 1500, further comprising altering a parameter of an  
25 instrument coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

1564. The method of claim 1500, further comprising generating a database, wherein the database comprises the determined first, second, and third properties of the specimen.

5 1565. The method of claim 1564, further comprising calibrating the measurement device using the database.

1566. The method of claim 1564, further comprising monitoring output signals of the measurement device using the database.

10 1567. The method of claim 1564, wherein the database further comprises first, second, and third properties of a plurality of specimens.

1568. The method of claim 1567, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices.

15 1569. The method of claim 1568, further comprising calibrating the plurality of measurement devices using the database.

20 1570. The method of claim 1568, further comprising monitoring output signals of the plurality of measurement devices using the database.

25 1571. The method of claim 1500, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

1572. The method of claim 1500, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further



comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

- 5     1573. The method of claim 1500, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the  
10     specimen to reduce within wafer variation of at least one of the determined properties.

1574. The method of claim 1500, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.

15

1575. The method of claim 1500, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.

- 20     1576. The method of claim 1500, further comprising monitoring a parameter of one or more instruments coupled to the process tool.

1577. The method of claim 1576, further comprising determining a relationship between the determined properties and at least one of the monitored parameters.

25

1578. The method of claim 1577, further comprising altering a parameter of at least one of the instruments in response to the relationship.

1579. The method of claim 1500, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to the at least one of the determined properties of the specimen.

5 1580. The method of claim 1500, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

15

further processing the partially processed one or more output signals using the remote controller computer.

1581. The method of claim 1580, wherein at least partially processing the one or more output signals comprises determining the first, second, and third properties of the specimen.

20

1582. The method of claim 1580, wherein further processing the partially processed one or more output signals comprises determining the first, second, and third properties of the specimen.

25 1583. A computer-implemented method for controlling a system configured to determine at least three properties of a specimen during use, wherein the system comprises a measurement device, comprising:

controlling the measurement device, wherein the measurement device comprises an illumination system and a detection system, and wherein the measurement device is coupled to a stage, comprising:

5                   controlling the illumination system to direct energy toward a surface of the specimen;

                  controlling the detection system to detect energy propagating from the surface of the specimen; and

10

                  generating one or more output signals in response to the detected energy; and

                  processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a critical dimension of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

15

20   1584. The method of claim 1583, further comprising controlling the stage, wherein the stage is configured to support the specimen.

1585. The method of claim 1583, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.

25

1586. The method of claim 1583, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.

1587. The method of claim 1583, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.

5 1588. The method of claim 1583, wherein the illumination system comprises a single energy source.

1589. The method of claim 1583, wherein the illumination system comprises more than one energy source.

10 1590. The method of claim 1583, wherein the detection system comprises a single energy sensitive device.

1591. The method of claim 1583, wherein the detection system comprises more than one energy sensitive devices.

15

1592. The method of claim 1583, wherein the measurement device further comprises a non-imaging scatterometer.

20 1593. The method of claim 1583, wherein the measurement device further comprises a scatterometer.

1594. The method of claim 1583, wherein the measurement device further comprises a spectroscopic scatterometer.

25 1595. The method of claim 1583, wherein the measurement device further comprises a reflectometer.

1596. The method of claim 1583, wherein the measurement device further comprises a spectroscopic reflectometer.

5 1597. The method of claim 1583, wherein the measurement device further comprises a coherence probe microscope.

1598. The method of claim 1583, wherein the measurement device further comprises a bright field imaging device.

10 1599. The method of claim 1583, wherein the measurement device further comprises a dark field imaging device.

1600. The method of claim 1583, wherein the measurement device further comprises a bright field and dark field imaging device.

15

1601. The method of claim 1583, wherein the measurement device further comprises a non-imaging bright field device.

20 1602. The method of claim 1583, wherein the measurement device further comprises a non-imaging dark field device.

1603. The method of claim 1583, wherein the measurement device further comprises a non-imaging bright field and dark field device.

25 1604. The method of claim 1583, wherein the measurement device further comprises an ellipsometer.

1605. The method of claim 1583, wherein the measurement device further comprises a spectroscopic ellipsometer.

5 1606. The method of claim 1583, wherein the measurement device further comprises a dual beam spectrophotometer.

1607. The method of claim 1583, wherein the measurement device further comprises a beam profile ellipsometer.

10 1608. The method of claim 1583, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device,  
15 a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

20 1609. The method of claim 1583, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

25 1610. The method of claim 1583, wherein the defects comprise micro defects and macro defects.

1611. The method of claim 1583, wherein the defects comprises micro defects or macro defects.
1612. The method of claim 1583, wherein the thin film characteristic comprises a  
5 thickness of a copper film, and wherein the defects comprise voids in the copper film.
1613. The method of claim 1583, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.
- 10 1614. The method of claim 1583, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.
- 15 1615. The method of claim 1614, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.
1616. The method of claim 1583, further comprising:  
20  
controlling the illumination system to direct energy toward a bottom surface of the specimen; and  
controlling the detection system to detect energy propagating from the bottom  
25 surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.
1617. The method of claim 1616, wherein the defects comprise macro defects.

1618. The method of claim 1583, wherein the measurement device further comprises non-optical components, and wherein controlling the detection system comprises controlling the detection system to measure a non-optical characteristic of the surface of the specimen.

1619. The method of claim 1583, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1620. The method of claim 1583, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is coupled to an atomic layer deposition tool.

1621. The method of claim 1583, wherein processing the one or more output signals to determine the first, second, and third properties of the specimen comprises substantially simultaneously determining the first, second, and third properties of the specimen.

1622. The method of claim 1583, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be determined substantially simultaneously.

1623. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool.



1624. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

5 1625. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

1626. The method of claim 1583, wherein the stage and the measurement device are  
10 coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

1627. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to  
15 move the specimen from the process tool to the stage, and wherein the wafer handler is coupled to the process tool.

1628. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the  
20 specimen from the system to the process tool.

1629. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties  
25 of the specimen can be determined while the specimen is waiting between process steps.

1630. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured

to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

5 1631. The method of claim 1583, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

10 1632. The method of claim 1583, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

15 1633. The method of claim 1583, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

20 1634. The method of claim 1583, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

1635. The method of claim 1583, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

25 1636. The method of claim 1583, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

1637. The method of claim 1636, further comprising controlling the illumination system and controlling the detection system during the process step.
- 5 1638. The method of claim 1637, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.
- 10 1639. The method of claim 1637, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.
- 15 1640. The method of claim 1583, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.
1641. The method of claim 1640, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.
- 20 1642. The method of claim 1583, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.
- 25 1643. The method of claim 1583, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

1644. The method of claim 1643, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5 1645. The method of claim 1583, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

1646. The method of claim 1583, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

1647. The method of claim 1583, further comprising altering a parameter of one or more  
15 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

1648. The method of claim 1583, further comprising generating a database, wherein the database comprises the determined first, second, and third properties of the specimen.

20 1649. The method of claim 1648, further comprising calibrating the measurement device using the database.

1650. The method of claim 1648, further comprising monitoring output signals of the measurement device using the database.

25

1651. The method of claim 1648, wherein the database further comprises first, second, and third properties of a plurality of specimens.

1652. The method of claim 1648, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices.

1653. The method of claim 1652, further comprising calibrating the plurality of  
5 measurement devices using the database.

1654. The method of claim 1652, further comprising monitoring output signals of the plurality of measurement devices using the database.

10 1655. The method of claim 1583, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

15 1656. The method of claim 1583, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

20

1657. The method of claim 1583, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least  
25 one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1658. The method of claim 1583, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.
- 5 1659. The method of claim 1583, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.
1660. The method of claim 1583, further comprising monitoring a parameter of one or  
10 more instruments coupled to the process tool.
1661. The method of claim 1660, further comprising determining a relationship between the determined properties and at least one of the monitored parameters.
- 15 1662. The method of claim 1661, further comprising altering a parameter of at least one of the instruments in response to the relationship.
1663. The method of claim 1583, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the  
20 determined properties of the specimen.
1664. The method of claim 1583, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

1665. The method of claim 1664, wherein at least partially processing the one or more output signals comprises determining the first, second, and third properties of the specimen.

10

1666. The method of claim 1664, wherein further processing the partially processed one or more output signals comprises determining the first, second, and third properties of the specimen.

15 1667. A semiconductor device fabricated by a method, the method comprising:

forming a portion of the semiconductor device upon a specimen;

20 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

25 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a critical dimension of the specimen, wherein the second property  
5 comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

1668. The device of claim 1667, wherein the illumination system comprises a single energy source.

10

1669. The device of claim 1667, wherein the illumination system comprises more than one energy source.

1670. The device of claim 1667, wherein the detection system comprises a single energy  
15 sensitive device.

1671. The device of claim 1667, wherein the detection system comprises more than one energy sensitive devices.

20 1672. The device of claim 1667, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field  
25 device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.



1673. The device of claim 1667, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.
1674. The device of claim 1667, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
1675. The device of claim 1667, wherein the defects comprise micro defects and macro defects.
1676. The device of claim 1667, wherein the defects comprises micro defects or macro defects.
1677. The device of claim 1667, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.
1678. The device of claim 1667, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

1679. The device of claim 1667, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

5

1680. The device of claim 1679, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

10 1681. The device of claim 1667, further comprising:

directing energy toward a bottom surface of the specimen; and

15 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

1682. The device of claim 1681, wherein the defects comprise macro defects.

20 1683. The device of claim 1667, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

25 1684. The device of claim 1667, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1685. The device of claim 1667, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

5 1686. The device of claim 1667, wherein the stage and the measurement device are coupled to a process tool.

1687. The device of claim 1667, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group  
10 consisting of a lithography tool, an etch tool, and a deposition tool.

1688. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;  
15

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

20 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

25 generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property

comprises a critical dimension of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the portion of the specimen.

5    1689. The method of claim 1688, wherein the illumination system comprises a single energy source.

1690. The method of claim 1688, wherein the illumination system comprises more than one energy source.

10

1691. The method of claim 1688, wherein the detection system comprises a single energy sensitive device.

15    1692. The method of claim 1688, wherein the detection system comprises more than one energy sensitive devices.

1693. The method of claim 1688, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
20    microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

25    1694. The method of claim 1688, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a

spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

1695. The method of claim 1688, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

1696. The method of claim 1688, wherein the defects comprise micro defects and macro defects.

1697. The method of claim 1688, wherein the defects comprises micro defects or macro defects.

1698. The method of claim 1688, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

1699. The method of claim 1688, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

1700. The method of claim 1688, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1701. The method of claim 1700, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 1702. The method of claim 1688, further comprising:

directing energy toward a bottom surface of the specimen; and

10 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

1703. The method of claim 1702, wherein the defects comprise macro defects.

15 1704. The method of claim 1688, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

20 1705. The method of claim 1688, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1706. The method of claim 1688, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

25

1707. The method of claim 1688, wherein the stage and the measurement device are coupled to a process tool.

1708. The method of claim 1688, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

- 5 1709. A system configured to determine at least three properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

- 10 a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

- 15 a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use;

- 20 a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

- a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or  
25 more output signals and to determine a first property, a second property, and a third property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a critical dimension of the specimen, wherein the second property comprises a presence of

defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

1710. The system of claim 1709, wherein the measurement device is selected from the  
5 group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic  
scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
microscope, a bright field imaging device, a dark field imaging device, a bright field and  
dark field imaging device, a non-imaging bright field device, a non-imaging dark field  
device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic  
10 ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

1711. The system of claim 1709, wherein the measurement device further comprises at  
least a first measurement device and a second measurement device, and wherein the first  
and second measurement devices are selected from the group consisting of a non-imaging  
15 scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a  
spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device,  
a dark field imaging device, a bright field and dark field imaging device, a non-imaging  
bright field device, a non-imaging dark field device, a non-imaging bright field and dark  
field device, and ellipsometer, a spectroscopic ellipsometer, a dual beam  
20 spectrophotometer, and a beam profile ellipsometer.

1712. The system of claim 1709, wherein the measurement device further comprises at  
least a first measurement device and a second measurement device, and wherein optical  
elements of the first measurement device comprise optical elements of the second  
25 measurement device.

1713. The system of claim 1709, wherein the defects comprise micro defects and macro  
defects.



1714. The system of claim 1709, wherein the defects comprises micro defects or macro defects.

5 1715. The system of claim 1709, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

1716. The system of claim 1709, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

10

1717. The system of claim 1709, wherein the remote controller computer is further configured to determine a fourth property of the specimen from the at least partially processed one or more output signals during use, and wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

15

1718. The system of claim 1717, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

20

1719. The system of claim 1709, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

25

1720. The system of claim 1719, wherein the defects comprise macro defects.

1721. The system of claim 1709, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

5 1722. The system of claim 1709, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1723. The system of claim 1709, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the system is  
10 coupled to an atomic layer deposition tool.

1724. The system of claim 1709, wherein the remote controller computer is coupled to a process tool.

15 1725. The system of claim 1709, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from a group consisting of a lithography tool, an etch tool, and a deposition tool.

1726. The system of claim 1709, wherein the remote controller computer is coupled to a  
20 process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

1727. The system of claim 1709, wherein the remote controller computer is coupled to a  
25 process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

1728. The system of claim 1709, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

- 5 1729. The system of claim 1728, wherein the remote controller computer is further configured to determine a relationship between the determined properties and at least one of the monitored parameters during use.

1730. The system of claim 1729, wherein the remote controller computer is further  
10 configured to alter a parameter of at least one of the instruments in response to the relationship during use.

1731. The system of claim 1709, wherein the remote controller computer is coupled to a process tool, wherein the illumination system is further configured to direct energy  
15 toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first, second, and third properties of the specimen during the process step.

- 20 1732. The system of claim 1731, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

- 25 1733. The system of claim 1731, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

1734. The system of claim 1709, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during  
5 use.

1735. The system of claim 1734, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of  
10 the specimen during said moving, and wherein the remote controller computer is further configured to determine the first, second, and third properties of the specimen during said moving.

1736. The system of claim 1709, wherein the remote controller computer is further  
15 configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

1737. The system of claim 1709, wherein the remote controller computer is further  
20 configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

1738. The system of claim 1737, wherein the remote controller computer is further  
25 configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

1739. The system of claim 1709, wherein the remote controller computer is further  
configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

1740. The system of claim 1709, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control  
5 technique during use.

1741. The system of claim 1709, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control  
10 technique during use.

1742. The system of claim 1709, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first, second, and third properties of the specimen.  
15

1743. The system of claim 1742, wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

1744. The system of claim 1742, wherein the remote controller computer is further  
20 configured to monitor output signals generated by measurement device using the database during use.

1745. The system of claim 1742, wherein the database further comprises first, second, and third properties of a plurality of specimens.  
25

1746. The system of claim 1745, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices.

1747. The system of claim 1746, wherein the remote controller computer is further coupled to the plurality of measurement devices.

1748. The system of claim 1747, wherein the remote controller computer is further  
5 configured to calibrate the plurality of measurement devices using the database during use.

1749. The system of claim 1747, wherein the remote controller computer is further  
configured to monitor output signals generated by the plurality of measurement devices  
10 using the database during use.

1750. The system of claim 1709, wherein the remote controller computer is further  
coupled to a plurality of measurement devices, and wherein each of the plurality of  
measurement devices is coupled to one of a plurality of process tools.

15

1751. A method for determining at least three properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a  
measurement device, and wherein the measurement device comprises an  
20 illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection  
25 system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a critical dimension of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property  
5 comprises a thin film characteristic of the specimen, comprising:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;  
10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.  
15

1752. The method of claim 1751, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, a coherence probe  
20 microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer.

25 1753. The method of claim 1751, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a

spectroscopic reflectometer, a coherence probe microscope, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, an ellipsometer, a spectroscopic ellipsometer, a dual beam  
5 spectrophotometer, and a beam profile ellipsometer.

1754. The method of claim 1751, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second  
10 measurement device.

1755. The method of claim 1751, wherein the defects comprise micro defects and macro defects.

15 1756. The method of claim 1751, wherein the defects comprises micro defects or macro defects.

1757. The method of claim 1751, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.  
20

1758. The method of claim 1751, wherein the defects comprise macro defects on a back side of the specimen, and wherein the macro defects comprise copper contamination.

1759. The method of claim 1751, further comprising processing the one or more output  
25 signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.



1760. The method of claim 1759, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5 1761. The method of claim 1751, further comprising:

directing energy toward a bottom surface of the specimen; and

10 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

1762. The method of claim 1761, wherein the defects comprise macro defects.

15 1763. The method of claim 1751, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprising measuring a non-optical characteristic of the specimen.

20 1764. The method of claim 1751, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer.

1765. The method of claim 1751, wherein the measurement device further comprises at least an eddy current device and a spectroscopic ellipsometer, and wherein the measurement device is further coupled to an atomic layer deposition tool.

25

1766. The method of claim 1751, wherein the remote controller computer is coupled to a process tool.

1767. The method of claim 1751, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, and a deposition tool.

- 5 1768. The method of claim 1751, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback control technique.

10

1769. The method of claim 1751, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedforward control technique.

15

1770. The method of claim 1751, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

20

1771. The method of claim 1770, further comprising determining a relationship between the determined properties and at least one of the monitored parameters using the remote controller computer.

- 25 1772. The method of claim 1771, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

1773. The method of claim 1751, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, the method further comprising performing said directing and said detecting during a process step.

- 5 1774. The method of claim 1773, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

1775. The method of claim 1773, further comprising altering a parameter of one or more  
10 instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.

1776. The method of claim 1751, further comprising:

- 15 moving the specimen from a first process chamber to a second process chamber using the stage; and

performing said directing and said detecting during said moving the specimen.

- 20 1777. The method of claim 1751, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

1778. The method of claim 1751, further comprising comparing at least one of the  
25 determined properties of the specimen to a predetermined range for the property using the remote controller computer.

1779. The method of claim 1778, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5 1780. The method of claim 1751, wherein the remote controller computer is coupled to the measurement device.

1781. The method of claim 1780, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to at least one  
10 of the determined properties of the specimen.

1782. The method of claim 1780, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control technique.

15

1783. The method of claim 1780, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedforward control technique.

20

1784. The method of claim 1751, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first, second, and third properties of the specimen.

25 1785. The method of claim 1784, further comprising calibrating the measurement device using the database and the remote controller computer.

1786. The method of claim 1784, further comprising monitoring output signals of the measurement device using the database and the remote controller computer. .

1787. The method of claim 1784, wherein the database further comprises first, second,  
5 and third properties of a plurality of specimens.

1788. The method of claim 1787, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices.

10 1789. The method of claim 1788, further comprising calibrating the plurality of measurement devices using the database and the remote controller computer.

1790. The method of claim 1788, further comprising monitoring output signals of the plurality of measurement devices using the database and the remote controller computer.

15

1791. The method of claim 1751, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

20

1792. The method of claim 1751, further comprising altering a parameter of one or more instruments coupled to at least one of a plurality of process tools using the remote controller computer in response to at least one of the determined properties of the specimen.

25

1793. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

5                   an illumination system configured to direct energy toward a surface of the specimen during use; and

                  a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use,  
10               wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use; and

                  a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output  
15               signals during use, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.

1794. The system of claim 1793, wherein the stage is further configured to move  
20               laterally during use.

1795. The system of claim 1793, wherein the stage is further configured to move rotatably during use.

25   1796. The system of claim 1793, wherein the stage is further configured to move laterally and rotatably during use.

1797. The system of claim 1793, wherein the illumination system comprises a single energy source.

5 1798. The system of claim 1793, wherein the illumination system comprises more than one energy source.

1799. The system of claim 1793, wherein the detection system comprises a single energy sensitive device.

10 1800. The system of claim 1793, wherein the detection system comprises more than one energy sensitive devices.

1801 The system of claim 1793, wherein the measurement device further comprises a non-imaging scatterometer.

15

1802. The system of claim 1793, wherein the measurement device further comprises a scatterometer.

20 1803. The system of claim 1793, wherein the measurement device further comprises a spectroscopic scatterometer.

1804. The system of claim 1793, wherein the measurement device further comprises a reflectometer.

25 1805. The system of claim 1793, wherein the measurement device further comprises a spectroscopic reflectometer.

1806. The system of claim 1793, wherein the measurement device further comprises an ellipsometer.

5 1807. The system of claim 1793, wherein the measurement device further comprises a spectroscopic ellipsometer.

1808. The system of claim 1793, wherein the measurement device further comprises a bright field imaging device.

10 1809. The system of claim 1793, wherein the measurement device further comprises a dark field imaging device.

1810. The system of claim 1793, wherein the measurement device further comprises a bright field and dark field imaging device.

15

1811. The system of claim 1793, wherein the measurement device further comprises a non-imaging bright field device.

20 1812. The system of claim 1793, wherein the measurement device further comprises a non-imaging dark field device.

1813. The system of claim 1793, wherein the measurement device further comprises a non-imaging bright field and dark field device.

25 1814. The system of claim 1793, wherein the measurement device further comprises a double dark field device.



1815. The system of claim 1793, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

1816. The system of claim 1793, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

1817. The system of claim 1793, wherein the processor is further configured to determine a third property from the one or more output signals during use, wherein the third property comprises a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

1818. The system of claim 1793, wherein the macro defects comprise copper contamination on a back side of the specimen.

1819. The system of claim 1793, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of

the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1820. The system of claim 1819, wherein the system is coupled to a process tool  
5 selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

1821. The system of claim 1793, wherein the illumination system is further configured  
to direct energy toward a bottom surface of the specimen during use, wherein the  
10 detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the first property further comprises a presence of macro defects on the bottom surface of the specimen.

1822. The system of claim 1793, wherein the system is further configured to determine  
15 at least two properties of the specimen substantially simultaneously during use.

1823. The system of claim 1793, wherein the illumination system is further configured  
to direct energy to multiple locations on the surface of the specimen substantially  
simultaneously, and wherein the detection system is further configured to detect energy  
20 propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

1824. The system of claim 1793, wherein the system is coupled to a process tool.  
25

1825. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

1826. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.
1827. The system of claim 1793, wherein the system is coupled to a process tool, and  
5 wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.
1828. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool  
10 during use.
1829. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.  
15
1830. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.
1831. The system of claim 1793, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.  
20
1832. The system of claim 1793, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.  
25

1833. The system of claim 1793, wherein the system is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

1834. The system of claim 1793, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

1835. The system of claim 1793, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

1836. The system of claim 1793, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

1837. The system of claim 1793, wherein the system comprises a measurement chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

1838. The system of claim 1793, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

5 1839. The system of claim 1838, wherein the processor is further configured to determine at least the first and second properties of the specimen during the process step.

1840. The system of claim 1839, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises  
10 at least one singularity representative of an end of the process step.

1841. The system of claim 1839, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ  
15 control technique during use.

1842. The system of claim 1793, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during  
20 use.

1843. The system of claim 1842, wherein the system is further configured to determine at least the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

25 1844. The system of claim 1793, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

1845. The system of claim 1793, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

5

1846. The system of claim 1845, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

10 1847. The system of claim 1793, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

15 1848. The system of claim 1793, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

1849. The system of claim 1793, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to  
20 at least one of the determined properties using a feedforward control technique during use.

1850. The system of claim 1793, wherein the processor is further configured to generate a database during use, and wherein the database comprises the determined first and  
25 second properties of the specimen.

1851. The system of claim 1850, wherein the processor is further configured to calibrate the measurement device using the database during use.

1852. The system of claim 1850, wherein the processor is further configured to monitor the determined properties generated by measurement device using the database during use.

5

1853. The system of claim 1850, wherein the database further comprises first and second properties of a plurality of specimens.

1854. The system of claim 1853, wherein the first and second properties of the plurality of specimens are determined using the measurement device.

10

1855. The system of claim 1853, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices.

1856. The system of claim 1855, wherein the processor is further coupled to the plurality of measurement devices.

15

1857. The system of claim 1856, wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

20

1858. The system of claim 1856, wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

1859. The system of claim 1793, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

25

1860. The system of claim 1793, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is  
5 further configured to calibrate the system and at least the one additional system during use.

1861. The system of claim 1793, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen,  
10 wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1862. The system of claim 1793, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

20 1863. The system of claim 1793, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

25 1864. The system of claim 1793, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.



1865. The system of claim 1864, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

- 5 1866. The system of claim 1864, wherein the processor is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

1867. The system of claim 1793, wherein the processor is further coupled to a plurality of measurement devices, and wherein at least one of the plurality of measurement devices  
10 is coupled to at least one of a plurality of process tools.

1868. The system of claim 1793, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

15

1869. The system of claim 1793, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured  
20 to further process the at least partially processed one or more output signals during use.

1870. The system of claim 1869, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

- 25 1871. The system of claim 1869, wherein the remote controller computer is further configured to determine the first property and the second property of the specimen during use.

1872. A method for determining at least two properties of a specimen, comprising:
- 5 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;
- directing energy toward a surface of the specimen using the illumination system;
- 10 detecting energy propagating from the surface of the specimen using the detection system;
- generating one or more output signals responsive to the detected energy; and
- 15 processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.
1873. The method of claim 1872, further comprising laterally moving the stage during
- 20 said directing energy and said detecting energy.
1874. The method of claim 1872, further comprising rotatably moving the stage during said directing energy and said detecting energy.
- 25 1875. The method of claim 1872, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

1876. The method of claim 1872, wherein the illumination system comprises a single energy source.

5 1877. The method of claim 1872, wherein the illumination system comprises more than one energy source.

1878. The method of claim 1872, wherein the detection system comprises a single energy sensitive device.

10 1879. The method of claim 1872, wherein the detection system comprises more than one energy sensitive devices.

1880. The method of claim 1872, wherein detecting light comprises detecting dark field light propagating along a dark field path from the surface of the specimen.

15 1881. The method of claim 1872, wherein the measurement device further comprises a non-imaging scatterometer.

20 1882. The method of claim 1872, wherein the measurement device further comprises a scatterometer.

1883. The method of claim 1872, wherein the measurement device further comprises a spectroscopic scatterometer.

25 1884. The method of claim 1872, wherein the measurement device further comprises a reflectometer.

1885. The method of claim 1872, wherein the measurement device further comprises a spectroscopic reflectometer.
- 5 1886. The method of claim 1872, wherein the measurement device further comprises an ellipsometer.
1887. The method of claim 1872, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 10 1888. The method of claim 1872, wherein the measurement device further comprises a bright field imaging device.
1889. The method of claim 1872, wherein the measurement device further comprises a dark field imaging device.
- 15 1890. The method of claim 1872, wherein the measurement device further comprises a bright field and dark field imaging device.
1891. The method of claim 1872, wherein the measurement device further comprises a non-imaging bright field device.
- 20 1892. The method of claim 1872, wherein the measurement device further comprises a non-imaging dark field device.
- 25 1893. The method of claim 1872, wherein the measurement device further comprises a non-imaging bright field and dark field device.

1894. The method of claim 1872, wherein the measurement device further comprises a double dark field device.

5 1895. The method of claim 1872, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device,  
10 a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

15 1896. The method of claim 1872, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

20 1897. The method of claim 1872, further comprising:

directing energy toward a bottom surface of the specimen; and

25 detecting energy propagating from the bottom surface of the specimen, wherein the first property further comprises a presence of macro defects on the bottom surface of the specimen.

1898. The method of claim 1872, further comprising processing the one or more output signals to determine a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

- 5 1899. The method of claim 1872, wherein the macro defects comprise copper contamination on a back side of the specimen.

1900. The method of claim 1872, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is  
10 selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1901. The method of claim 1900, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an  
15 atomic layer deposition tool, a cleaning tool, and an etch tool.

1902. The method of claim 1872, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.  
20

1903. The method of claim 1872, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple  
25 locations substantially simultaneously.

1904. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool.

1905. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

5

1906. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

10 1907. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

15 1908. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

20 1909. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

25 1910. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

1911. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

5

1912. The method of claim 1872, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

10

1913. The method of claim 1872, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

15 1914. The method of claim 1872, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

1915. The method of claim 1872, wherein the stage and the measurement device are  
20 disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

1916. The method of claim 1872, wherein the stage and the measurement device are  
25 arranged vertically proximate to a process chamber of a process tool.

1917. The method of claim 1872, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process



chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

1918. The method of claim 1917, further comprising performing said directing and said  
5 detecting during the process step.

1919. The method of claim 1917, further comprising obtaining a signature  
characterizing the process step, wherein the signature comprises at least one singularity  
representative of an end of the process step.

10

1920. The method of claim 1917, further comprising altering a parameter of one or more  
instruments coupled to the process tool in response to at least one of the determined  
properties using an in situ control technique.

15 1921. The method of claim 1872, further comprising moving the specimen from a first  
process chamber to a second process chamber using the stage, wherein the first process  
chamber and the second process chamber are disposed within a process tool.

1922. The method of claim 1921, further comprising performing said directing and said  
20 detecting during said moving the specimen from the first process chamber to the second  
process chamber.

1923. The method of claim 1872, further comprising comparing at least one of the  
determined properties of the specimen and determined properties of a plurality of  
25 specimens.

1924. The method of claim 1872, further comprising comparing at least one of the  
determined properties of the specimen to a predetermined range for the property.

1925. The method of claim 1924, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5

1926. The method of claim 1872, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

10 1927. The method of claim 1872, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

15 1928. The method of claim 1872, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

1929. The method of claim 1872, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

20

1930. The method of claim 1929, further comprising calibrating the measurement device using the database.

25 1931. The method of claim 1929, further comprising monitoring output signals generated by the measurement device using the database.

1932. The method of claim 1929, wherein the database further comprises first and second properties of a plurality of specimens.

1933. The method of claim 1932, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

5 1934. The method of claim 1933, further comprising calibrating the plurality of measurement devices using the database.

1935. The method of claim 1933, further comprising monitoring output signals generated by the plurality of measurement devices using the database.

10

1936. The method of claim 1872, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

15

1937. The method of claim 1872, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

20

1938. The method of claim 1872, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one  
25 parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

1939. The method of claim 1872, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.
- 5 1940. The method of claim 1872, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.
1941. The method of claim 1872, further comprising monitoring a parameter of one or  
10 more instruments coupled to the process tool.
1942. The method of claim 1941, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.
- 15 1943. The method of claim 1942, further comprising altering a parameter of at least one of the instruments in response to the relationship.
1944. The method of claim 1872, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the  
20 determined properties of the specimen.
1945. The method of claim 1872, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.  
25
1946. The method of claim 1872, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor,  
wherein the local processor is coupled to the measurement device;

5        sending the partially processed one or more output signals from the local  
processor to a remote controller computer; and

      further processing the partially processed one or more output signals using the  
remote controller computer.

10      1947. The method of claim 1946, wherein at least partially processing the one or more  
output signals comprises determining the first and second properties of the specimen.

      1948. The method of claim 1946, wherein further processing the partially processed one  
or more output signals comprises determining the first and second properties of the  
15      specimen.

      1949. A computer-implemented method for controlling a system configured to  
determine at least two properties of a specimen during use, wherein the system comprises  
a measurement device, comprising:

20        controlling the measurement device, wherein the measurement device comprises  
an illumination system and a detection system, and wherein the measurement  
device is coupled to a stage, comprising:

25        controlling the illumination system to direct energy toward a surface of the  
specimen;

controlling the detection system to detect energy propagating from the surface of the specimen; and

generating one or more output signals responsive to the detected energy;  
and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.

1950. The method of claim 1949, further comprising controlling the stage, wherein the stage is configured to support the specimen.

1951. The method of claim 1949, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.

1952. The method of claim 1949, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.

1953. The method of claim 1949, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.

1954. The method of claim 1949, wherein the illumination system comprises a single energy source.

1955. The method of claim 1949, wherein the illumination system comprises more than one energy source.

1956. The method of claim 1949, wherein the detection system comprises a single energy sensitive device.

5 1957. The method of claim 1949, wherein the detection system comprises more than one energy sensitive devices.

1958. The method of claim 1949, wherein the measurement device further comprises a non-imaging scatterometer.

10

1959. The method of claim 1949, wherein the measurement device further comprises a scatterometer.

15

1960. The method of claim 1949, wherein the measurement device further comprises a spectroscopic scatterometer.

1961. The method of claim 1949, wherein the measurement device further comprises a reflectometer.

20

1962. The method of claim 1949, wherein the measurement device further comprises a spectroscopic reflectometer

1963. The method of claim 1949, wherein the measurement device further comprises an ellipsometer.

25

1964. The method of claim 1949, wherein the measurement device further comprises a spectroscopic ellipsometer.

1965. The method of claim 1949, wherein the measurement device further comprises a bright field imaging device.

5 1966. The method of claim 1949, wherein the measurement device further comprises a dark field imaging device.

1967. The method of claim 1949, wherein the measurement device further comprises a bright field and dark field imaging device.

10 1968. The method of claim 1949, wherein the measurement device further comprises a non-imaging bright field device.

1969. The method of claim 1949, wherein the measurement device further comprises a non-imaging dark field device.

15

1970. The method of claim 1949, wherein the measurement device further comprises a non-imaging bright field and dark field device.

20 1971. The method of claim 1949, wherein the measurement device further comprises a double dark field device.

1972. The method of claim 1949, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a  
25 spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright



field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

5     1973. The method of claim 1949, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10    1974. The method of claim 1949, further comprising:

controlling the illumination system to direct energy toward a bottom surface of the specimen; and

15       controlling the detection system to detect energy propagating from the bottom surface of the specimen, wherein the first property comprises a presence of defects on the bottom surface of the specimen.

1975. The method of claim 1949, further comprising processing the one or more output  
20    signals to determine a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

1976. The method of claim 1949, wherein the macro defects comprise copper  
contamination on a back side of the specimen.

25

1977. The method of claim 1949, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is

selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

1978. The method of claim 1977, wherein the stage and the measurement device are  
5 coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

1979. The method of claim 1949, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially  
10 simultaneously determining the first and second properties of the specimen.

1980. The method of claim 1949, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the  
15 multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

1981. The method of claim 1949, wherein the stage and the measurement device are  
20 coupled to a process tool.

1982. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

25

1983. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

1984. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical  
5 polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

1985. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is  
10 coupled to the process tool.

1986. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.

1987. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.

1988. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

1989. The method of claim 1949, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured

to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

1990. The method of claim 1949, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

1991. The method of claim 1949, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

1992. The method of claim 1949, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

1993. The method of claim 1949, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

1994. The method of claim 1949, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

1995. The method of claim 1994, further comprising controlling the illumination system and controlling the detection system during the process step.

1996. The method of claim 1995, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

5 1997. The method of claim 1995, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

1998. The method of claim 1949, further comprising controlling the stage to move the  
10 specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

1999. The method of claim 1998, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first  
15 process chamber to the second process chamber.

2000. The method of claim 1949, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.  
20

2001. The method of claim 1949, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

2002. The method of claim 2001, further comprising generating an output signal if at  
25 least one of the determined properties of the specimen is outside of the predetermined range for the property.

2003. The method of claim 1949, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties.

2004. The method of claim 1949, further comprising altering a parameter of one or more  
5 instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

2005. The method of claim 1949, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2006. The method of claim 1949, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the database.

15 2007. The method of claim 1949, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals generated by the measurement device using the database.

20 2008. The method of claim 1949, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

25 2009. The method of claim 1949, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and

wherein the database further comprises first and second properties of a plurality of specimens generated using a plurality of measurement devices.

2010. The method of claim 2009, further comprising calibrating the plurality of  
5 measurement devices using the database.

2011. The method of claim 2009, further comprising monitoring output signals generated by the plurality of measurement devices using the database.

10 2012. The method of claim 1949, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

15 2013. The method of claim 1949, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

20

2014. The method of claim 1949, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least  
25 one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

2015. The method of claim 1949, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.
- 5    2016. The method of claim 1949, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.
2017. The method of claim 1949, further comprising monitoring a parameter of one or  
10 more instruments coupled to a process tool.
2018. The method of claim 1949, further comprising monitoring a parameter of one or more instruments coupled to a process tool and determining a relationship between at least one of the determined properties and at least one of the monitored parameters.  
15
2019. The method of claim 1949, further comprising monitoring a parameter of one or more instruments coupled to a process tool, determining a relationship between at least one of the determined properties and at least one of the monitored parameters, and altering a parameter of at least one of the instruments in response to the relationship.  
20
2020. The method of claim 1949, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the determined properties of the specimen.
- 25    2021. The method of claim 1949, wherein the measurement device comprises non-optical components, and wherein controlling the detection system to detect energy comprises controlling the non-optical components to measure a non-optical characteristic of the surface of the specimen.



2022. The method of claim 1949, wherein processing the one or more output signals comprises:

5           at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

          sending the partially processed one or more output signals from the local processor to a remote controller computer; and

10

          further processing the partially processed one or more output signals using the remote controller computer.

2023. The method of claim 2022, wherein at least partially processing the one or more  
15   output signals comprises determining the first and second properties of the specimen.

2024. The method of claim 2022, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

20

2025. A semiconductor device fabricated by a method, the method comprising:

          forming a portion of the semiconductor device upon a specimen;

25           disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

5

generating one or more output signals in response to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.

10

2026. The device of claim 2025, wherein the illumination system comprises a single energy source.

15

2027. The device of claim 2025, wherein the illumination system comprises more than one energy source.

2028. The device of claim 2025, wherein the detection system comprises a single energy sensitive device.

20

2029. The device of claim 2025, wherein the detection system comprises more than one energy sensitive devices.

2030. The device of claim 2025, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a

25

bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2031. The device of claim 2025, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2032. The device of claim 2025, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2033. The device of claim 2025, further comprising:  
directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein the first property further comprises a presence of macro defects on the bottom surface of the specimen.

5     2034. The device of claim 2025, further comprising processing the one or more output signals to determine a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

2035. The device of claim 2025, wherein the macro defects comprise copper  
10     contamination on a back side of the specimen.

2036. The device of claim 2025, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer  
15     on the specimen, and a roughness of a feature of the specimen.

2037. The device of claim 2036, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.  
20

2038. The device of claim 2025, wherein the stage and the measurement device are coupled to a process tool.

2039. The device of claim 2025, wherein the stage and the measurement device are  
25     coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

2040. The device of claim 2025, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the surface of the specimen.

5     2041. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;

10     disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

15     detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

20     processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.

25     2042. The method of claim 2041, wherein the illumination system comprises a single energy source.

2043. The method of claim 2041, wherein the illumination system comprises more than one energy source.

2044. The method of claim 2041, wherein the detection system comprises a single  
5 energy sensitive device.

2045. The method of claim 2041, wherein the detection system comprises more than one energy sensitive devices.

10 2046. The method of claim 2041, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a  
15 bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

20 2047. The method of claim 2041, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field  
25 imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray

fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2048. The method of claim 2041, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2049. The method of claim 2041, further comprising:  
10 directing energy toward a bottom surface of the specimen; and  
  
detecting energy propagating from the bottom surface of the specimen, wherein  
the first property further comprises a presence of macro defects on the bottom  
15 surface of the specimen.

2050. The method of claim 2041, further comprising processing the one or more output signals to determine a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

2051. The method of claim 2041, wherein the macro defects comprise copper contamination on a back side of the specimen.

2052. The method of claim 2041, further comprising processing the one or more output  
25 signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

2053. The method of claim 2052, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

- 5 2054. The method of claim 2041, wherein the stage and the measurement device are coupled to a process tool.

2055. The method of claim 2041, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group  
10 consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

2056. The method of claim 2041, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical  
15 characteristic of the surface of the specimen.

2057. A system configured to determine at least two properties of a specimen during use, comprising:

- 20 a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

- 25 an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use,



wherein the measurement device is configured to generate one or more output signals responsive to the detected energy;

5 a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

10 a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen.

15 2058. The system of claim 2057, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-  
20 imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

25 2059. The system of claim 2057, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a

spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray  
5 fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2060. The system of claim 2057, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical  
10 elements of the first measurement device comprise optical elements of the second measurement device.

2061. The system of claim 2057, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the  
15 detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the first property further comprises a presence of macro defects on the bottom surface of the specimen.

2062. The system of claim 2057, wherein the remote controller computer is configured  
20 to determine a third property from the at least partially processed one or more output signals during use, wherein the third property comprises a thickness of a copper film, and wherein the macro defects or the micro defects comprise voids in the copper film.

2063. The system of claim 2057, wherein the macro defects comprise copper  
25 contamination on a back side of the specimen.

2064. The system of claim 2057, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially

processed one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

5    2065. The system of claim 2064, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

10    2066. The system of claim 2057, wherein the remote controller computer is coupled to a process tool.

2067. The system of claim 2057, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

20    2068. The system of claim 2057, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

25    2069. The system of claim 2057, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

2070. The system of claim 2057, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

- 5     2071. The system of claim 2070, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

2072. The system of claim 2071, wherein the remote controller computer is further  
10     configured to alter a parameter of at least one of the instruments in response to the relationship during use.

2073. The system of claim 2057, wherein the remote controller computer is coupled to a process tool, wherein the illumination system is further configured to direct energy  
15     toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during the process step.

- 20     2074. The system of claim 2073, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

- 25     2075. The system of claim 2073, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

2076. The system of claim 2057, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

2077. The system of claim 2076, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

2078. The system of claim 2057, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

2079. The system of claim 2057, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

2080. The system of claim 2079, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

2081. The system of claim 2057, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

2082. The system of claim 2057, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control  
5 technique during use.

2083. The system of claim 2057, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control  
10 technique during use.

2084. The system of claim 2057, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller  
15 computer is further configured to calibrate the measurement device using the database during use.

2085. The system of claim 2057, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the  
20 determined first and second properties of the specimen, and wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

2086. The system of claim 2057, wherein the remote controller computer is further  
25 configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

2087. The system of claim 2057, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens determined using a plurality of measurement devices.

2088. The system of claim 2087, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

2089. The system of claim 2087, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

2090. The system of claim 2057, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein each of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

2091. The system of claim 2057, wherein the remote controller computer is further coupled to a plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

2092. The system of claim 2057, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the surface of the specimen.

2093. A method for determining at least two properties of a specimen, comprising:

5 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

10 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

15 processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a presence of macro defects on the specimen, and wherein the second property comprises a presence of micro defects on the specimen, comprising:

20 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

25 sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.



2094. The method of claim 2093, wherein the measurement device is selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2095. The method of claim 2093, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a spectroscopic reflectometer, an ellipsometer, a spectroscopic ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a double dark field device, an X-ray reflectometer, an X-ray fluorescence device, an optical fluorescence device, an eddy current imaging device, and a relatively large spot e-beam device.

2096. The method of claim 2093, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2097. The method of claim 2093, further comprising:

directing energy toward a bottom surface of the specimen; and

5 detecting energy propagating from the bottom surface of the specimen, wherein  
the first property further comprises a presence of macro defects on the bottom  
surface of the specimen.

2098. The method of claim 2093, further comprising processing the one or more output  
signals to determine a thickness of a copper film, and wherein the macro defects or the  
10 micro defects comprise voids in the copper film.

2099. The method of claim 2093, wherein the macro defects comprise copper  
contamination on a back side of the specimen.

15 2100. The method of claim 2093, further comprising processing the one or more output  
signals to determine a third property of the specimen, wherein the third property is  
selected from the group consisting of a roughness of the specimen, a roughness of a layer  
on the specimen, and a roughness of a feature of the specimen.

20 2101. The method of claim 2100, wherein the stage and the measurement device are  
coupled to a process tool selected from the group consisting of a lithography tool, an  
atomic layer deposition tool, a cleaning tool, and an etch tool.

2102. The method of claim 2093, wherein the remote controller computer is coupled to a  
25 process tool.

2103. The method of claim 2093, wherein the remote controller computer is coupled to a  
process tool, and wherein the process tool is selected from the group consisting of a

lithography tool, an etch tool, an ion implanter, a chemical-mechanical polishing tool, a deposition tool, a thermal tool, a cleaning tool, and a plating tool.

2104. The method of claim 2093, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback control technique.

2105. The method of claim 2093, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedforward control technique.

2106. The method of claim 2093, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

2107. The method of claim 2093, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer and determining a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer.

2108. The method of claim 2093, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer, determining

a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer, and altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

5

2109. The method of claim 2093, wherein the illumination system and the detection system are coupled to a process chamber of a process tool, the method further comprising performing said directing and said detecting during a process step.

10 2110. The method of claim 2109, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

15 2111. The method of claim 2109, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.

2112. The method of claim 2093, further comprising:

20 moving the specimen from a first process chamber to a second process chamber using the stage; and

performing said directing and said detecting during said moving the specimen.

25 2113. The method of claim 2093, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

2114. The method of claim 2093, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

- 5     2115. The method of claim 2114, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

2116. The method of claim 2093, wherein the remote controller computer is coupled to  
10     the measurement device.

2117. The method of claim 2116, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to at least one of the determined properties of the specimen.

15

2118. The method of claim 2116, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control technique.

- 20     2119. The method of claim 2116, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedforward control technique.

- 25     2120. The method of claim 2093, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen.

2121. The method of claim 2093, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the remote controller computer and the database.

5

2122. The method of claim 2093, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals generated by the measurement device using the remote controller computer and the database.

10

2123. The method of claim 2093, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

15

2124. The method of claim 2123, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices.

20

2125. The method of claim 2124, further comprising calibrating the plurality of measurement devices using the remote controller computer and the database.

2126. The method of claim 2124, further comprising monitoring output signals generated by the plurality of measurement devices using the remote controller computer and the database.

25

2127. The method of claim 2093, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote

controller computer, wherein each of the plurality of local processors is coupled to a measurement device.

2128. The method of claim 2127, further comprising altering a parameter of one or more  
5 instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to at least one of the determined properties of the specimen.

2129. The method of claim 2127, wherein at least one of the plurality of measurement  
10 devices is coupled to one of a plurality of process tools.

2130. The method of claim 2129, further comprising altering a parameter of one or more  
instruments coupled to at least one of the plurality of process tools using the remote  
controller computer in response to at least one of the determined properties of the  
15 specimen.

2131. The method of claim 2093, wherein the measurement device comprises non-  
optical components, and wherein detecting energy comprises measuring a non-optical  
characteristic of the surface of the specimen.

20

2132. A system configured to determine at least three properties of a specimen during  
use, comprising:

a stage configured to support the specimen during use;

25

a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

5 a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use; and

10 a processor coupled to the measurement device and configured to determine a first property, a second property, and a third property of the specimen from the one or more output signals during use, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

15 2133. The system of claim 2132, wherein the stage is further configured to move laterally during use.

20 2134. The system of claim 2132, wherein the stage is further configured to move rotatably during use.

2135. The system of claim 2132, wherein the stage is further configured to move laterally and rotatably during use.

25 2136. The system of claim 2132, wherein the illumination system comprises a single energy source.



2137. The system of claim 2132, wherein the illumination system comprises more than one energy source.
- 5 2138. The system of claim 2132, wherein the detection system comprises a single energy sensitive device.
2139. The system of claim 2132, wherein the detection system comprises more than one energy sensitive devices.
- 10 2140. The system of claim 2132, wherein the measurement device further comprises an optical profilometer.
2141. The system of claim 2132, wherein the measurement device further comprises an interferometer.
- 15 2142. The system of claim 2132, wherein the measurement device further comprises a spectroscopic reflectometer.
- 20 2143. The system of claim 2132, wherein the measurement device further comprises a spectroscopic ellipsometer.
2144. The system of claim 2132, wherein the measurement device further comprises a dual beam spectrophotometer.
- 25 2145. The system of claim 2132, wherein the measurement device further comprises a beam profile ellipsometer.

2146. The system of claim 2132, wherein the measurement device further comprises a non-imaging scatterometer.
- 5 2147. The system of claim 2132, wherein the measurement device further comprises a scatterometer.
2148. The system of claim 2132, wherein the measurement device further comprises a spectroscopic scatterometer.
- 10 2149. The system of claim 2132, wherein the measurement device further comprises a reflectometer.
2150. The system of claim 2132, wherein the measurement device further comprises an ellipsometer.
- 15 2151. The system of claim 2132, wherein the measurement device further comprises a bright field imaging device.
2152. The system of claim 2132, wherein the measurement device further comprises a dark field imaging device.
- 20 2153. The system of claim 2132, wherein the measurement device further comprises a bright field and dark field imaging device.
- 25 2154. The system of claim 2132, wherein the measurement device further comprises a non-imaging bright field device.

2155. The system of claim 2132, wherein the measurement device further comprises a non-imaging dark field device.
2156. The system of claim 2132, wherein the measurement device further comprises a non-imaging bright field and dark field device.
2157. The system of claim 2132, wherein the measurement device further comprises a double dark field device.
2158. The system of claim 2132, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.
2159. The system of claim 2132, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
2160. The system of claim 2132, wherein the defects comprise micro defects and macro defects.

2161. The system of claim 2132, wherein the defects comprises micro defects or macro defects.

2162. The system of claim 2132, wherein the thin film characteristic comprises a  
5 thickness of a copper film, and wherein the defects comprise voids in the copper film.

2163. The system of claim 2132, wherein the defects comprise copper contamination on a back side of the specimen.

10 2164. The system of claim 2132, wherein the processor is further configured to determine a fourth property of the specimen from the one or more output signals during use, and wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

15

2165. The system of claim 2164, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

20 2166. The system of claim 2132, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

25

2167. The system of claim 2166, wherein the defects comprise macro defects.

2168. The system of claim 2132, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the specimen.

- 5     2169. The system of claim 2132, wherein the system is further configured to determine at least the three properties of the specimen substantially simultaneously during use.

2170. The system of claim 2132, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially  
10 simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be determined substantially simultaneously.

- 15     2171. The system of claim 2132, wherein the system is coupled to a semiconductor fabrication process tool.

2172. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

20

2173. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

2174. The system of claim 2132, wherein the system is coupled to a process tool, and  
25 wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

2175. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.

- 5 2176. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.

- 10 2177. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

- 15 2178. The system of claim 2132, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

- 20 2179. The system of claim 2132, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

- 25 2180. The system of claim 2132, wherein the system is coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.

2181. The system of claim 2132, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the

measurement chamber, and wherein the measurement chamber is coupled to a process tool.

2182. The system of claim 2132, wherein the system further comprises a measurement  
5 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

2183. The system of claim 2132, wherein the system further comprises a measurement  
10 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

2184. The system of claim 2132, wherein the system further comprises a measurement  
15 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

2185. The system of claim 2132, wherein a process tool comprises a process chamber,  
20 wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

2186. The system of claim 2185, wherein the processor is further configured to  
determine at least the three properties of the specimen during the process step.

25 2187. The system of claim 2186, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

2188. The system of claim 2186, wherein the processor is further coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

2189. The system of claim 2132, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

2190. The system of claim 2189, wherein the system is further configured to determine at least the three properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

2191. The system of claim 2132, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

2192. The system of claim 2132, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

2193. The system of claim 2192, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.



2194. The system of claim 2132, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

- 5 2195. The system of claim 2132, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

- 10 2196. The system of claim 2132, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

- 15 2197. The system of claim 2132, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined properties of the specimen, and wherein the processor is further configured to calibrate the measurement device using the database during use.

- 20 2198. The system of claim 2132, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined properties of the specimen, and wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

- 25 2199. The system of claim 2132, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined properties of the specimen, and wherein the database further comprises first, second, and third properties of a plurality of specimens.

2200. The system of claim 2199, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

2201. The system of claim 2199, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

2202. The system of claim 2132, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

2203. The system of claim 2132, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

2204. The system of claim 2132, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to

at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

5 2205. The system of claim 2132, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

10 2206. The system of claim 2132, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

15 2207. The system of claim 2132, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

20 2208. The system of claim 2207, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

2209. The system of claim 2208, wherein the processor is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

25 2210. The system of claim 2132, wherein the processor is further coupled to a plurality of measurement devices, and wherein at least one of the plurality of measurement devices is coupled to one of a plurality of process tools.

2211. The system of claim 2132, wherein the processor is further coupled to a plurality of process tools, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

5

2212. The system of claim 2132, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

10

2213. The system of claim 2212, wherein the local processor is further configured to determine the first, second, and third properties of the specimen during use.

15

2214. The system of claim 2212, wherein the remote controller computer is further configured to determine the first, second, and third properties of the specimen during use.

2215. A method for determining at least three properties of a specimen, comprising:

20

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

25

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5        processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

10       2216. The method of claim 2215, further comprising laterally moving the stage during said directing energy and said detecting energy.

2217. The method of claim 2215, further comprising rotatably moving the stage during said directing energy and said detecting energy.

15       2218. The method of claim 2215, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

20       2219. The method of claim 2215, wherein the illumination system comprises a single energy source.

2220. The method of claim 2215, wherein the illumination system comprises more than one energy source.

25       2221. The method of claim 2215, wherein the detection system comprises a single energy sensitive device.

2222. The method of claim 2215, wherein the detection system comprises more than one energy sensitive devices.

2223. The method of claim 2215, wherein the measurement device further comprises an optical profilometer.

5 2224. The method of claim 2215, wherein the measurement device further comprises an interferometer.

2225. The method of claim 2215, wherein the measurement device further comprises a spectroscopic reflectometer.

10

2226. The method of claim 2215, wherein the measurement device further comprises a spectroscopic ellipsometer.

15 2227. The method of claim 2215, wherein the measurement device further comprises a dual beam spectrophotometer.

2228. The method of claim 2215, wherein the measurement device further comprises a beam profile ellipsometer.

20 2229. The method of claim 2215, wherein the measurement device further comprises a non-imaging scatterometer.

2230. The method of claim 2215, wherein the measurement device further comprises a scatterometer.

25

2231. The method of claim 2215, wherein the measurement device further comprises a spectroscopic scatterometer.

2232. The method of claim 2215, wherein the measurement device further comprises a reflectometer.

5 2233. The method of claim 2215, wherein the measurement device further comprises an ellipsometer.

2234. The method of claim 2215, wherein the measurement device further comprises a bright field imaging device.

10 2235. The method of claim 2215, wherein the measurement device further comprises a dark field imaging device.

15 2236. The method of claim 2215, wherein the measurement device further comprises a bright field and dark field imaging device.

2237. The method of claim 2215, wherein the measurement device further comprises a non-imaging bright field device.

20 2238. The method of claim 2215, wherein the measurement device further comprises a non-imaging dark field device.

2239. The method of claim 2215, wherein the measurement device further comprises a non-imaging bright field and dark field device.

25 2240. The method of claim 2215, wherein the measurement device further comprises a double dark field device.

2241. The method of claim 2215, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.
2242. The method of claim 2215, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
2243. The method of claim 2215, wherein the defects comprise micro defects and macro defects.
2244. The method of claim 2215, wherein the defects comprises micro defects or macro defects.
2245. The method of claim 2215, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.
2246. The method of claim 2215, wherein the defects comprise copper contamination on a back side of the specimen.



2247. The method of claim 2215, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

5

2248. The method of claim 2247, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

10 2249. The method of claim 2215, further comprising:

directing energy toward a bottom surface of the specimen; and

15 detecting energy propagating from the bottom surface of the specimen, wherein the second property comprises a presence of defects on the bottom surface of the specimen.

2250. The method of claim 2249, wherein the defects comprise macro defects.

20 2251. The method of claim 2215, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the specimen.

25 2252. The method of claim 2215, wherein processing the one or more output signals to determine the first, second, and properties of the specimen comprises substantially simultaneously determining the first, second, and third properties of the specimen.

2253. The method of claim 2215, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be  
5 determined substantially simultaneously.

2254. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool.

10 2255. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

2256. The method of claim 2215, wherein the stage and the measurement device are  
15 coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

2257. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, and wherein the semiconductor fabrication process tool is  
20 selected from the group consisting of a lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.

2258. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and  
25 wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

2259. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

- 5     2260. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

- 10    2261. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

- 15    2262. The method of claim 2215, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

- 20    2263. The method of claim 2215, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

- 25    2264. The method of claim 2215, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

2265. The method of claim 2215, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

- 5     2266. The method of claim 2215, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

- 10     2267. The method of claim 2215, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

- 15     2268. The method of claim 2267, further comprising performing said directing and said detecting during the process step.

- 20     2269. The method of claim 2268, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

2270. The method of claim 2268, further comprising altering a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

- 25     2271. The method of claim 2215, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

2272. The method of claim 2271, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

- 5 2273. The method of claim 2215, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

2274. The method of claim 2215, further comprising comparing at least one of the  
10 determined properties of the specimen to a predetermined range for the property.

2275. The method of claim 2274, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

15

2276. The method of claim 2215, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

- 20 2277. The method of claim 2215, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

2278. The method of claim 2215, further comprising altering a parameter of one or more  
25 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2279. The method of claim 2215, further comprising generating a database, wherein the database comprises the determined properties of the specimen, the method further comprising calibrating the measurement device using the database.

5     2280. The method of claim 2215, further comprising generating a database, wherein the database comprises the determined properties of the specimen, the method further comprising monitoring output signals generated by the measurement device using the database.

10    2281. The method of claim 2215, further comprising generating a database, wherein the database comprises the determined properties of the specimen, and wherein the database further comprises first, second, and third properties of a plurality of specimens.

15    2282. The method of claim 2281, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.

20    2283. The method of claim 2281, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals generated by the plurality of measurement devices using the database.

25    2284. The method of claim 2215, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

2285. The method of claim 2215, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand  
5 alone system.

2286. The method of claim 2215, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one  
10 parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

2287. The method of claim 2215, further comprising altering a parameter of one or more  
15 instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.

2288. The method of claim 2215, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined  
20 properties of the specimen using a feedforward control technique.

2289. The method of claim 2215, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

25 2290. The method of claim 2215, further comprising monitoring a parameter of an instrument coupled to a process tool and determining a relationship between the at least one of the determined properties and at least one of the monitored parameters.

2291. The method of claim 2215, further comprising monitoring a parameter of an instrument coupled to a process tool, determining a relationship between the at least one of the determined properties and at least one of the monitored parameters, and altering a parameter of at least one of the instruments in response to the relationship.

5

2292. The method of claim 2215, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the determined properties of the specimen.

10 2293. The method of claim 2215, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

15

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

20

further processing the partially processed one or more output signals using the remote controller computer.

2294. The method of claim 2293, wherein at least partially processing the one or more output signals comprises determining the first, second, and third properties of the specimen.

25

2295. The method of claim 2293, wherein further processing the partially processed one or more output signals comprises determining the first, second, and third properties of the specimen.



2296. A computer-implemented method for controlling a system configured to determine at least three properties of a specimen during use, wherein the system comprises a measurement device, comprising:

5

controlling the measurement device, wherein the measurement device comprises an illumination system and a detection system, and wherein the measurement device is coupled to a stage, comprising:

10

controlling the illumination system to direct energy toward a surface of the specimen;

controlling the detection system to detect energy propagating from the surface of the specimen; and

15

generating one or more output signals responsive to the detected energy; and

20

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

25

2297. The method of claim 2296, further comprising controlling the stage, wherein the stage is configured to support the specimen.

2298. The method of claim 2296, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.
2299. The method of claim 2296, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.
2300. The method of claim 2296, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.
2301. The method of claim 2296, wherein the illumination system comprises a single energy source.
2302. The method of claim 2296, wherein the illumination system comprises more than one energy source.
2303. The method of claim 2296, wherein the detection system comprises a single energy sensitive device.
2304. The method of claim 2296, wherein the detection system comprises more than one energy sensitive devices.
2305. The method of claim 2296, wherein the measurement device comprises an optical profilometer.
2306. The method of claim 2296, wherein the measurement device further comprises an interferometer.

2307. The method of claim 2296, wherein the measurement device further comprises a spectroscopic reflectometer.
- 5 2308. The method of claim 2296, wherein the measurement device further comprises a spectroscopic ellipsometer.
2309. The method of claim 2296, wherein the measurement device further comprises a dual beam spectrophotometer.
- 10 2310. The method of claim 2296, wherein the measurement device further comprises a beam profile ellipsometer.
2311. The method of claim 2296, wherein the measurement device further comprises a non-imaging scatterometer.
- 15 2312. The method of claim 2296, wherein the measurement device further comprises a scatterometer.
2313. The method of claim 2296, wherein the measurement device further comprises a spectroscopic scatterometer.
- 20 2314. The method of claim 2296, wherein the measurement device further comprises a reflectometer.
- 25 2315. The method of claim 2296, wherein the measurement device further comprises an ellipsometer.

2316. The method of claim 2296, wherein the measurement device further comprises a bright field imaging device.

5 2317. The method of claim 2296, wherein the measurement device further comprises a dark field imaging device.

2318. The method of claim 2296, wherein the measurement device further comprises a bright field and dark field imaging device.

10 2319. The method of claim 2296, wherein the measurement device further comprises a non-imaging bright field device.

2320. The method of claim 2296, wherein the measurement device further comprises a non-imaging dark field device.

15 2321. The method of claim 2296, wherein the measurement device further comprises a non-imaging bright field and dark field device.

20 2322. The method of claim 2296, wherein the measurement device further comprises a double dark field device.

2323. The method of claim 2296, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical  
25 profilometer, an interferometer, a spectroscopic reflectometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging

device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

2324. The method of claim 2296, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2325. The method of claim 2296, wherein the defects comprise micro defects and macro  
10 defects.

2326. The method of claim 2296, wherein the defects comprises micro defects or macro defects.

15 2327. The method of claim 2296, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

2328. The method of claim 2296, wherein the defects comprise copper contamination on  
a back side of the specimen.

20

2329. The method of claim 2296, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

25

2330. The method of claim 2329, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

2331. The method of claim 2296, further comprising:

5           controlling the illumination system to direct energy toward a bottom surface of the specimen; and

          controlling the detection system to detect energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

10

2332. The method of claim 2331, wherein the defects comprise macro defects.

2333. The method of claim 2296, wherein the measurement device further comprises non-optical components, and wherein controlling the detection system to detect energy  
15       comprises controlling the non-optical components to measure a non-optical characteristic of the specimen.

2334. The method of claim 2296, wherein processing the one or more output signals to determine the first, second, and third properties of the specimen comprises substantially  
20       simultaneously determining the first, second, and third properties of the specimen.

2335. The method of claim 2296, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the  
25       multiple locations substantially simultaneously such that the first, second, and third properties of the specimen at the multiple locations can be determined substantially simultaneously.

2336. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool.

5 2337. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

10 2338. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

15 2339. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, and etch tool, a chemical-mechanical polishing tool, and a thermal tool.

20 2340. The method of claim 2296, further comprising controlling a wafer handler to move the specimen from a process tool to the stage, wherein the wafer handler is coupled to the process tool.

2341. The method of claim 2296, further comprising controlling the stage to move the specimen from the system to a process tool.

25 2342. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.

2343. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

5

2344. The method of claim 2296, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

10

2345. The method of claim 2296, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

15 2346. The method of claim 2296, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

20 2347. The method of claim 2296, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

25 2348. The method of claim 2296, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.



2349. The method of claim 2296, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.
- 5 2350. The method of claim 2349, further comprising controlling the illumination system and controlling the detection system during the process step.
2351. The method of claim 2350, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one  
10 singularity representative of an end of the process step.
2352. The method of claim 2350, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.  
15
2353. The method of claim 2296, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.
- 20 2354. The method of claim 2353, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.
2355. The method of claim 2296, further comprising comparing at least one of the  
25 determined properties of the specimen and determined properties of a plurality of specimens.

2356. The method of claim 2296, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

2357. The method of claim 2356, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

2358. The method of claim 2296, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

2359. The method of claim 2296, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

2360. The method of claim 2296, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2361. The method of claim 2296, further comprising generating a database, wherein the database comprises the determined first, second, and third properties of the specimen, the method further comprising calibrating the measurement device using the database.

2362. The method of claim 2296, further comprising generating a database, wherein the database comprises the determined first, second, and third properties of the specimen, the method further comprising monitoring output signals generated by the measurement device using the database.

2363. The method of claim 2296, further comprising generating a database, wherein the database comprises the determined first, second, and third properties of the specimen, and wherein the database further comprises first, second, and third properties of a plurality of specimens.

5

2364. The method of claim 2363, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.

10 2365. The method of claim 2363, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals generated by the plurality of measurement devices using the database.

15 2366. The method of claim 2296, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

20 2367. The method of claim 2296, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

25

2368. The method of claim 2296, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least

one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

- 5    2369. The method of claim 2296, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.

2370. The method of claim 2296, further comprising altering a parameter of one or more  
10 instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.

2371. The method of claim 2296, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

15

2372. The method of claim 2371, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

2373. The method of claim 2372, further comprising altering a parameter of at least one  
20 of the instruments in response to the relationship.

2374. The method of claim 2296, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the determined properties of the specimen.

25

2375. The method of claim 2296, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor,  
wherein the local processor is coupled to the measurement device;

5 sending the partially processed one or more output signals from the local  
processor to a remote controller computer; and

further processing the partially processed one or more output signals using the  
remote controller computer.

10 2376. The method of claim 2375, wherein at least partially processing the one or more  
output signals comprises determining the first, second, and third properties of the  
specimen.

15 2377. The method of claim 2375, wherein further processing the partially processed one  
or more output signals comprises determining the first, second, and third properties of the  
specimen.

2378. A semiconductor device fabricated by a method, the method comprising:

20 forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a  
measurement device, and wherein the measurement device comprises an  
illumination system and a detection system;

25 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property

10 comprises a thin film characteristic of the specimen.

2379. The device of claim 2378, wherein the illumination system comprises a single energy source.

15 2380. The device of claim 2378, wherein the illumination system comprises more than one energy source.

2381. The device of claim 2378, wherein the detection system comprises a single energy sensitive device.

20

2382. The device of claim 2378, wherein the detection system comprises more than one energy sensitive devices.

2383. The device of claim 2378, wherein the measurement device is selected from the

25 group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field

imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

- 5     2384. The device of claim 2378, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-  
10    imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.
- 15    2385. The device of claim 2378, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
- 20    2386. The device of claim 2378, wherein the defects comprise micro defects and macro defects.
- 25    2387. The device of claim 2378, wherein the defects comprises micro defects or macro defects.
2388. The device of claim 2378, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

2389. The device of claim 2378, wherein the defects comprise copper contamination on a back side of the specimen.

5 2390. The device of claim 2378, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

10 2391. The device of claim 2390, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

2392. The device of claim 2378, further comprising:

15 directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

20

2393. The device of claim 2392, wherein the defects comprise macro defects.

2394. The device of claim 2378, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical  
25 characteristic of the specimen.

2395. The device of claim 2378, wherein the stage and the measurement device are coupled to a process tool.



2396. The device of claim 2378, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.

2397. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals in response to the detected energy; and

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

2398. The method of claim 2397, wherein the illumination system comprises a single energy source.

2399. The method of claim 2397, wherein the illumination system comprises more than  
5 one energy source.

2400. The method of claim 2397, wherein the detection system comprises a single energy sensitive device.

10 2401. The method of claim 2397, wherein the detection system comprises more than one energy sensitive devices.

2402. The method of claim 2397, wherein the measurement device is selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic  
15 reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device,  
20 and a double dark field device.

2403. The method of claim 2397, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical  
25 profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and

dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

2404. The method of claim 2397, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2405. The method of claim 2397, wherein the defects comprise micro defects and macro defects.

2406. The method of claim 2397, wherein the defects comprises micro defects or macro defects.

2407. The method of claim 2397, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

2408. The method of claim 2397, wherein the defects comprise copper contamination on a back side of the specimen.

2409. The method of claim 2397, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

2410. The method of claim 2409, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

2411. The method of claim 2397, further comprising:

directing energy toward a bottom surface of the specimen; and

5

detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

10 2412. The method of claim 2411, wherein the defects comprise macro defects.

2413. The method of claim 2397, wherein the measurement device comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the specimen.

15

2414. The method of claim 2397, wherein the stage and the measurement device are coupled to a process tool.

2415. The method of claim 2397, wherein the stage and the measurement device are  
20 coupled to a process tool, and wherein the process tool is selected from the group consisting of a lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.

2416. A system configured to determine at least three properties of a specimen during  
25 use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

5

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals in response to the detected energy;

10

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

15

a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property, a second property, and a third property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen.

20

2417. The system of claim 2416, wherein the measurement device is selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field

25

device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

2418. The system of claim 2416, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein the first  
and second measurement devices are selected from the group consisting of an optical  
profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic  
ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-  
imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an  
10 ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and  
dark field imaging device, a non-imaging bright field device, a non-imaging dark field  
device, a non-imaging bright field and dark field device, and a double dark field device.

2419. The system of claim 2416, wherein the measurement device further comprises at  
15 least a first measurement device and a second measurement device, and wherein optical  
elements of the first measurement device comprise optical elements of the second  
measurement device.

2420. The system of claim 2416, wherein the defects comprise micro defects and macro  
20 defects.

2421. The system of claim 2416, wherein the defects comprises micro defects or macro  
defects.

25 2422. The system of claim 2416, wherein the thin film characteristic comprises a  
thickness of a copper film, and wherein the defects comprise voids in the copper film.

2423. The system of claim 2416, wherein the defects comprise copper contamination on a back side of the specimen.

5 2424. The system of claim 2416, wherein the remote controller computer is further configured to determine a fourth property of the specimen from the at least partially processed one or more output signals during use, and wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

10 2425. The system of claim 2424, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

15 2426. The system of claim 2416, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

20 2427. The system of claim 2426, wherein the defects comprise macro defects.

2428. The system of claim 2416, wherein the illumination system and the detection system comprise non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the specimen.

25

2429. The system of claim 2416, wherein the remote controller computer is coupled to a process tool.

2430. The system of claim 2416, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from a group consisting of a lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.
- 5 2431. The system of claim 2416, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.
- 10 2432. The system of claim 2416, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.
- 15 2433. The system of claim 2416, wherein the remote controller computer is coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.
- 20 2434. The system of claim 2433, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.
- 25 2435. The system of claim 2434, wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.
2436. The system of claim 2416, wherein the illumination system is further configured to direct energy toward the surface of the specimen during a process step, wherein the



detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first, second, and third properties of the specimen during the process step.

5

2437. The system of claim 2436, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

10

2438. The system of claim 2436, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

15

2439. The system of claim 2416, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

20

2440. The system of claim 2439, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first, second, and third properties of the specimen during said moving.

25

2441. The system of claim 2416, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

5 2442. The system of claim 2416, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

2443. The system of claim 2442, wherein the remote controller computer is further  
10 configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

2444. The system of claim 2416, wherein the remote controller computer is further  
15 configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

2445. The system of claim 2416, wherein the remote controller computer is further  
configured to alter a parameter of one or more instruments coupled to the measurement  
device in response to at least one of the determined properties using a feedback control  
20 technique during use.

2446. The system of claim 2416, wherein the remote controller computer is further  
configured to alter a parameter of one or more instruments coupled to the measurement  
device in response to at least one of the determined properties using a feedforward control  
25 technique during use.

2447. The system of claim 2416, wherein the remote controller computer is further  
configured to generate a database during use, wherein the database comprises the

determined first, second, and third properties of the specimen, and wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

- 5    2448. The system of claim 2416, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first, second, and third properties of the specimen, and wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

10

2449. The system of claim 2416, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first, second, and third properties of the specimen, and wherein the database further comprises first, second, and third properties of a plurality of specimens.

15

2450. The system of claim 2449, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to calibrate the plurality  
20 of measurement devices using the database during use.

20

2451. The system of claim 2449, wherein the first, second, and third properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the remote controller computer is further coupled to the plurality of measurement devices,  
25 and wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

25

2452. The system of claim 2416, wherein the remote controller computer is further coupled to a plurality of measurement devices, wherein each of the plurality of measurement devices is coupled to one of a plurality of process tools.

5 2453. The system of claim 2416, wherein the remote controller computer is coupled to at least one of a plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

10 2454. A method for determining at least three properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

15

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

20

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property, a second property, and a third property of the specimen, wherein the first property comprises a flatness measurement of the specimen, wherein the second property comprises a presence of defects on the specimen, and wherein the third property comprises a thin film characteristic of the specimen, comprising:

25

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

5                    sending the partially processed one or more output signals from the local processor to a remote controller computer; and

                    further processing the partially processed one or more output signals using the remote controller computer.

10

2455. The method of claim 2454, wherein the measurement device is selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-imaging scatterometer, a scatterometer, a spectroscopic

15 scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

20 2456. The method of claim 2454, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of an optical profilometer, an interferometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, and a beam profile ellipsometer a non-  
25 imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a bright field imaging device, a dark field imaging device, a bright field and dark field imaging device, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, and a double dark field device.

2457. The method of claim 2454, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2458. The method of claim 2454, wherein the defects comprise micro defects and macro defects.

2459. The method of claim 2454, wherein the defects comprises micro defects or macro defects.

2460. The method of claim 2454, wherein the thin film characteristic comprises a thickness of a copper film, and wherein the defects comprise voids in the copper film.

2461. The method of claim 2454, wherein the defects comprise copper contamination on a back side of the specimen.

2462. The method of claim 2454, further comprising processing the one or more output signals to determine a fourth property of the specimen, wherein the fourth property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

2463. The method of claim 2462, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

2464. The method of claim 2454, further comprising:

directing energy toward a bottom surface of the specimen; and

5 detecting energy propagating from the bottom surface of the specimen, wherein  
the second property further comprises a presence of defects on the bottom surface  
of the specimen.

2465. The method of claim 2464, wherein the defects comprise macro defects.

10 2466. The method of claim 2454, wherein the measurement device comprises non-  
optical components, and wherein detecting energy comprises measuring a non-optical  
characteristic of the specimen.

15 2467. The method of claim 2454, wherein the remote controller computer is coupled to a  
process tool.

2468. The method of claim 2454, wherein the remote controller computer is coupled to a  
process tool, and wherein the process tool is selected from the group consisting of a  
lithography tool, an etch tool, a chemical-mechanical polishing tool, and a thermal tool.  
20

2469. The method of claim 2454, wherein the remote controller computer is coupled to a  
process tool, the method further comprising altering a parameter of one or more  
instruments coupled to the process tool using the remote controller computer in response  
to at least one of the determined properties of the specimen comprises using a feedback  
25 control technique.

2470. The method of claim 2454, wherein the remote controller computer is coupled to a  
process tool, the method further comprising altering a parameter of one or more

instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen comprises using a feedforward control technique.

- 5     2471. The method of claim 2454, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

- 10     2472. The method of claim 2471, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer.

- 15     2473. The method of claim 2472, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

2474. The method of claim 2454, wherein the illumination system and the detection system are coupled to a process chamber of a process tool, the method further comprising performing said directing and said detecting during a process step.

- 20     2475. The method of claim 2474, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

- 25     2476. The method of claim 2474, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.

2477. The method of claim 2454, further comprising:



moving the specimen from a first process chamber to a second process chamber using the stage; and

5 performing said directing and said detecting during said moving the specimen.

2478. The method of claim 2454, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

10

2479. The method of claim 2454, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

15 2480. The method of claim 2479, further comprising generating an output signal using the remote controller computer if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

20 2481. The method of claim 2454, wherein the remote controller computer is coupled to the measurement device, the method further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to at least one of the determined properties of the specimen.

25 2482. The method of claim 2454, wherein the remote controller computer is coupled to the measurement device, the method further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control technique.

2483. The method of claim 2454, wherein the remote controller computer is coupled to the measurement device, the method further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller  
5 computer in response to at least one of the determined properties using a feedforward control technique.

2484. The method of claim 2454, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first, second  
10 and third properties of the specimen.

2485. The method of claim 2454, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first, second and third properties of the specimen, the method further comprising calibrating the  
15 measurement device using the remote controller computer.

2486. The method of claim 2454, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first, second and third properties of the specimen, the method further comprising monitoring output  
20 signals generated by the measurement device using the remote controller computer.

2487. The method of claim 2454, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first, second and third properties of the specimen, and wherein the database further comprises first,  
25 second, and third properties of a plurality of specimens.

2488. The method of claim 2487, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method

further comprising calibrating the plurality of measurement devices using the remote controller computer.

2489. The method of claim 2487, wherein the first, second, and third properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals generated by the plurality of measurement devices using the remote controller computer.

2490. The method of claim 2454, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

2491. The method of claim 2490, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to at least one of the determined properties of the specimen.

2492. The method of claim 2490, wherein at least one of the plurality of measurement devices is coupled to one of a plurality of process tools.

2493. The method of claim 2492, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of process tools using the remote controller computer in response to at least one of the determined properties of the specimen.

2494. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

5

an illumination system configured to direct energy toward a surface of the specimen during use; and

10

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use; and

15

a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen.

20

2495. The system of claim 2494, wherein the stage is further configured to move laterally during use.

2496. The system of claim 2494, wherein the stage is further configured to move rotatably during use.

25

2497. The system of claim 2494, wherein the stage is further configured to move laterally and rotatably during use.

2498. The system of claim 2494, wherein the illumination system comprises a single energy source.

5 2499. The system of claim 2494, wherein the illumination system comprises more than one energy source.

2500. The system of claim 2494, wherein the detection system comprises a single energy sensitive device.

10 2501. The system of claim 2494, wherein the detection system comprises more than one energy sensitive devices.

2502. The system of claim 2494, wherein the measurement device further comprises a coherence probe microscope.

15

2503. The system of claim 2494, wherein the measurement device further comprises an interferometer.

20 2504. The system of claim 2494, wherein the measurement device further comprises an optical profilometer.

2505. The system of claim 2494, wherein the measurement device further comprises a spectroscopic reflectometer.

25 2506. The system of claim 2494, wherein the measurement device further comprises a spectroscopic ellipsometer.

2507. The system of claim 2494, wherein the measurement device further comprises a dual beam spectrophotometer.
- 5 2508. The system of claim 2494, wherein the measurement device further comprises a beam profile ellipsometer.
2509. The system of claim 2494, wherein the measurement device further comprises a non-imaging scatterometer.
- 10 2510. The system of claim 2494, wherein the measurement device further comprises a scatterometer.
2511. The system of claim 2494, wherein the measurement device further comprises a spectroscopic scatterometer.
- 15 2512. The system of claim 2494, wherein the measurement device further comprises a reflectometer.
2513. The system of claim 2494, wherein the measurement device further comprises a bright field imaging device.
- 20 2514. The system of claim 2494, wherein the measurement device further comprises a dark field imaging device.
- 25 2515. The system of claim 2494, wherein the measurement device further comprises a bright field and dark field imaging device.

2516. The system of claim 2494, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.
- 10 2517. The system of claim 2494, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.
- 15 2518. The system of claim 2494, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be  
20 determined at the multiple locations substantially simultaneously.
2519. The system of claim 2494, wherein the system is coupled to a process tool.
2520. The system of claim 2494, wherein the system is coupled to a process tool, and  
25 wherein the system is disposed within the process tool.
2521. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

2522. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

5

2523. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.

10 2524. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.

15 2525. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

20 2526. The system of claim 2494, wherein the system is coupled to a lithography tool, wherein the system is configured to determine the flatness measurement of the specimen prior to an exposure step of the lithography process, and wherein the system is configured to determine the overlay misregistration subsequent to the exposure step of the lithography process.

25 2527. The system of claim 2494, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.



2528. The system of claim 2494, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

5

2529. The system of claim 2494, wherein the system is coupled to a process tool, and wherein the process tool comprises a lithography tool.

2530. The system of claim 2494, wherein the system further comprises a measurement  
10 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

2531. The system of claim 2494, wherein the system further comprises a measurement  
15 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

2532. The system of claim 2494, wherein the system further comprises a measurement  
20 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

2533. The system of claim 2494, wherein the system further comprises a measurement  
25 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

2534. The system of claim 2494, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

- 5    2535. The system of claim 2534, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

2536. The system of claim 2535, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises  
10    at least one singularity representative of an end of the process step.

2537. The system of claim 2535, wherein the processor is further coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ  
15    control technique during use.

2538. The system of claim 2494, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during  
20    use.

2539. The system of claim 2538, wherein the system is further configured to determine at least one of the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

25

2540. The system of claim 2494, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

2541. The system of claim 2494, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

5

2542. The system of claim 2541, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

10 2543. The system of claim 2494, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

15 2544. The system of claim 2494, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

20 2545. The system of claim 2494, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

25 2546. The system of claim 2494, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to calibrate the measurement device using the database during use.

2547. The system of claim 2494, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

5

2548. The system of claim 2494, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens determined using a plurality of measurement

10

devices.

2549. The system of claim 2548, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

15

2550. The system of claim 2548, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

20

2551. The system of claim 2494, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

25

2552. The system of claim 2494, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is

further configured to calibrate the system and at least the one additional system during use.

5 2553. The system of claim 2494, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

10

2554. The system of claim 2494, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

15

2555. The system of claim 2494, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

20

2556. The system of claim 2494, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

25 2557. The system of claim 2556, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

2558. The system of claim 2557, wherein the processor is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

2559. The system of claim 2494, wherein the processor is further coupled to a plurality of measurement devices, and wherein the plurality of measurement devices is coupled to a plurality of process tools.

2560. The system of claim 2494, wherein the processor is further coupled to a plurality of process tools, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

2561. The system of claim 2494, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

2562. The system of claim 2561, wherein the local processor is further configured to determine the first property and the second property of the specimen during use.

2563. The system of claim 2561, wherein the remote controller computer is further configured to determine the first property and the second property of the specimen during use.

2564. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

5 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

10 generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen.

15

2565. The method of claim 2564, further comprising laterally moving the stage during said directing energy and said detecting energy.

20 2566. The method of claim 2564, further comprising rotatably moving the stage during said directing energy and said detecting energy.

2567. The method of claim 2564, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

25

2568. The method of claim 2564, wherein the illumination system comprises a single energy source.

2569. The method of claim 2564, wherein the illumination system comprises more than one energy source.
- 5 2570. The method of claim 2564, wherein the detection system comprises a single energy sensitive device.
2571. The method of claim 2564, wherein the detection system comprises more than one energy sensitive devices.
- 10 2572. The method of claim 2564, wherein the measurement device further comprises a coherence probe microscope.
2573. The method of claim 2564, wherein the measurement device further comprises an interferometer.
- 15 2574. The method of claim 2564, wherein the measurement device further comprises an optical profilometer.
2575. The method of claim 2564, wherein the measurement device further comprises a spectroscopic reflectometer.
- 20 2576. The method of claim 2564, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 25 2577. The method of claim 2564, wherein the measurement device further comprises a dual beam spectrophotometer.



2578. The method of claim 2564, wherein the measurement device further comprises a beam profile ellipsometer.
- 5 2579. The method of claim 2564, wherein the measurement device further comprises a non-imaging scatterometer.
2580. The method of claim 2564, wherein the measurement device further comprises a scatterometer.
- 10 2581. The method of claim 2564, wherein the measurement device further comprises a spectroscopic scatterometer.
2582. The method of claim 2564, wherein the measurement device further comprises a reflectometer.
- 15 2583. The method of claim 2564, wherein the measurement device further comprises a bright field imaging device.
2584. The method of claim 2564, wherein the measurement device further comprises a dark field imaging device.
- 20 2585. The method of claim 2564, wherein the measurement device further comprises a bright field and dark field imaging device.
- 25 2586. The method of claim 2564, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic

reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

5

2587. The method of claim 2564, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10

2588. The method of claim 2564, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

15

2589. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool.

20

2590. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

25

2591. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

2592. The method of claim 2564, wherein the stage and the measurement device are coupled to a lithography tool.

2593. The method of claim 2564, wherein the stage and the measurement device are coupled to a lithography tool, the method further comprising determining the flatness measurement of the specimen prior to an exposure step of the lithography process and determining the overlay misregistration subsequent to the exposure step of the lithography process.

2594. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

2595. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

2596. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

2597. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

2598. The method of claim 2564, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

5

2599. The method of claim 2564, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

10 2600. The method of claim 2564, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

15 2601. The method of claim 2564, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

20 2602. The method of claim 2564, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

25 2603. The method of claim 2564, wherein the stage and the measurement device are disposed within a measurement chamber, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

2604. The method of claim 2603, further comprising performing said directing and said detecting during the process step.

2605. The method of claim 2604, further comprising obtaining a signature  
5 characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

2606. The method of claim 2604, further comprising altering a parameter of one or more instruments coupled to the process tool in response to at least one of the determined  
10 properties using an in situ control technique.

2607. The method of claim 2564, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.  
15

2608. The method of claim 2607, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

20 2609. The method of claim 2564, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

2610. The method of claim 2564, further comprising comparing at least one of the  
25 determined properties of the specimen to a predetermined range for the property.

2611. The method of claim 2610, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

5     2612. The method of claim 2564, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

2613. The method of claim 2564, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

2614. The method of claim 2564, further comprising altering a parameter of one or more  
15 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2615. The method of claim 2564, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen.

20     2616. The method of claim 2564, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the database.

2617. The method of claim 2564, further comprising generating a database, wherein the  
25 database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals of the measurement device using the database.

2618. The method of claim 2564, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

5

2619. The method of claim 2618, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.

10 2620. The method of claim 2618, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the database.

15 2621. The method of claim 2564, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

20 2622. The method of claim 2564, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

25

2623. The method of claim 2564, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one

parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

- 5     2624. The method of claim 2564, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedback control technique.

- 10    2625. The method of claim 2564, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedforward control technique.

- 15    2626. The method of claim 2564, further comprising monitoring a parameter of one or more instruments coupled to the process tool.

2627. The method of claim 2626, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

- 20    2628. The method of claim 2627, further comprising altering a parameter of at least one of the instruments in response to the relationship.

- 25    2629. The method of claim 2564, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the determined properties of the specimen.

2630. The method of claim 2564, wherein processing the one or more output signals comprises:



at least partially processing the one or more output signals using a local processor,  
wherein the local processor is coupled to the measurement device;

5        sending the partially processed one or more output signals from the local  
processor to a remote controller computer; and

      further processing the partially processed one or more output signals using the  
remote controller computer.

10    2631. The method of claim 2630, wherein at least partially processing the one or more  
output signals comprises determining the first and second properties of the specimen.

      2632. The method of claim 2630, wherein further processing the partially processed one  
or more output signals comprises determining the first and second properties of the  
15    specimen.

      2633. A computer-implemented method for controlling a system configured to  
determine at least two properties of a specimen during use, wherein the system comprises  
a measurement device, the method comprising:

20        controlling the measurement device, wherein the measurement device comprises  
an illumination system and a detection system, and wherein the measurement  
device is coupled to a stage, comprising:

25                controlling the illumination system to direct energy toward a surface of the  
specimen;

controlling the detection system to detect energy propagating from the surface of the specimen; and

generating one or more output signals responsive to the detected energy;  
and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen.

2634. The method of claim 2633, further comprising controlling the stage, wherein the stage is configured to support the specimen.

2635. The method of claim 2633, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.

2636. The method of claim 2633, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.

2637. The method of claim 2633, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.

2638. The method of claim 2633, wherein the illumination system comprises a single energy source.

2639. The method of claim 2633, wherein the illumination system comprises more than one energy source.

2640. The method of claim 2633, wherein the detection system comprises a single energy sensitive device.

5 2641. The method of claim 2633, wherein the detection system comprises more than one energy sensitive devices.

2642. The method of claim 2633, wherein the measurement device further comprises a coherence probe microscope.

10

2643. The method of claim 2633, wherein the measurement device further comprises an interferometer.

15

2644. The method of claim 2633, wherein the measurement device further comprises an optical profilometer.

2645. The method of claim 2633, wherein the measurement device further comprises a spectroscopic reflectometer.

20

2646. The method of claim 2633, wherein the measurement device further comprises a spectroscopic ellipsometer.

2647. The method of claim 2633, wherein the measurement device further comprises a dual beam spectrophotometer.

25

2648. The method of claim 2633, wherein the measurement device further comprises a beam profile ellipsometer.

2649. The method of claim 2633, wherein the measurement device further comprises a non-imaging scatterometer.

5 2650. The method of claim 2633, wherein the measurement device further comprises a scatterometer.

2651. The method of claim 2633, wherein the measurement device further comprises a spectroscopic scatterometer.

10 2652. The method of claim 2633, wherein the measurement device further comprises a reflectometer.

2653. The method of claim 2633, wherein the measurement device further comprises a bright field imaging device.

15 2654. The method of claim 2633, wherein the measurement device further comprises a dark field imaging device.

20 2655. The method of claim 2633, wherein the measurement device further comprises a bright field and dark field imaging device.

2656. The method of claim 2633, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence  
25 probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic

scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2657. The method of claim 2633, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2658. The method of claim 2633, further comprising controlling the illumination system  
10 to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially  
simultaneously.

15

2659. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool.

2660. The method of claim 2633, wherein the stage and the measurement device are  
20 coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

2661. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed  
25 within the process tool.

2662. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool comprises a lithography tool.

2663. The method of claim 2633, wherein the system is coupled to a lithography tool, the method further comprising controlling the system to determine the flatness measurement of the specimen prior to an exposure step of the lithography process and  
5 controlling the system to determine the overlay misregistration subsequent to the exposure step of the lithography process.

2664. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to  
10 move the specimen from the process tool to the stage, and wherein the wafer handler is coupled to the process tool.

2665. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the  
15 specimen from the system to the process tool.

2666. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties  
20 of the specimen can be determined while the specimen is waiting between process steps.

2667. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the  
25 support device is substantially parallel to an upper surface of the stage.

2668. The method of claim 2633, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured

to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

2669. The method of claim 2633, wherein the stage and the measurement device are  
5 disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

2670. The method of claim 2633, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is  
10 disposed within a process tool.

2671. The method of claim 2633, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.  
15

2672. The method of claim 2633, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

20 2673. The method of claim 2633, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

2674. The method of claim 2673, further comprising controlling the illumination system  
25 and controlling the detection system during the process step to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

2675. The method of claim 2673, further comprising controlling the illumination system and controlling the detection system during the process step to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

5

2676. The method of claim 2633, further comprising controlling the stage to move the specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

10 2677. The method of claim 2676, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first process chamber to the second process chamber.

15 2678. The method of claim 2633, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

2679. The method of claim 2633, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

20

2680. The method of claim 2679, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.

25 2681. The method of claim 2633, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.



2682. The method of claim 2633, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

5 2683. The method of claim 2633, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2684. The method of claim 2633, further comprising generating a database, wherein the  
10 database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the database.

2685. The method of claim 2633, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the  
15 method further comprising monitoring output signals of the measurement device using the database.

2686. The method of claim 2633, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and  
20 wherein the database further comprises determined first and second properties of a plurality of specimens.

2687. The method of claim 2686, wherein the determined first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the  
25 method further comprising calibrating the plurality of measurement devices using the database.

2688. The method of claim 2686, wherein the determined first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the database.

5

2689. The method of claim 2633, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

10

2690. The method of claim 2633, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

15

2691. The method of claim 2633, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

20

2692. The method of claim 2633, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedback control technique.

25

2693. The method of claim 2633, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedforward control technique.

- 5 2694. The method of claim 2633, further comprising monitoring a parameter of one or more instruments coupled to a process tool.

2695. The method of claim 2694, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

10

2696. The method of claim 2695, further comprising altering a parameter of at least one of the instruments in response to the relationship.

2697. The method of claim 2633, further comprising altering a parameter of one or more  
15 instruments coupled to a plurality of process tools in response to at least one of the determined properties of the specimen.

2698. The method of claim 2633, wherein processing the one or more output signals comprises:

20

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

- 25 sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

2699. The method of claim 2698, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

5 2700. The method of claim 2698, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

2701. A semiconductor device fabricated by a method, the method comprising:

10

forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an

15

illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection

20

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises overlay  
misregistration of the specimen, and wherein the second property comprises a  
flatness measurement of the specimen.

25

2702. The device of claim 2701, wherein the illumination system comprises a single energy source.

2703. The device of claim 2701, wherein the illumination system comprises more than  
5 one energy source.

2704. The device of claim 2701, wherein the detection system comprises a single energy sensitive device.

10 2705. The device of claim 2701, wherein the detection system comprises more than one energy sensitive devices.

2706. The device of claim 2701, wherein the measurement device is selected from the group consisting of a coherence probe microscope, an interferometer, an optical  
15 profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

20 2707. The device of claim 2701, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam  
25 profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2708. The device of claim 2701, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

5

2709. The device of claim 2701, wherein the stage and the measurement device are coupled to a process tool.

2710. The device of claim 2701, wherein the stage and the measurement device are  
10 coupled to a process tool, and wherein the process tool comprises a lithography tool.

2711. The device of claim 2701, wherein the stage and the measurement device are coupled to a lithography tool, the method further comprising determining the flatness measurement of the specimen prior to an exposure step of the lithography process and  
15 determining the overlay misregistration subsequent to the exposure step of the lithography process.

2712. A method for fabricating a semiconductor device, comprising:

20 forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

25

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen.

10

2713. The method of claim 2712, wherein the illumination system comprises a single energy source.

2714. The method of claim 2712, wherein the illumination system comprises more than  
15 one energy source.

2715. The method of claim 2712, wherein the detection system comprises a single energy sensitive device.

20 2716. The method of claim 2712, wherein the detection system comprises more than one energy sensitive devices.

2717. The method of claim 2712, wherein the measurement device is selected from the group consisting of a coherence probe microscope, an interferometer, an optical  
25 profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2718. The method of claim 2712, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence  
5 probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

10

2719. The method of claim 2712, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

15

2720. The method of claim 2712, wherein the stage and the measurement device are coupled to a process tool.

2721. The method of claim 2712, wherein the stage and the measurement device are  
20 coupled to a process tool, and wherein the process tool comprises a lithography tool.

2722. The method of claim 2712, wherein the stage and the measurement device are coupled to a lithography tool, the method further comprising determining the flatness measurement of the specimen prior to an exposure step of the lithography process and  
25 determining the overlay misregistration subsequent to the exposure step of the lithography process.



2723. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use;

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen.

2724. The system of claim 2723, wherein the measurement device is selected from the group consisting of a coherence probe microscope, an interferometer, an optical

profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

5

2725. The system of claim 2723, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic  
10 reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

15 2726. The system of claim 2723, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

20 2727. The system of claim 2723, wherein the remote controller computer is further coupled to a process tool.

2728. The system of claim 2723, wherein the remote controller computer is further coupled to a process tool, and wherein the process tool comprises a lithography tool.

25

2729. The system of claim 2723, wherein the system is coupled to a lithography tool, wherein the system is configured to determine the flatness measurement of the specimen prior to an exposure step of the lithography process, and wherein the system is configured

to determine the overlay misregistration subsequent to the exposure step of the lithography process.

5 2730. The system of claim 2723, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

10 2731. The system of claim 2723, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

15 2732. The system of claim 2723, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

20 2733. The system of claim 2732, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

25 2734. The system of claim 2733, wherein the remote controller computer is further configured to alter a parameter of one or more instruments in response to the relationship during use.

2735. The system of claim 2723, wherein the illumination system is further configured to direct energy toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is  
5 further configured to determine the first and second properties of the specimen during the process step.

2736. The system of claim 2735, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein  
10 the signature comprises at least one singularity representative of an end of the process step.

2737. The system of claim 2735, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in  
15 response to at least one of the determined properties using an in situ control technique during use.

2738. The system of claim 2723, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to  
20 move the specimen from the first process chamber to the second process chamber during use.

2739. The system of claim 2723, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the  
25 detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

2740. The system of claim 2723, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

5

2741. The system of claim 2723, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

10 2742. The system of claim 2741, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

15 2743. The system of claim 2723, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

20 2744. The system of claim 2723, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

25 2745. The system of claim 2723, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

2746. The system of claim 2723, wherein the remote controller computer is further configured to generate a database during use, and wherein the database comprises the determined first and second properties of the specimen.

5 2747. The system of claim 2723, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

10

2748. The system of claim 2723, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to monitor output signals generated by measurement  
15 device using the database during use.

15

2749. The system of claim 2723, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further  
20 comprises first and second properties of a plurality of specimens.

20

2750. The system of claim 2749, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the remote controller computer is further coupled to the plurality of measurement devices,  
25 and wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

25

2751. The system of claim 2749, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

2752. The system of claim 2723, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein the plurality of measurement devices is coupled to at least one of a plurality of process tools.

2753. The system of claim 2723, wherein the remote controller computer is further coupled to a plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the plurality of process tools during use.

2754. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises overlay misregistration of the specimen, and wherein the second property comprises a flatness measurement of the specimen, comprising:

5

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

10

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

15

2755. The method of claim 2754, wherein the measurement device is selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

20

25

2756. The method of claim 2754, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a coherence probe microscope, an interferometer, an optical profilometer, a spectroscopic reflectometer, a spectroscopic ellipsometer, a dual beam spectrophotometer, a beam profile ellipsometer, a non-imaging scatterometer, a scatterometer, a spectroscopic



scatterometer, a reflectometer, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2757. The method of claim 2754, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2758. The method of claim 2754, wherein the remote controller computer is further  
10 coupled to a process tool.

2759. The method of claim 2754, wherein the remote controller computer is further coupled to a process tool, and wherein the process tool is comprises a lithography tool.

15 2760. The method of claim 2754, wherein the stage and the measurement device are coupled to a lithography tool, the method further comprising determining the flatness measurement of the specimen prior to an exposure step of the lithography process and determining the overlay misregistration subsequent to the exposure step of the lithography process.

20 2761. The method of claim 2754, wherein the remote controller computer is further coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback  
25 control technique.

2762. The method of claim 2754, wherein the remote controller computer is further coupled to a process tool, the method further comprising altering a parameter of one or

more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedforward control technique.

- 5     2763. The method of claim 2754, wherein the remote controller computer is further coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

- 10    2764. The method of claim 2763, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer.

- 15    2765. The method of claim 2764, further comprising altering a parameter of one or more instruments coupled to the process tool in response to the relationship using the remote controller computer.

- 20    2766. The method of claim 2754, wherein the illumination system and the detection system are coupled to a process chamber of a process tool, the method further comprising performing said directing and said detecting during a process step.

2767. The method of claim 2766, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

- 25    2768. The method of claim 2766, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.

2769. The method of claim 2754, further comprising:

moving the specimen from a first process chamber to a second process chamber  
using the stage; and

5

performing said directing and said detecting during said moving the specimen.

2770. The method of claim 2754, further comprising comparing at least one of the  
determined properties of the specimen and determined properties of a plurality of  
specimens using the remote controller computer.

10

2771. The method of claim 2754, further comprising comparing at least one of the  
determined properties of the specimen to a predetermined range for the property using the  
remote controller computer.

15

2772. The method of claim 2771, further comprising generating an output signal using  
the remote controller computer if at least one of the determined properties of the  
specimen is outside of the predetermined range for the property.

20 2773. The method of claim 2754, further comprising altering a sampling frequency of  
the measurement device in response to at least one of the determined properties of the  
specimen.

2774. The method of claim 2754, further comprising altering a parameter of one or more  
instruments coupled to the measurement device using the remote controller computer in  
response to at least one of the determined properties using a feedback control technique.

25

2775. The method of claim 2754, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedforward control technique.

5

2776. The method of claim 2754, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the remote controller computer and the database.

10

2777. The method of claim 2754, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring the measurement device using the remote controller computer and the database.

15

2778. The method of claim 2754, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

20

2779. The method of claim 2778, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the remote controller computer and the database.

25

2780. The method of claim 2778, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further

comprising monitoring output signals of the plurality of measurement devices using the remote controller computer and the database.

2781. The method of claim 2754, further comprising sending the at least partially  
5 processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

2782. The method of claim 2781, wherein at least one of the plurality of measurement  
10 devices is coupled to a process tool.

2783. The method of claim 2782, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen.

15 2784. A system configured to determine at least two properties of a specimen during use, comprising:

20 a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

25 an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use,

wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use; and

5 a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises a characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on the specimen.

10 2785. The system of claim 2784, wherein the stage is further configured to move laterally during use.

2786. The system of claim 2784, wherein the stage is further configured to move rotatably during use.

15 2787. The system of claim 2784, wherein the stage is further configured to move laterally and rotatably during use.

20 2788. The system of claim 2784, wherein the illumination system comprises a single energy source.

2789. The system of claim 2784, wherein the illumination system comprises more than one energy source.

25 2790. The system of claim 2784, wherein the detection system comprises a single energy sensitive device.

2791. The system of claim 2784, wherein the detection system comprises more than one energy sensitive devices.
2792. The system of claim 2784, wherein the measurement device further comprises a modulated optical reflectometer.
2793. The system of claim 2784, wherein the measurement device further comprises an X-ray reflectance device.
2794. The system of claim 2784, wherein the measurement device further comprises an eddy current device.
2795. The system of claim 2784, wherein the measurement device further comprises a photo-acoustic device.
2796. The system of claim 2784, wherein the measurement device further comprises a spectroscopic ellipsometer.
2797. The system of claim 2784, wherein the measurement device further comprises a spectroscopic reflectometer.
2798. The system of claim 2784, wherein the measurement device further comprises a dual beam spectrophotometer.
2799. The system of claim 2784, wherein the measurement device further comprises a non-imaging scatterometer.

2800. The system of claim 2784, wherein the measurement device further comprises a scatterometer.

2801. The system of claim 2784, wherein the measurement device further comprises a spectroscopic scatterometer.

2802. The system of claim 2784, wherein the measurement device further comprises a reflectometer.

2803. The system of claim 2784, wherein the measurement device further comprises an ellipsometer.

2804. The system of claim 2784, wherein the measurement device further comprises a non-imaging bright field device.

2805. The system of claim 2784, wherein the measurement device further comprises a non-imaging dark field device.

2806. The system of claim 2784, wherein the measurement device further comprises a non-imaging bright field and dark field device.

2807. The system of claim 2784, wherein the measurement device further comprises a bright field imaging device.

2808. The system of claim 2784, wherein the measurement device further comprises a dark field imaging device.



2809. The system of claim 2784, wherein the measurement device further comprises a bright field and dark field imaging device.

2810. The system of claim 2784, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2811. The system of claim 2784, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

2812. The system of claim 2784, wherein the measurement device further comprises non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the specimen.

2813. The system of claim 2784, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a concentration of ions in the implanted region, a depth of the implanted region, and a distribution profile of the implanted region.

2814. The system of claim 2784, wherein the defects comprise micro defects and macro defects.

2815. The system of claim 2784, wherein the defects comprises micro defects or macro  
5 defects.

2816. The system of claim 2784, wherein the illumination system is further configured to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom  
10 surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

2817. The system of claim 2816, wherein the defects comprise macro defects.

15 2818. The system of claim 2784, wherein the system is further configured to determine at least the two properties of the specimen substantially simultaneously during use.

2819. The system of claim 2784, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially  
20 simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

25 2820. The system of claim 2784, wherein the system is coupled to a process tool.

2821. The system of claim 2784, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

2822. The system of claim 2784, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

5 2823. The system of claim 2784, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

2824. The system of claim 2784, wherein the system is coupled to a process tool, and  
10 wherein the stage is configured to move the specimen from the system to the process tool during use.

2825. The system of claim 2784, wherein the system is coupled to a process tool, and wherein the stage is further configured to move the specimen to a process chamber of the  
15 process tool during use.

2826. The system of claim 2784, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the specimen while the specimen is waiting between process steps.

20

2827. The system of claim 2784, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

25

2828. The system of claim 2784, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen

during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

2829. The system of claim 2784, wherein the system is coupled to a process tool, and  
5 wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

2830. The system of claim 2784, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the  
10 measurement chamber, and wherein the measurement chamber is coupled to a process tool.

2831. The system of claim 2784, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the  
15 measurement chamber, and wherein the measurement chamber is disposed within a process tool.

2832. The system of claim 2784, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the  
20 measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

2833. The system of claim 2784, wherein the system further comprises a measurement chamber, wherein the stage and the measurement device are disposed within the  
25 measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

2834. The system of claim 2784, wherein a process tool comprises a process chamber, wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

5 2835. The system of claim 2834, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

2836. The system of claim 2835, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises  
10 at least one singularity representative of an end of the process step.

2837. The system of claim 2835, wherein the processor is further coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ  
15 control technique during use.

2838. The system of claim 2784, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during  
20 use.

2839. The system of claim 2838, wherein the system is further configured to determine at least the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.  
25

2840. The system of claim 2784, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

2841. The system of claim 2784, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

5

2842. The system of claim 2841, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

10 2843. The system of claim 2784, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

15 2844. The system of claim 2784, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

20 2845. The system of claim 2784, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

25 2846. The system of claim 2784, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen.

2847. The system of claim 2784, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second

properties of the specimen, and wherein the processor is further configured to calibrate the measurement device using the database during use.

2848. The system of claim 2784, wherein the processor is further configured to generate  
5 a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

2849. The system of claim 2784, wherein the processor is further configured to generate  
10 a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

2850. The system of claim 2849, wherein the first and second properties of the plurality  
15 of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

20 2851. The system of claim 2849, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

25

2852. The system of claim 2784, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration

standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

5 2853. The system of claim 2784, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

10 2854. The system of claim 2784, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on  
15 the specimen to reduce within wafer variation of at least one of the determined properties.

2855. The system of claim 2784, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined  
20 properties using a feedback control technique during use.

2856. The system of claim 2784, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined  
25 properties using a feedforward control technique during use.



2857. The system of claim 2784, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

5 2858. The system of claim 2857, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

2859. The system of claim 2858, wherein the processor is further configured to alter a  
10 parameter of one or more instruments in response to the relationship during use.

2860. The system of claim 2784, wherein the processor is further coupled to a plurality of measurement devices, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of  
15 measurement devices during use.

2861. The system of claim 2784, wherein the processor is further coupled to a plurality of measurement devices, and wherein at least one of the plurality of measurement devices is coupled to at least one of a plurality of process tools.  
20

2862. The system of claim 2861, wherein the processor is further coupled to at least one of the plurality of process tools, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.  
25

2863. The system of claim 2784, wherein the processor comprises a local processor coupled to the measurement device and a remote controller computer coupled to the local processor, wherein the local processor is configured to at least partially process the one or

more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

2864. The system of claim 2863, wherein the local processor is further configured to  
5 determine the first property and the second property of the specimen during use.

2865. The system of claim 2863, wherein the remote controller computer is further  
configured to determine the first property and the second property of the specimen during  
use.  
10

2866. A method for determining at least two properties of a specimen, comprising:  
  
disposing the specimen upon a stage, wherein the stage is coupled to a  
measurement device, and wherein the measurement device comprises an  
15 illumination system and a detection system;  
  
directing energy toward a surface of the specimen using the illumination system;  
  
detecting energy propagating from the surface of the specimen using the detection  
20 system;  
  
generating one or more output signals responsive to the detected energy; and  
  
processing the one or more output signals to determine a first property and a  
25 second property of the specimen, wherein the first property comprises a  
characteristic of an implanted region of the specimen, and wherein the second  
property comprises a presence of defects on the specimen.

2867. The method of claim 2866, further comprising laterally moving the stage during said directing energy and said detecting energy.

2868. The method of claim 2866, further comprising rotatably moving the stage during  
5 said directing energy and said detecting energy.

2869. The method of claim 2866, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

10 2870. The method of claim 2866, wherein the illumination system comprises a single energy source.

2871. The method of claim 2866, wherein the illumination system comprises more than one energy source.

15

2872. The method of claim 2866, wherein the detection system comprises a single energy sensitive device.

2873. The method of claim 2866, wherein the detection system comprises more than one  
20 energy sensitive devices.

2874. The method of claim 2866, wherein the measurement device further comprises a modulated optical reflectometer.

25 2875. The method of claim 2866, wherein the measurement device further comprises an X-ray reflectance device.

2876. The method of claim 2866, wherein the measurement device further comprises an eddy current device.

5 2877. The method of claim 2866, wherein the measurement device further comprises a photo-acoustic device.

2878. The method of claim 2866, wherein the measurement device further comprises a spectroscopic ellipsometer.

10 2879. The method of claim 2866, wherein the measurement device further comprises a spectroscopic reflectometer.

2880. The method of claim 2866, wherein the measurement device further comprises a dual beam spectrophotometer.

15 2881. The method of claim 2866, wherein the measurement device further comprises a non-imaging scatterometer.

20 2882. The method of claim 2866, wherein the measurement device further comprises a scatterometer.

2883. The method of claim 2866, wherein the measurement device further comprises a spectroscopic scatterometer.

25 2884. The method of claim 2866, wherein the measurement device further comprises a reflectometer.

2885. The method of claim 2866, wherein the measurement device further comprises an ellipsometer.

2886. The method of claim 2866, wherein the measurement device further comprises a  
5 non-imaging bright field device.

2887. The method of claim 2866, wherein the measurement device further comprises a non-imaging dark field device.

10 2888. The method of claim 2866, wherein the measurement device further comprises a non-imaging bright field and dark field device.

2889. The method of claim 2866, wherein the measurement device further comprises a bright field imaging device.

15

2890. The method of claim 2866, wherein the measurement device further comprises a dark field imaging device.

2891. The method of claim 2866, wherein the measurement device further comprises a  
20 bright field and dark field imaging device.

2892. The method of claim 2866, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated  
25 optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-

imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

5     2893. The method of claim 2866, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10    2894. The method of claim 2866, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the specimen.

15    2895. The method of claim 2866, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a concentration of ions in the implanted region, a depth of ions in the implanted region, and a distribution profile of the implanted region.

20    2896. The method of claim 2866, wherein the defects comprise micro defects and macro defects.

2897. The method of claim 2866, wherein the defects comprises micro defects or macro defects.

25    2898. The method of claim 2866, further comprising:

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

5    2899. The method of claim 2898, wherein the defects comprise macro defects.

2900. The method of claim 2866, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

10

2901. The method of claim 2866, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple  
15    locations substantially simultaneously.

2902. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool.

20    2903. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

2904. The method of claim 2866, wherein the stage and the measurement device are  
25    coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

2905. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

5     2906. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

10    2907. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

15    2908. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

20    2909. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

25    2910. The method of claim 2866, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.



2911. The method of claim 2866, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.
- 5 2912. The method of claim 2866, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.
2913. The method of claim 2866, wherein the stage and the measurement device are  
10 disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.
2914. The method of claim 2866, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is  
15 arranged vertically proximate to a process chamber of a process tool.
2915. The method of claim 2866, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the  
20 specimen during a process step.
2916. The method of claim 2915, further comprising performing said directing and said detecting during the process step.
- 25 2917. The method of claim 2916, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

2918. The method of claim 2916, further comprising altering a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

- 5     2919. The method of claim 2866, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

2920. The method of claim 2919, further comprising performing said directing and said  
10     detecting during said moving the specimen from the first process chamber to the second process chamber.

2921. The method of claim 2866, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of  
15     specimens.

2922. The method of claim 2866, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

20     2923. The method of claim 2922, further comprising generating an output signal if at least one of the determined properties of the specimen are outside of the predetermined range for the property.

2924. The method of claim 2866, further comprising altering a sampling frequency of  
25     the measurement device in response to at least one of the determined properties of the specimen.

2925. The method of claim 2866, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

- 5 2926. The method of claim 2866, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

2927. The method of claim 2866, further comprising generating a database, wherein the  
10 database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the database.

2928. The method of claim 2866, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the  
15 method further comprising monitoring output signals of the measurement device using the database.

2929. The method of claim 2866, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and  
20 wherein the database further comprises first and second properties of a plurality of specimens.

2930. The method of claim 2929, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further  
25 comprising calibrating the plurality of measurement devices using the database.

2931. The method of claim 2929, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further

comprising monitoring output signals of the plurality of measurement devices using the database.

5 2932. The method of claim 2866, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

10 2933. The method of claim 2866, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

15 2934. The method of claim 2866, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen at the more than one position on the  
20 specimen to reduce within wafer variation of at least one of the determined properties.

2935. The method of claim 2866, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedback control technique.

25

2936. The method of claim 2866, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedforward control technique.

2937. The method of claim 2866, further comprising monitoring a parameter of one or more instruments coupled to the process tool.

- 5     2938. The method of claim 2937, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.

2939. The method of claim 2938, further comprising altering the parameter of the instrument in response to the relationship.

10

2940. The method of claim 2866, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to at least one of the determined properties.

- 15     2941. The method of claim 2866, wherein processing the one or more output signals comprises:

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

20

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

25     further processing the partially processed one or more output signals using the remote controller computer.

2942. The method of claim 2941, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

2943. The method of claim 2941, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

5

2944. A computer-implemented method for controlling a system configured to determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:

10           controlling the measurement device, wherein the measurement device comprises an illumination system and a detection system, and wherein the measurement device is coupled to a stage, comprising:

15                       controlling the illumination system to direct energy toward a surface of the specimen;

                          controlling the detection system to detect energy propagating from the surface of the specimen; and

20                       generating one or more output signals responsive to the detected energy; and

                          processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a  
25                       characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on the specimen.

2945. The method of claim 2944, further comprising controlling the stage, wherein the stage is configured to support the specimen.
- 5 2946. The method of claim 2944, further comprising controlling the stage to laterally move the stage during said directing energy and said detecting energy.
2947. The method of claim 2944, further comprising controlling the stage to rotatably move the stage during said directing energy and said detecting energy.
- 10 2948. The method of claim 2944, further comprising controlling the stage to laterally and rotatably move the stage during said directing energy and said detecting energy.
2949. The method of claim 2944, wherein the illumination system comprises a single energy source.
- 15 2950. The method of claim 2944, wherein the illumination system comprises more than one energy source.
2951. The method of claim 2944, wherein the detection system comprises a single energy sensitive device.
- 20 2952. The method of claim 2944, wherein the detection system comprises more than one energy sensitive devices.
- 25 2953. The method of claim 2944, wherein the measurement device further comprises a modulated optical reflectometer.

2954. The method of claim 2944, wherein the measurement device further comprises an X-ray reflectance device.

5 2955. The method of claim 2944, wherein the measurement device further comprises an eddy current device.

2956. The method of claim 2944, wherein the measurement device further comprises a photo-acoustic device.

10 2957. The method of claim 2944, wherein the measurement device further comprises a spectroscopic ellipsometer.

2958. The method of claim 2944, wherein the measurement device further comprises a spectroscopic reflectometer.

15 2959. The method of claim 2944, wherein the measurement device further comprises a dual beam spectrophotometer.

20 2960. The method of claim 2944, wherein the measurement device further comprises a non-imaging scatterometer.

2961. The method of claim 2944, wherein the measurement device further comprises a scatterometer.

25 2962. The method of claim 2944, wherein the measurement device further comprises a spectroscopic scatterometer.



2963. The method of claim 2944, wherein the measurement device further comprises a reflectometer.

2964. The method of claim 2944, wherein the measurement device further comprises an  
5 ellipsometer.

2965. The method of claim 2944, wherein the measurement device further comprises a non-imaging bright field device.

10 2966. The method of claim 2944, wherein the measurement device further comprises a non-imaging dark field device.

2967. The method of claim 2944, wherein the measurement device further comprises a non-imaging bright field and dark field device.

15

2968. The method of claim 2944, wherein the measurement device further comprises a bright field imaging device.

2969. The method of claim 2944, wherein the measurement device further comprises a  
20 dark field imaging device.

2970. The method of claim 2944, wherein the measurement device further comprises a bright field and dark field imaging device.

25 2971. The method of claim 2944, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-

acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field  
5 imaging device, a dark field imaging device, and a bright field and dark field imaging device.

2972. The method of claim 2944, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical  
10 elements of the first measurement device comprise optical elements of the second measurement device.

2973. The method of claim 2944, wherein the measurement device further comprises non-optical components, and wherein controlling the detection system to detect energy  
15 comprises controlling the non-optical components to measure a non-optical characteristic of the specimen.

2974. The method of claim 2944, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a  
20 concentration of ions in the implanted region, a depth of the implanted region, and a distribution profile of the implanted region.

2975. The method of claim 2944, wherein the defects comprise micro defects and macro defects.  
25

2976. The method of claim 2944, wherein the defects comprises micro defects or macro defects.

2977. The method of claim 2944, further comprising:

controlling the illumination system to direct energy toward a bottom surface of the specimen; and

5

controlling the detection system to detect energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

10 2978. The method of claim 2977, wherein the defects comprise macro defects.

2979. The method of claim 2944, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

15

2980. The method of claim 2944, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two  
20 properties of the specimen can be determined at the multiple locations substantially simultaneously.

2981. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool.

25

2982. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

2983. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

5

2984. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

10 2985. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is coupled to the process tool.

15 2986. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.

20 2987. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.

25 2988. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

2989. The method of claim 2944, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

5

2990. The method of claim 2944, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

10 2991. The method of claim 2944, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

15 2992. The method of claim 2944, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

20 2993. The method of claim 2944, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

25 2994. The method of claim 2944, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

2995. The method of claim 2994, further comprising controlling the illumination system and controlling the detection system during the process step.

2996. The method of claim 2994, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

- 5     2997. The method of claim 2994, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

2998. The method of claim 2944, further comprising controlling the stage to move the  
10     specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

2999. The method of claim 2998, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first  
15     process chamber to the second process chamber.

3000. The method of claim 2944, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.  
20

3001. The method of claim 2944, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

3002. The method of claim 3001, further comprising generating an output signal if at  
25     least one of the determined properties of the specimen are outside of the predetermined range for the property.

3003. The method of claim 2944, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

5 3004. The method of claim 2944, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

3005. The method of claim 2944, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

3006. The method of claim 2944, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the  
15 method further comprising calibrating the measurement device using the database.

3007. The method of claim 2944, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals of the measurement device using  
20 the database.

3008. The method of claim 2944, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of  
25 specimens.

3009. The method of claim 3008, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.

5     3010. The method of claim 3008, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the database.

10    3011. The method of claim 2944, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.

15    3012. The method of claim 2944, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.

20

3013. The method of claim 2944, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least  
25    one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.



3014. The method of claim 2944, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedback control technique.
- 5 3015. The method of claim 2944, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties using a feedforward control technique.
3016. The method of claim 2944, further comprising monitoring a parameter of one or  
10 more instruments coupled to the process tool.
3017. The method of claim 3016, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.
- 15 3018. The method of claim 3017, further comprising altering a parameter of at least one of the instruments in response to the relationship.
3019. The method of claim 2944, further comprising altering a parameter of one or more instruments coupled to each of a plurality of process tools in response to at least one of  
20 the determined properties of the specimen.
3020. The method of claim 2944, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

3021. The method of claim 3020, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

10 3022. The method of claim 3020, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

3023. A semiconductor device fabricated by a method, the method comprising:

15

forming a portion of the semiconductor device upon a specimen;

20 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

25 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on the specimen.

5

3024. The device of claim 3023, wherein the illumination system comprises a single energy source.

10

3025. The device of claim 3023, wherein the illumination system comprises more than one energy source.

3026. The device of claim 3023, wherein the detection system comprises a single energy sensitive device.

15

3027. The device of claim 3023, wherein the detection system comprises more than one energy sensitive devices.

3028. The device of claim 3023, wherein the measurement device further comprises a modulated optical reflectometer.

20

3029. The device of claim 3023, wherein the measurement device further comprises an X-ray reflectance device.

25

3030. The device of claim 3023, wherein the measurement device further comprises an eddy current device.

3031. The device of claim 3023, wherein the measurement device further comprises a photo-acoustic device.

3032. The device of claim 3023, wherein the measurement device further comprises a spectroscopic ellipsometer.

5 3033. The device of claim 3023, wherein the measurement device further comprises a spectroscopic reflectometer.

3034. The device of claim 3023, wherein the measurement device further comprises a dual beam spectrophotometer.

10

3035. The device of claim 3023, wherein the measurement device further comprises a non-imaging scatterometer.

15 3036. The device of claim 3023, wherein the measurement device further comprises a scatterometer.

3037. The device of claim 3023, wherein the measurement device further comprises a spectroscopic scatterometer.

20 3038. The device of claim 3023, wherein the measurement device further comprises a reflectometer.

3039. The device of claim 3023, wherein the measurement device further comprises an ellipsometer.

25

3040. The device of claim 3023, wherein the measurement device further comprises a non-imaging bright field device.

3041. The device of claim 3023, wherein the measurement device further comprises a non-imaging dark field device.

3042. The device of claim 3023, wherein the measurement device further comprises a  
5 non-imaging bright field and dark field device.

3043. The device of claim 3023, wherein the measurement device further comprises a bright field imaging device.

10 3044. The device of claim 3023, wherein the measurement device further comprises a dark field imaging device.

3045. The device of claim 3023, wherein the measurement device further comprises a bright field and dark field imaging device.

15

3046. The device of claim 3023, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-  
20 acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging  
25 device.

3047. The device of claim 3023, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical

elements of the first measurement device comprise optical elements of the second measurement device.

5 3048. The device of claim 3023, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the specimen.

10 3049. The device of claim 3023, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a concentration of ions in the implanted region, a depth of the implanted region, and a distribution profile of the implanted region.

15 3050. The device of claim 3023, wherein the defects comprise micro defects and macro defects.

3051. The device of claim 3023, wherein the defects comprises micro defects or macro defects.

20 3052. The device of claim 3023, further comprising:

directing energy toward a bottom surface of the specimen; and

25 detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

3053. The device of claim 3052, wherein the defects comprise macro defects.

3054. The device of claim 3023, wherein the stage and the measurement device are coupled to a process tool.

3055. The device of claim 3023, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

3056. A method for fabricating a semiconductor device, comprising:

forming a portion of the semiconductor device upon a specimen;

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on the specimen.

3057. The method of claim 3056, wherein the illumination system comprises a single energy source.

3058. The method of claim 3056, wherein the illumination system comprises more than  
5 one energy source.

3059. The method of claim 3056, wherein the detection system comprises a single energy sensitive device.

10 3060. The method of claim 3056, wherein the detection system comprises more than one energy sensitive devices.

3061. The method of claim 3056, wherein the measurement device is selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an  
15 eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a  
20 bright field and dark field imaging device.

3062. The method of claim 3056, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated  
25 optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-



imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

5     3063. The method of claim 3056, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

10    3064. The method of claim 3056, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-optical characteristic of the specimen.

15    3065. The method of claim 3056, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a concentration of ions in the implanted region, a depth of the implanted region, and a distribution profile of the implanted region.

20    3066. The method of claim 3056, wherein the defects comprise micro defects and macro defects.

3067. The method of claim 3056, wherein the defects comprises micro defects or macro defects.

25    3068. The method of claim 3056, further comprising:

directing energy toward a bottom surface of the specimen; and

detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

5     3069. The method of claim 3068, wherein the defects comprise macro defects.

3070. The method of claim 3056, wherein the stage and the measurement device are coupled to a process tool.

10    3071. The method of claim 3056, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

15    3072. A system configured to determine at least two properties of a specimen during use, comprising:

        a stage configured to support the specimen during use;

        a measurement device coupled to the stage, comprising:

20

        an illumination system configured to direct energy toward a surface of the specimen during use; and

25

        a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use;

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

5 a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises a characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on  
10 the specimen.

3073. The system of claim 3072, wherein the measurement device is selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a  
15 spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

20 3074. The system of claim 3072, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-  
25 acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field

imaging device, a dark field imaging device, and a bright field and dark field imaging device.

3075. The system of claim 3072, wherein the measurement device further comprises at  
5 least a first measurement device and a second measurement device, and wherein optical elements of the first measurement device comprise optical elements of the second measurement device.

3076. The system of claim 3072, wherein the measurement device further comprises  
10 non-optical components, and wherein the detected energy is responsive to a non-optical characteristic of the specimen.

3077. The system of claim 3072, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a  
15 concentration of ions in the implanted region, a depth of the implanted region, and a distribution of the implanted region.

3078. The system of claim 3072, wherein the defects comprise micro defects and macro defects.

20

3079. The system of claim 3072, wherein the defects comprises micro defects or macro defects.

3080. The system of claim 3072, wherein the illumination system is further configured  
25 to direct energy toward a bottom surface of the specimen during use, wherein the detection system is further configured to detect energy propagating from the bottom surface of the specimen during use, and wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

3081. The system of claim 3072, wherein the defects comprise macro defects.

3082. The system of claim 3072, wherein the remote controller computer is further  
5 coupled to a process tool.

3083. The system of claim 3072, wherein the remote controller computer is further  
coupled to a process tool, and wherein the process tool is selected from the group  
consisting of an ion implanter and a thermal tool.  
10

3084. The system of claim 3072, wherein the remote controller computer is further  
coupled to a process tool, and wherein the remote controller computer is further  
configured to alter a parameter of one or more instruments coupled to the process tool in  
response to at least one of the determined properties using a feedback control technique  
15 during use.

3085. The system of claim 3072, wherein the remote controller computer is further  
coupled to a process tool, and wherein the remote controller computer is further  
configured to alter a parameter of one or more instruments coupled to the process tool in  
20 response to at least one of the determined properties using a feedforward control  
technique during use.

3086. The system of claim 3072, wherein the remote controller computer is further  
coupled to a process tool, and wherein the remote controller computer is further  
25 configured to monitor a parameter of one or more instruments coupled to the process tool  
during use.

3087. The system of claim 3086, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

5 3088. The system of claim 3087, wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

3089. The system of claim 3072, wherein the illumination system is further configured  
10 to direct energy toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during the process step.

15 3090. The system of claim 3089, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

20 3091. The system of claim 3089, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

25 3092. The system of claim 3072, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to

move the specimen from the first process chamber to the second process chamber during use.

5 3093. The system of claim 3092, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

10

3094. The system of claim 3072, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

15 3095. The system of claim 3072, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

20 3096. The system of claim 3095, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

25 3097. The system of claim 3072, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

3098. The system of claim 3072, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement

device in response to at least one of the determined properties using a feedback control technique during use.

5 3099. The system of claim 3072, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

10 3100. The system of claim 3072, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

15 3101. The system of claim 3072, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

20 3102. The system of claim 3072, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, wherein the database further comprises first and second properties of a plurality of specimens, and wherein the first  
25 and second properties of the plurality of specimens are determined using a plurality of measurement devices.



3103. The system of claim 3102, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

5

3104. The system of claim 3102, wherein the remote controller computer is further coupled to the plurality of measurement devices, and wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

10

3105. The system of claim 3072, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein at least one of the plurality of measurement devices is coupled to a process tool.

15

3106. The system of claim 3072, wherein the remote controller computer is further coupled to a plurality of process tools, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

20

3107. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

25

directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises a characteristic of an implanted region of the specimen, and wherein the second property comprises a presence of defects on the specimen, comprising:

10

at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

15

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

further processing the partially processed one or more output signals using the remote controller computer.

20

3108. The method of claim 3107, wherein the measurement device is selected from the group consisting of a modulated optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, a dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field imaging device, a dark field imaging device, and a bright field and dark field imaging device.

25

3109. The method of claim 3107, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a modulated  
5 optical reflectometer, an X-ray reflectance device, an eddy current device, a photo-acoustic device, a spectroscopic ellipsometer, a spectroscopic reflectometer, a dual beam spectrophotometer, a non-imaging scatterometer, a scatterometer, a spectroscopic scatterometer, a reflectometer, an ellipsometer, a non-imaging bright field device, a non-imaging dark field device, a non-imaging bright field and dark field device, a bright field  
10 imaging device, a dark field imaging device, and a bright field and dark field imaging device.

3110. The method of claim 3107, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein optical  
15 elements of the first measurement device comprise optical elements of the second measurement device.

3111. The method of claim 3107, wherein the measurement device further comprises non-optical components, and wherein detecting energy comprises measuring a non-  
20 optical characteristic of the specimen.

3112. The method of claim 3107, wherein the characteristic of the implanted region is selected from the group consisting of a presence of ions in the implanted region, a concentration of ions in the implanted region, a depth of the implanted region, and a  
25 distribution profile of the implanted region.

3113. The method of claim 3107, wherein the defects comprise micro defects and macro defects.

3114. The method of claim 3107, wherein the defects comprises micro defects or macro defects.

5 3115. The method of claim 3107, further comprising:

directing energy toward a bottom surface of the specimen; and

10 detecting energy propagating from the bottom surface of the specimen, wherein the second property further comprises a presence of defects on the bottom surface of the specimen.

3116. The method of claim 3115, wherein the defects comprise macro defects.

15 3117. The method of claim 3107, wherein the remote controller computer is coupled to a process tool.

20 3118. The method of claim 3107, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of an ion implanter and a thermal tool.

25 3119. The method of claim 3107, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback control technique.

3120. The method of claim 3107, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedforward control technique.

3121. The method of claim 3107, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

3122. The method of claim 3121, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer.

3123. The method of claim 3122, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.

3124. The method of claim 3107, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, the method further comprising performing said directing and said detecting during a process step.

3125. The method of claim 3124, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.

3126. The method of claim 3124, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.

3127. The method of claim 3107, further comprising:

5 moving the specimen from a first process chamber to a second process chamber  
using the stage; and

performing said directing and said detecting during said moving the specimen.

10 3128. The method of claim 3107, further comprising comparing at least one of the  
determined properties of the specimen and determined properties of a plurality of  
specimens using the remote controller computer.

15 3129. The method of claim 3107, further comprising comparing at least one of the  
determined properties to a predetermined range for the property using the remote  
controller computer.

20 3130. The method of claim 3129, further comprising generating an output signal using  
the remote controller computer if at least one of the determined properties of the  
specimen is outside of the predetermined range for the property.

3131. The method of claim 3107, wherein the remote controller computer is coupled to  
the measurement device.

25 3132. The method of claim 3107, wherein the remote controller computer is coupled to  
the measurement device, the method further comprising altering a sampling frequency of  
the measurement device using the remote controller computer in response to at least one  
of the determined properties of the specimen.

3133. The method of claim 3107, wherein the remote controller computer is coupled to the measurement device, the method further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control  
5 technique.

3134. The method of claim 3107, wherein the remote controller computer is coupled to the measurement device, the method further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller  
10 computer in response to at least one of the determined properties using a feedforward control technique.

3135. The method of claim 3107, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and  
15 second properties of the specimen, the method further comprising calibrating the measurement device using the remote controller computer and the database.

3136. The method of claim 3107, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and  
20 second properties of the specimen, the method further comprising monitoring output signals of the measurement device using the remote controller computer and the database.

3137. The method of claim 3107, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and  
25 second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

3138. The method of claim 3137, wherein the determined first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the remote controller computer and the database.

5

3139. The method of claim 3137, wherein the determined first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the remote controller computer and the database.

10

3140. The method of claim 3107, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote controller computer, wherein each of the plurality of local processors is coupled to one of a plurality of measurement devices.

15

3141. The method of claim 3140, wherein at least one of the plurality of measurement devices is coupled to a process tool.

20

3142. The method of claim 3107, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools using the remote controller computer in response to at least one of the determined properties of the specimen.

3143. A system configured to determine at least two properties of a specimen during use, comprising:

25

a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:



an illumination system configured to direct energy toward a surface of the specimen during use; and

5           a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use; and

10           a processor coupled to the measurement device and configured to determine a first property and a second property of the specimen from the one or more output signals during use, wherein the first property comprises an adhesion characteristic of the specimen, and wherein the second property comprises a thickness of the specimen.

15           3144. The system of claim 3143, wherein the stage is further configured to move laterally during use.

20           3145. The system of claim 3143, wherein the stage is further configured to move rotatably during use.

3146. The system of claim 3143, wherein the stage is further configured to move laterally and rotatably during use.

25           3147. The system of claim 3143, wherein the measurement device further comprises a photo-acoustic device.

3148. The system of claim 3143, wherein the measurement device further comprises a spectroscopic ellipsometer.
- 5 3149. The system of claim 3143, wherein the measurement device further comprises an ellipsometer.
3150. The system of claim 3143, wherein the measurement device further comprises an X-ray reflectometer.
- 10 3151. The system of claim 3143, wherein the measurement device further comprises a grazing X-ray reflectometer.
3152. The system of claim 3143, wherein the measurement device further comprises an X-ray diffractometer.
- 15 3153. The system of claim 3143, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.
3154. The system of claim 3143, wherein the measurement device further comprises at  
20 least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.
- 25 3155. The system of claim 3143, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein elements of the first measurement device comprise elements of the second measurement device.

3156. The system of claim 3143, wherein the processor is further configured to determine a third property of the specimen from the one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

3157. The system of claim 3156, wherein the system is coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

3158. The system of claim 3143, wherein the system is further configured to determine at least two properties of the specimen substantially simultaneously during use.

3159. The system of claim 3143, wherein the illumination system is further configured to direct energy to multiple locations on the surface of the specimen substantially simultaneously, and wherein the detection system is further configured to detect energy propagating from the multiple locations on the surface of the specimen substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

3160. The system of claim 3143, wherein the system is coupled to a process tool.

3161. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the system is disposed within the process tool.

3162. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the system is arranged laterally proximate to the process tool.

3163. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the process tool comprises a wafer handler configured to move the specimen to the stage during use.

5 3164. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the stage is configured to move the specimen from the system to the process tool during use.

3165. The system of claim 3143, wherein the system is coupled to a process tool, and  
10 wherein the stage is further configured to move the specimen to a process chamber of the process tool during use.

3166. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the system is further configured to determine at least the two properties of the  
15 specimen while the specimen is waiting between process steps.

3167. The system of claim 3143, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially  
20 parallel to an upper surface of the stage.

3168. The system of claim 3143, wherein the system is coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to  
25 an upper surface of the support device.

3169. The system of claim 3143, wherein the system is coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch tool, an ion

implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

3170. The system of claim 3143, wherein the system further comprises a measurement  
5 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is coupled to a process tool.

3171. The system of claim 3143, wherein the system further comprises a measurement  
10 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is disposed within a process tool.

3172. The system of claim 3143, wherein the system further comprises a measurement  
15 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

3173. The system of claim 3143, wherein the system further comprises a measurement  
20 chamber, wherein the stage and the measurement device are disposed within the measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

3174. The system of claim 3143, wherein a process tool comprises a process chamber,  
25 wherein the stage is disposed within the process chamber, and wherein the stage is further configured to support the specimen during a process step.

3175. The system of claim 3174, wherein the processor is further configured to determine at least the two properties of the specimen during the process step.

5 3176. The system of claim 3174, wherein the processor is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

10 3177. The system of claim 3174, wherein the processor is coupled to the process tool and is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

15 3178. The system of claim 3143, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to move the specimen from the first process chamber to the second process chamber during use.

20 3179. The system of claim 3178, wherein the system is further configured to determine at least the two properties of the specimen as the stage is moving the specimen from the first process chamber to the second process chamber.

25 3180. The system of claim 3143, wherein the processor is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

3181. The system of claim 3143, wherein the processor is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

3182. The system of claim 3181, wherein the processor is further configured to generate an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property during use.

5

3183. The system of claim 3143, wherein the processor is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

10 3184. The system of claim 3143, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique during use.

15 3185. The system of claim 3143, wherein the processor is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

20 3186. The system of claim 3143, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to calibrate the measurement device using the database during use.

25 3187. The system of claim 3143, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the processor is further configured to monitor output signals generated by measurement device using the database during use.

3188. The system of claim 3143, wherein the processor is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

5

3189. The system of claim 3188, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to calibrate the plurality of measurement devices using the database during use.

10

3190. The system of claim 3188, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, wherein the processor is further coupled to the plurality of measurement devices, and wherein the processor is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

15

3191. The system of claim 3143, further comprising a stand alone system coupled to the system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system during use.

20

3192. The system of claim 3143, further comprising a stand alone system coupled the system and at least one additional system, wherein the stand alone system is configured to be calibrated with a calibration standard during use, and wherein the stand alone system is further configured to calibrate the system and at least the one additional system during use.

25



3193. The system of claim 3143, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, and wherein the processor is configured to alter at least one parameter of one or more instruments coupled to a process tool in response to  
5 at least one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

3194. The system of claim 3143, wherein the processor is further coupled to a process tool.  
10

3195. The system of claim 3143, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

15 3196. The system of claim 3143, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control technique during use.

20 3197. The system of claim 3143, wherein the processor is further coupled to a process tool, and wherein the processor is further configured to monitor a parameter of one or more instruments coupled to the process tool during use.

25 3198. The system of claim 3197, wherein the processor is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

3199. The system of claim 3198, wherein the processor is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

3200. The system of claim 3143, wherein the processor is further coupled to a plurality  
5 of measurement devices, and wherein at least one of the plurality of measurement devices is coupled to a process tool.

3201. The system of claim 3143, wherein the processor is further coupled to a plurality  
of process tools, and wherein the processor is further configured to alter a parameter of  
10 one or more instruments coupled to at least one of the plurality of process tools during use.

3202. The system of claim 3143, wherein the processor comprises a local processor  
coupled to the measurement device and a remote controller computer coupled to the local  
15 processor, wherein the local processor is configured to at least partially process the one or more output signals during use, and wherein the remote controller computer is configured to further process the at least partially processed one or more output signals during use.

3203. The system of claim 3202, wherein the local processor is further configured to  
20 determine the first property and the second property of the specimen during use.

3204. The system of claim 3202, wherein the remote controller computer is further  
configured to determine the first property and the second property of the specimen during  
use.

25

3205. A method for determining at least two properties of a specimen, comprising:

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

5 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

10 generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the specimen, wherein the first property comprises an adhesion characteristic of the specimen, and wherein the second property comprises a

15 thickness of the specimen.

3206. The method of claim 3205, further comprising laterally moving the stage during said directing energy and said detecting energy.

20 3207. The method of claim 3205, further comprising rotatably moving the stage during said directing energy and said detecting energy.

3208. The method of claim 3205, further comprising laterally and rotatably moving the stage during said directing energy and said detecting energy.

25

3209. The method of claim 3205, wherein the measurement device further comprises a photo-acoustic device.

3210. The method of claim 3205, wherein the measurement device further comprises a spectroscopic ellipsometer.

5 3211. The method of claim 3205, wherein the measurement device further comprises an ellipsometer.

3212. The method of claim 3205, wherein the measurement device further comprises an X-ray reflectometer.

10 3213. The method of claim 3205, wherein the measurement device further comprises a grazing X-ray reflectometer.

3214. The method of claim 3205, wherein the measurement device further comprises an X-ray diffractometer.

15

3215. The method of claim 3205, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.

20 3216. The method of claim 3205, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.

25 3217. The method of claim 3205, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein at least one element of the first measurement device comprises at least one element of the second measurement device.

3218. The method of claim 3205, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

3219. The method of claim 3218, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

3220. The method of claim 3205, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

3221. The method of claim 3205, further comprising directing energy toward multiple locations on the surface of the specimen substantially simultaneously and detecting energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially simultaneously.

3222. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool.

3223. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

3224. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

- 5     3225. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch tool, an ion implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

10

3226. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a wafer handler, and wherein disposing the specimen upon the stage comprises moving the specimen from the process tool to the stage using the wafer handler.

15

3227. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, the method further comprising moving the specimen to the process tool subsequent to said directing and said detecting using the stage.

- 20     3228. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, the method further comprising determining at least the two properties of the specimen while the specimen is waiting between process steps.

- 25     3229. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.

3230. The method of claim 3205, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

5

3231. The method of claim 3205, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

10 3232. The method of claim 3205, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is disposed within a process tool.

15 3233. The method of claim 3205, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.

20 3234. The method of claim 3205, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

25 3235. The method of claim 3205, wherein disposing the specimen upon the stage comprises disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

3236. The method of claim 3235, further comprising performing said directing and said detecting during the process step.

3237. The method of claim 3236, further comprising obtaining a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

5

3238. The method of claim 3236, further comprising altering a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

10 3239. The method of claim 3205, further comprising moving the specimen from a first process chamber to a second process chamber using the stage, wherein the first process chamber and the second process chamber are disposed within a process tool.

15 3240. The method of claim 3239, further comprising performing said directing and said detecting during said moving the specimen from the first process chamber to the second process chamber.

20 3241. The method of claim 3205, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.

3242. The method of claim 3205, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

25 3243. The method of claim 3242, further comprising generating an output signal if at least one of the determined properties of the specimen is outside of the predetermined range for the property.



3244. The method of claim 3205, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

5 3245. The method of claim 3205, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

3246. The method of claim 3205, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

3247. The method of claim 3205, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the  
15 method further comprising calibrating the measurement device using the database.

3248. The method of claim 3205, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals of the measurement device using  
20 the database.

3249. The method of claim 3205, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of  
25 specimens.

3250. The method of claim 3249, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.

5     3251. The method of claim 3249, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the database.

10    3252. The method of claim 3205, wherein a stand alone system is coupled to the measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device with the stand alone system.

15    3253. The method of claim 3205, wherein a stand alone system is coupled to the measurement device and at least one additional measurement device, the method further comprising calibrating the stand alone system with a calibration standard and calibrating the measurement device an at least the one additional measurement device with the stand alone system.

20

3254. The method of claim 3205, further comprising determining at least the two properties of the specimen at more than one position on the specimen, wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least one  
25    of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

3255. The method of claim 3205, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.
- 5 3256. The method of claim 3205, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.
3257. The method of claim 3205, further comprising monitoring a parameter of one or  
10 more instruments coupled to the process tool.
3258. The method of claim 3257, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.
- 15 3259. The method of claim 3258, further comprising altering a parameter of at least one of the instruments in response to the relationship.
3260. The method of claim 3205, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the  
20 determined properties of the specimen.
3261. The method of claim 3205, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

3262. The method of claim 3261, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

10 3263. The method of claim 3261, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

3264. A computer-implemented method for controlling a system configured to  
15 determine at least two properties of a specimen during use, wherein the system comprises a measurement device, comprising:

controlling the measurement device, wherein the measurement device comprises  
an illumination system and a detection system, and wherein the measurement  
20 device is coupled to a stage, comprising:

controlling the illumination system to direct energy toward a surface of the specimen;

25 controlling the detection system to detect energy propagating from the surface of the specimen; and

generating one or more output signals responsive to the detected energy;  
and

5        processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises an adhesion  
characteristic of the specimen, and wherein the second property comprises a  
thickness of the specimen.

10       3265. The method of claim 3264, further comprising controlling the stage, wherein the  
stage is configured to support the specimen.

3266. The method of claim 3264, further comprising controlling the stage to laterally  
move the stage during said directing energy and said detecting energy.

15       3267. The method of claim 3264, further comprising controlling the stage to rotatably  
move the stage during said directing energy and said detecting energy.

20       3268. The method of claim 3264, further comprising controlling the stage to laterally  
and rotatably move the stage during said directing energy and said detecting energy.

3269. The method of claim 3264, wherein the measurement device further comprises a  
photo-acoustic device.

25       3270. The method of claim 3264, wherein the measurement device further comprises a  
spectroscopic ellipsometer.

3271. The method of claim 3264, wherein the measurement device further comprises an  
ellipsometer.

3272. The method of claim 3264, wherein the measurement device further comprises an X-ray reflectometer.
- 5 3273. The method of claim 3264, wherein the measurement device further comprises a grazing X-ray reflectometer.
3274. The method of claim 3264, wherein the measurement device further comprises an X-ray diffractometer.
- 10 3275. The method of claim 3264, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.
3276. The method of claim 3264, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.
- 15 3277. The method of claim 3264, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein at least one element of the first measurement device comprises at least one element of the second measurement device.
- 20 3278. The method of claim 3264, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.
- 25

3279. The method of claim 3278, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5

3280. The method of claim 3264, wherein processing the one or more output signals to determine the first and second properties of the specimen comprises substantially simultaneously determining the first and second properties of the specimen.

10 3281. The method of claim 3264, further comprising controlling the illumination system to direct energy toward multiple locations on the surface of the specimen substantially simultaneously and controlling the detection system to detect energy propagating from the multiple locations substantially simultaneously such that one or more of the at least two properties of the specimen can be determined at the multiple locations substantially  
15 simultaneously.

3282. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool.

20 3283. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are arranged laterally proximate to the process tool.

25 3284. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, and wherein the stage and the measurement device are disposed within the process tool.

3285. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch tool, and ion implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and  
5 a plating tool.

3286. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage, and wherein the wafer handler is  
10 coupled to the process tool.

3287. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling the stage to move the specimen from the system to the process tool.  
15

3288. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, the method further comprising controlling a wafer handler to move the specimen from the process tool to the stage such that at least the two properties of the specimen can be determined while the specimen is waiting between process steps.  
20

3289. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured to support the specimen during a process step, and wherein an upper surface of the support device is substantially parallel to an upper surface of the stage.  
25

3290. The method of claim 3264, wherein the stage and the measurement device are coupled to a process tool, wherein the process tool comprises a support device configured



to support the specimen during a process step, and wherein an upper surface of the stage is angled with respect to an upper surface of the support device.

3291. The method of claim 3264, wherein the stage and the measurement device are  
5 disposed within a measurement chamber, and wherein the measurement chamber is coupled to a process tool.

3292. The method of claim 3264, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is  
10 disposed within a process tool.

3293. The method of claim 3264, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged laterally proximate to a process chamber of a process tool.  
15

3294. The method of claim 3264, wherein the stage and the measurement device are disposed within a measurement chamber, and wherein the measurement chamber is arranged vertically proximate to a process chamber of a process tool.

20 3295. The method of claim 3264, further comprising disposing the specimen upon a support device disposed within a process chamber of a process tool, and wherein the support device is configured to support the specimen during a process step.

3296. The method of claim 3295, further comprising controlling the illumination system  
25 and controlling the detection system during the process step.

3297. The method of claim 3296, further comprising controlling the system to obtain a signature characterizing the process step, wherein the signature comprises at least one singularity representative of an end of the process step.

- 5     3298. The method of claim 3264, further comprising controlling the system to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique.

3299. The method of claim 3264, further comprising controlling the stage to move the  
10     specimen from a first process chamber to a second process chamber, wherein the first process chamber and the second process chamber are disposed within a process tool.

3300. The method of claim 3299, further comprising controlling the illumination system and controlling the detection system during said moving the specimen from the first  
15     process chamber to the second process chamber.

3301. The method of claim 3264, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens.  
20

3302. The method of claim 3264, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property.

3303. The method of claim 3302, further comprising generating an output signal if at  
25     least one of the determined properties of the specimen is outside of the predetermined range for the property.

3304. The method of claim 3264, further comprising altering a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen.

5 3305. The method of claim 3264, further comprising altering a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedback control technique.

3306. The method of claim 3264, further comprising altering a parameter of one or more  
10 instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique.

3307. The method of claim 3264, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the  
15 method further comprising calibrating the measurement device using the database.

3308. The method of claim 3264, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals of the measurement device using  
20 the database.

3309. The method of claim 3264, further comprising generating a database, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of  
25 specimens.

3310. The method of claim 3309, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the database.
- 5 3311. The method of claim 3309, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the database.
- 10 3312. The method of claim 3264, wherein a stand alone system is coupled to the system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system.
- 15 3313. The method of claim 3264, wherein a stand alone system is coupled to the system and at least one additional system, the method further comprising controlling the stand alone system to calibrate the stand alone system with a calibration standard and further controlling the stand alone system to calibrate the system and at least the one additional system.
- 20 3314. The method of claim 3264, wherein the system is further configured to determine at least the two properties of the specimen at more than one position on the specimen, and wherein the specimen comprises a wafer, the method further comprising altering at least one parameter of one or more instruments coupled to a process tool in response to at least
- 25 one of the determined properties of the specimen at the more than one position on the specimen to reduce within wafer variation of at least one of the determined properties.

3315. The method of claim 3264, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedback control technique.
- 5 3316. The method of claim 3264, further comprising altering a parameter of one or more instruments coupled to a process tool in response to at least one of the determined properties of the specimen using a feedforward control technique.
3317. The method of claim 3264, further comprising monitoring a parameter of one or  
10 more instruments coupled to the process tool.
3318. The method of claim 3317, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters.
- 15 3319. The method of claim 3317, further comprising altering a parameter of at least one of the instruments in response to the relationship.
3320. The method of claim 3264, further comprising altering a parameter of one or more instruments coupled to a plurality of process tools in response to at least one of the  
20 determined properties of the specimen.
3321. The method of claim 3264, wherein processing the one or more output signals comprises:
- 25 at least partially processing the one or more output signals using a local processor, wherein the local processor is coupled to the measurement device;

sending the partially processed one or more output signals from the local processor to a remote controller computer; and

5 further processing the partially processed one or more output signals using the remote controller computer.

3322. The method of claim 3321, wherein at least partially processing the one or more output signals comprises determining the first and second properties of the specimen.

10 3323. The method of claim 3321, wherein further processing the partially processed one or more output signals comprises determining the first and second properties of the specimen.

3324. A semiconductor device fabricated by a method, the method comprising:

15

forming a portion of the semiconductor device upon a specimen;

20 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

25 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

processing the one or more output signals to determine a first property and a second property of the portion of the semiconductor device, wherein the first property comprises an adhesion characteristic on the portion of the specimen, and wherein the second property comprises a thickness of the portion of the specimen.

5

3325. The device of claim 3324, wherein the measurement device further comprises a photo-acoustic device.

3326. The device of claim 3324, wherein the measurement device further comprises a spectroscopic ellipsometer.

10

3327. The device of claim 3324, wherein the measurement device further comprises an ellipsometer.

3328. The device of claim 3324, wherein the measurement device further comprises an X-ray reflectometer.

15

3329. The device of claim 3324, wherein the measurement device further comprises a grazing X-ray reflectometer.

20

3330. The device of claim 3324, wherein the measurement device further comprises an X-ray diffractometer.

3331. The device of claim 3324, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.

25

3332. The device of claim 3324, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first

and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.

5     3333. The device of claim 3324, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein at least one element of the first measurement device comprises at least one element of the second measurement device.

10    3334. The method of claim 3324, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

15    3335. The method of claim 3334, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

20    3336. The device of claim 3324, wherein the stage and the measurement device are coupled to a process tool.

3337. The device of claim 3324, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch tool, an ion implanter, a chemical vapor deposition tool, a physical  
25    vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

3338. A method for fabricating a semiconductor device, comprising:



forming a portion of the semiconductor device upon a specimen;

5 disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

directing energy toward a surface of the specimen using the illumination system;

10 detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy during use; and

15 processing the one or more output signals to determine a first property and a second property of the portion of the semiconductor device, wherein the first property comprises an adhesion characteristic of the portion of the specimen, and wherein the second property comprises a thickness of the portion of the specimen.

20 3339. The method of claim 3338, wherein the measurement device further comprises a photo-acoustic device.

25 3340. The method of claim 3338, wherein the measurement device further comprises a spectroscopic ellipsometer.

3341. The method of claim 3338, wherein the measurement device further comprises an ellipsometer.

3342. The method of claim 3338, wherein the measurement device further comprises an X-ray reflectometer.

- 5 3343. The method of claim 3338, wherein the measurement device further comprises a grazing X-ray reflectometer.

3344. The method of claim 3338, wherein the measurement device further comprises an X-ray diffractometer.

10

3345. The method of claim 3338, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.

3346. The method of claim 3338, wherein the measurement device further comprises at  
15 least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.

- 20 3347. The method of claim 3338, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein at least one element of the first measurement device comprises at least one element of the second measurement device.

- 25 3348. The method of claim 3338, further comprising processing the one or more output signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

3349. The method of claim 3348, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5

3350. The method of claim 3338, wherein the stage and the measurement device are coupled to a process tool.

3351. The method of claim 3338, wherein the stage and the measurement device are coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch tool, an ion implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

15 3352. A system configured to determine at least two properties of a specimen during use, comprising:

a stage configured to support the specimen during use;

20 a measurement device coupled to the stage, comprising:

an illumination system configured to direct energy toward a surface of the specimen during use; and

25 a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use, wherein the measurement device is configured to generate one or more output signals responsive to the detected energy during use;

a local processor coupled to the measurement device and configured to at least partially process the one or more output signals during use; and

5 a remote controller computer coupled to the local processor, wherein the remote controller computer is configured to receive the at least partially processed one or more output signals and to determine a first property and a second property of the specimen from the at least partially processed one or more output signals during use, wherein the first property comprises an adhesion characteristic of the  
10 specimen, and wherein the second property comprises a thickness of the specimen.

3353. The system of claim 3352, wherein the measurement device further comprises a photo-acoustic device.

15 3354. The system of claim 3352, wherein the measurement device further comprises a spectroscopic ellipsometer.

3355. The system of claim 3352, wherein the measurement device further comprises an  
20 ellipsometer.

3356. The system of claim 3352, wherein the measurement device further comprises an X-ray reflectometer.

25 3357. The system of claim 3352, wherein the measurement device further comprises a grazing X-ray reflectometer.

3358. The system of claim 3352, wherein the measurement device further comprises an X-ray diffractometer.

5 3359. The system of claim 3352, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.

3360. The system of claim 3352, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first and second measurement devices are selected from the group consisting of a photo-  
10 acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.

3361. The system of claim 3352, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein at least  
15 one element of the first measurement device comprises at least one element of the second measurement device.

3362. The system of claim 3352, wherein the remote controller computer is further configured to determine a third property of the specimen from the at least partially  
20 processed one or more output signals during use, and wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

3363. The system of claim 3362, wherein the system is coupled to a process tool  
25 selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

3364. The system of claim 3352, wherein the remote controller computer is further coupled to a process tool.

5 3365. The system of claim 3352, wherein the remote controller computer is further coupled to a process tool, and wherein the process tool is selected from a group consisting of an etch tool, an ion implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

10 3366. The system of claim 3352, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedback control technique during use.

15 3367. The system of claim 3352, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using a feedforward control  
20 technique during use.

3368. The system of claim 3352, wherein the remote controller computer is further coupled to a process tool, and wherein the remote controller computer is further configured to monitor a parameter of one or more instruments coupled to the process tool  
25 during use.

3369. The system of claim 3352, wherein the remote controller computer is further configured to determine a relationship between at least one of the determined properties and at least one of the monitored parameters during use.

5 3370. The system of claim 3369, wherein the remote controller computer is further configured to alter a parameter of at least one of the instruments in response to the relationship during use.

3371. The system of claim 3352, wherein the illumination system is further configured  
10 to direct energy toward the surface of the specimen during a process step, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during the process step, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during the process step.

15 3372. The system of claim 3371, wherein the remote controller computer is further configured to obtain a signature characterizing the process step during use, and wherein the signature comprises at least one singularity representative of an end of the process step.

20 3373. The system of claim 3371, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the process tool in response to at least one of the determined properties using an in situ control technique during use.

25 3374. The system of claim 3352, wherein a process tool comprises a first process chamber and a second process chamber, and wherein the stage is further configured to

move the specimen from the first process chamber to the second process chamber during use.

5 3375. The system of claim 3374, wherein the illumination system is further configured to direct energy toward the surface of the specimen during said moving, wherein the detection system is further configured to detect energy propagating from the surface of the specimen during said moving, and wherein the remote controller computer is further configured to determine the first and second properties of the specimen during said moving.

10

3376. The system of claim 3352, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen and properties of a plurality of specimens during use.

15 3377. The system of claim 3352, wherein the remote controller computer is further configured to compare at least one of the determined properties of the specimen to a predetermined range for the property during use.

20 3378. The system of claim 3377, wherein the remote controller computer is further configured to generate an output signal if at least one of the determined properties of the specimen are outside of the predetermined range for the property during use.

25 3379. The system of claim 3352, wherein the remote controller computer is further configured to alter a sampling frequency of the measurement device in response to at least one of the determined properties of the specimen during use.

3380. The system of claim 3352, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement



device in response to at least one of the determined properties using a feedback control technique during use.

5 3381. The system of claim 3352, wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to the measurement device in response to at least one of the determined properties using a feedforward control technique during use.

10 3382. The system of claim 3352, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to calibrate the measurement device using the database during use.

15 3383. The system of claim 3352, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the remote controller computer is further configured to monitor output signals generated by measurement device using the database during use.

20 3384. The system of claim 3352, wherein the remote controller computer is further configured to generate a database during use, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

25 3385. The system of claim 3384, wherein the first and second properties of the plurality of specimens are determined using a plurality of measurement devices, and wherein the remote controller computer is further coupled to the plurality of measurement devices.

3386. The system of claim 3385, wherein the remote controller computer is further configured to calibrate the plurality of measurement devices using the database during use.

5

3387. The system of claim 3385, wherein the remote controller computer is further configured to monitor output signals generated by the plurality of measurement devices using the database during use.

10 3388. The system of claim 3352, wherein the remote controller computer is further coupled to a plurality of measurement devices, and wherein at least one of the plurality of measurement devices is coupled to a process tool.

3389. The system of claim 3352, wherein the remote controller computer is further  
15 coupled to a plurality of process tool, and wherein the remote controller computer is further configured to alter a parameter of one or more instruments coupled to at least one of the plurality of process tools during use.

3390. A method for determining at least two properties of a specimen, comprising:  
20

disposing the specimen upon a stage, wherein the stage is coupled to a measurement device, and wherein the measurement device comprises an illumination system and a detection system;

25 directing energy toward a surface of the specimen using the illumination system;

detecting energy propagating from the surface of the specimen using the detection system;

generating one or more output signals responsive to the detected energy; and

5        processing the one or more output signals to determine a first property and a  
second property of the specimen, wherein the first property comprises an adhesion  
characteristic of the specimen, and wherein the second property comprises a  
thickness of the specimen, comprising:

10                at least partially processing the one or more output signals using a local  
processor, wherein the local processor is coupled to the measurement  
device;

              sending the partially processed one or more output signals from the local  
processor to a remote controller computer; and

15                further processing the partially processed one or more output signals using  
the remote controller computer.

3391. The method of claim 3390, wherein the measurement device further comprises a  
20        photo-acoustic device.

3392. The method of claim 3390, wherein the measurement device further comprises a  
spectroscopic ellipsometer.

25        3393. The method of claim 3390, wherein the measurement device further comprises an  
ellipsometer.

3394. The method of claim 3390, wherein the measurement device further comprises an X-ray reflectometer.

5 3395. The method of claim 3390, wherein the measurement device further comprises a grazing X-ray reflectometer.

3396. The method of claim 3390, wherein the measurement device further comprises an X-ray diffractometer.

10 3397. The method of claim 3390, wherein the measurement device further comprises a photo-acoustic device and an ellipsometer.

3398. The method of claim 3390, wherein the measurement device further comprises at least a first measurement device and a second measurement device, and wherein the first  
15 and second measurement devices are selected from the group consisting of a photo-acoustic device, a spectroscopic ellipsometer, an ellipsometer, an X-ray reflectometer, a grazing X-ray reflectometer, an X-ray diffractometer, and an eddy current device.

3399. The method of claim 3390, wherein the measurement device further comprises at  
20 least a first measurement device and a second measurement device, and wherein at least one element of the first measurement device comprises at least one element of the second measurement device.

3400. The method of claim 3390, further comprising processing the one or more output  
25 signals to determine a third property of the specimen, wherein the third property is selected from the group consisting of a roughness of the specimen, a roughness of a layer on the specimen, and a roughness of a feature of the specimen.

3401. The method of claim 3400, wherein the stage and the measurement device are coupled to a process tool selected from the group consisting of a lithography tool, an atomic layer deposition tool, a cleaning tool, and an etch tool.

5     3402. The method of claim 3390, wherein the remote controller computer is coupled to a process tool.

3403. The method of claim 3390, wherein the remote controller computer is coupled to a process tool, and wherein the process tool is selected from the group consisting of an etch  
10     tool, an ion implanter, a chemical vapor deposition tool, a physical vapor deposition tool, an atomic layer deposition tool, a thermal tool, a cleaning tool, and a plating tool.

3404. The method of claim 3390, wherein the remote controller computer is coupled to a process tool, the method further comprising altering a parameter of one or more  
15     instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedback control technique.

3405. The method of claim 3390, wherein the remote controller computer is coupled to a  
20     process tool, the method further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties of the specimen using a feedforward control technique.

25     3406. The method of claim 3390, wherein the remote controller computer is coupled to a process tool, the method further comprising monitoring a parameter of one or more instruments coupled to the process tool using the remote controller computer.

3407. The method of claim 3406, further comprising determining a relationship between at least one of the determined properties and at least one of the monitored parameters using the remote controller computer.
- 5 3408. The method of claim 3407, further comprising altering a parameter of at least one of the instruments in response to the relationship using the remote controller computer.
3409. The method of claim 3390, wherein the illumination system and the detection system are coupled to a process chamber of the process tool, the method further  
10 comprising performing said directing and said detecting during a process step.
3410. The method of claim 3409, further comprising obtaining a signature characterizing the process step using the remote controller computer, wherein the signature comprises at least one singularity representative of an end of the process step.  
15
3411. The method of claim 3409, further comprising altering a parameter of one or more instruments coupled to the process tool using the remote controller computer in response to at least one of the determined properties using an in situ control technique.
- 20 3412. The method of claim 3390, further comprising:
- moving the specimen from a first process chamber to a second process chamber using the stage; and
- 25 performing said directing and said detecting during said moving the specimen.

3413. The method of claim 3390, further comprising comparing at least one of the determined properties of the specimen and determined properties of a plurality of specimens using the remote controller computer.

5 3414. The method of claim 3390, further comprising comparing at least one of the determined properties of the specimen to a predetermined range for the property using the remote controller computer.

3415. The method of claim 3414, further comprising generating an output signal using  
10 the remote controller computer if at least one of the determined properties of the specimen are outside of the predetermined range for the property.

3416. The method of claim 3390, wherein the remote controller computer is coupled to the measurement device.

15

3417. The method of claim 3416, further comprising altering a sampling frequency of the measurement device using the remote controller computer in response to at least one of the determined properties of the specimen.

20 3418. The method of claim 3416, further comprising altering a parameter of one or more instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedback control technique.

3419. The method of claim 3416, further comprising altering a parameter of one or more  
25 instruments coupled to the measurement device using the remote controller computer in response to at least one of the determined properties using a feedforward control technique.

3420. The method of claim 3390, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising calibrating the measurement device using the remote controller computer and the database.

5

3421. The method of claim 3390, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, the method further comprising monitoring output signals of the measurement device using the remote controller computer and the database.

10

3422. The method of claim 3390, further comprising generating a database using the remote controller computer, wherein the database comprises the determined first and second properties of the specimen, and wherein the database further comprises first and second properties of a plurality of specimens.

15

3423. The method of claim 3422, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising calibrating the plurality of measurement devices using the remote controller computer and the database.

20

3424. The method of claim 3422, wherein the first and second properties of the plurality of specimens are generated using a plurality of measurement devices, the method further comprising monitoring output signals of the plurality of measurement devices using the remote controller computer and the database.

25

3425. The method of claim 3390, further comprising sending the at least partially processed one or more output signals from a plurality of local processors to the remote



controller computer, wherein at least one of the plurality of local processors is coupled to one of a plurality of measurement devices.

5 3426. The method of claim 3425, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of measurement devices using the remote controller computer in response to at least one of the determined properties of the specimen.

10 3427. The method of claim 3425, wherein at least one of the plurality of measurement devices is coupled to at least one of a plurality of process tools.

15 3428. The method of claim 3427, further comprising altering a parameter of one or more instruments coupled to at least one of the plurality of process tools using the remote controller computer in response to at least one of the determined properties of the specimen.

3429. A system configured to determine at least two properties of a specimen during use, comprising:

20 a stage configured to support the specimen during use;

a measurement device coupled to the stage, comprising:

25 an illumination system configured to direct energy toward a surface of the specimen during use; and

a detection system coupled to the illumination system and configured to detect energy propagating from the surface of the specimen during use,